iC-PZ Series

HIGH-RESOLUTION REFLECTIVE ABSOLUTE ENCODER

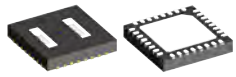
FEATURES

- Reflective, compact, high-resolution, absolute encoder iCs
- Series of 3 basic encoder iCs for matched code discs (⌀ 9 mm, 26 mm) and linear scales (max. 6.71 m)
- Unique *FlexCode*® circuitry for arbitrary code disc diameters
- Monolithic HD Phased Array with excellent signal matching
- *EncoderBlue*®: System-on-chip design with embedded blue LED for excellent signal quality
- LED power control
- Absolute singleturn resolution of 22 bit (⌀ 26 mm) with on-chip interpolation
- Automatic adjustment features on command
- Calibration and configuration storage via external I2C EEPROM
- Digital BiSS, SSI, and SPI interfaces with CMOS I/O
- Operational and temperature monitoring with alarm messaging
- Operation at 4.5 V to 5.5 V within -40 °C to 125 °C
- 2.5 V, 3.3 V, and 5.0 V compatible I/O ports
- Unique *FlexCount*® interpolation for arbitrary ABZ resolution
- UVW commutation signals for motors with 1 to 32 pole pairs
- Configurable analog outputs
- Absolute Data Interface (ADI) to multiturn sensors
- Wide assembly tolerances ensure easy installation

APPLICATIONS

- Low-height, absolute optical position encoders
- Factory automation and robotics
- Servo motors
- Linear actuators

PACKAGES

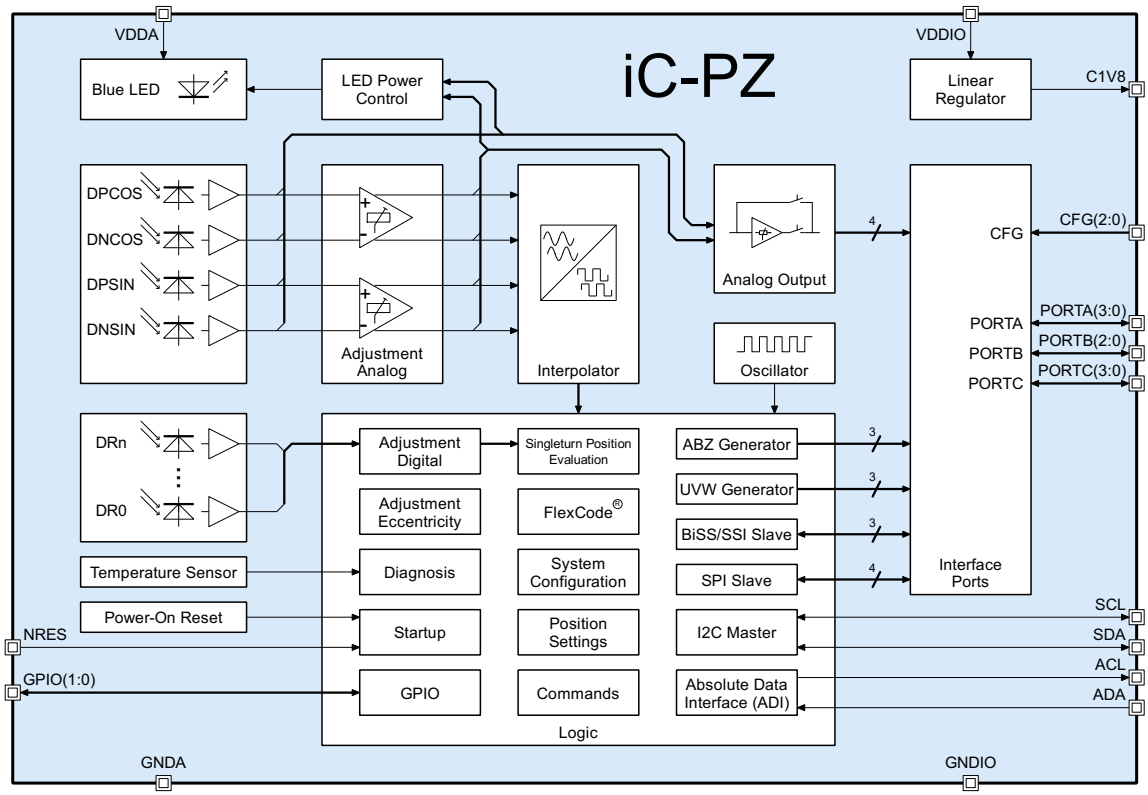


optoQFN32-5x5

5 mm x 5 mm x 0.9 mm

RoHS compliant

BLOCK DIAGRAM



DESCRIPTION

The iC-PZ Series represents advanced optical-reflective absolute encoder iCs featuring integrated photosensors. Utilizing an *HD Phased Array* and an *Embedded Blue LED Chip*, an outstanding signal fidelity is obtained at relaxed alignment tolerances.

Typical applications are high-resolution rotary and linear position encoders.

Blue-enhanced photosensors are adapted to the short wavelength of the embedded blue LED, improving the signal contrast for an outstanding jitter performance. The optical crosstalk is minimized due to the unique assembly technology of the emitter and sensor.

The internally powered blue LED ensures constant illumination without any external wiring. A sine square or sum control mode is selectable for LED power control.

Automatic adjustment features provide fast and reliable signal calibration on command.

Unique features like FlexCount® and FlexCode® guarantee highest flexibility regarding encoder resolution and diameter.

The configuration and calibration data is stored in an external I2C EEPROM. Additional user data can be stored and accessed via iC-PZ.

The analog circuitry and the integrated blue LED are operated at 5 V ± 10 %. For the digital supply including the I/O ports, a voltage range of 2.25 V to 5.5 V is possible. Both supply inputs can be shorted and operated at 5 V.

BiSS, SSI, and SPI are supported as digital interfaces to ensure easy system-integration.

General notice on materials under excessive conditions
Epoxy resins (such as solder resists, IC package and injection molding materials, as well as adhesives) may show discoloration, yellowing, and surface changes in general when exposed long-term to high temperatures, humidity, irradiation, or due to thermal treatments for soldering and other manufacturing processes.

Equally, standard molding materials used for IC packages can show visible changes induced by irradiation, among others when exposed to light of shorter wavelengths, blue light for instance. Such surface effects caused by visible or IR LED light are rated to be of cosmetic nature, without influence to the chip's function, its specifications and reliability.

Note that any other material used in the system (e.g. varnish, glue, code disc) should also be verified for irradiation effects.

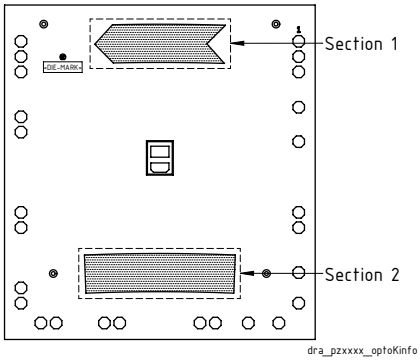
General notice on application-specific programming
Parameters defined in the datasheet represent supplier's attentive tests and validations, but - by principle - do not imply any warranty or guarantee as to their accuracy, completeness or correctness under all application conditions. In particular, setup conditions, register settings and power-up have to be thoroughly validated by the user within his specific application environment and requirements (system responsibility).

The chip's performance in application is impacted by system conditions like the quality of the optical target, the illumination, temperature and mechanical stress, sensor alignment and initial calibration.

CONTENTS

PACKAGING INFORMATION

SENSOR LAYOUT

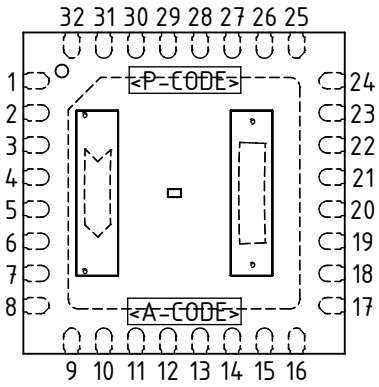


AOI CRITERIA

<Die Mark>	<Section>	<Area Class>[1]
iC-PZxxxx	1	A16
	2	A25

[1] Inspection class for the optical inspection of detector areas. Refer to Optical Selection Criteria for further description.

PIN CONFIGURATION
oQFN32-5x5 (5 mm x 5 mm)

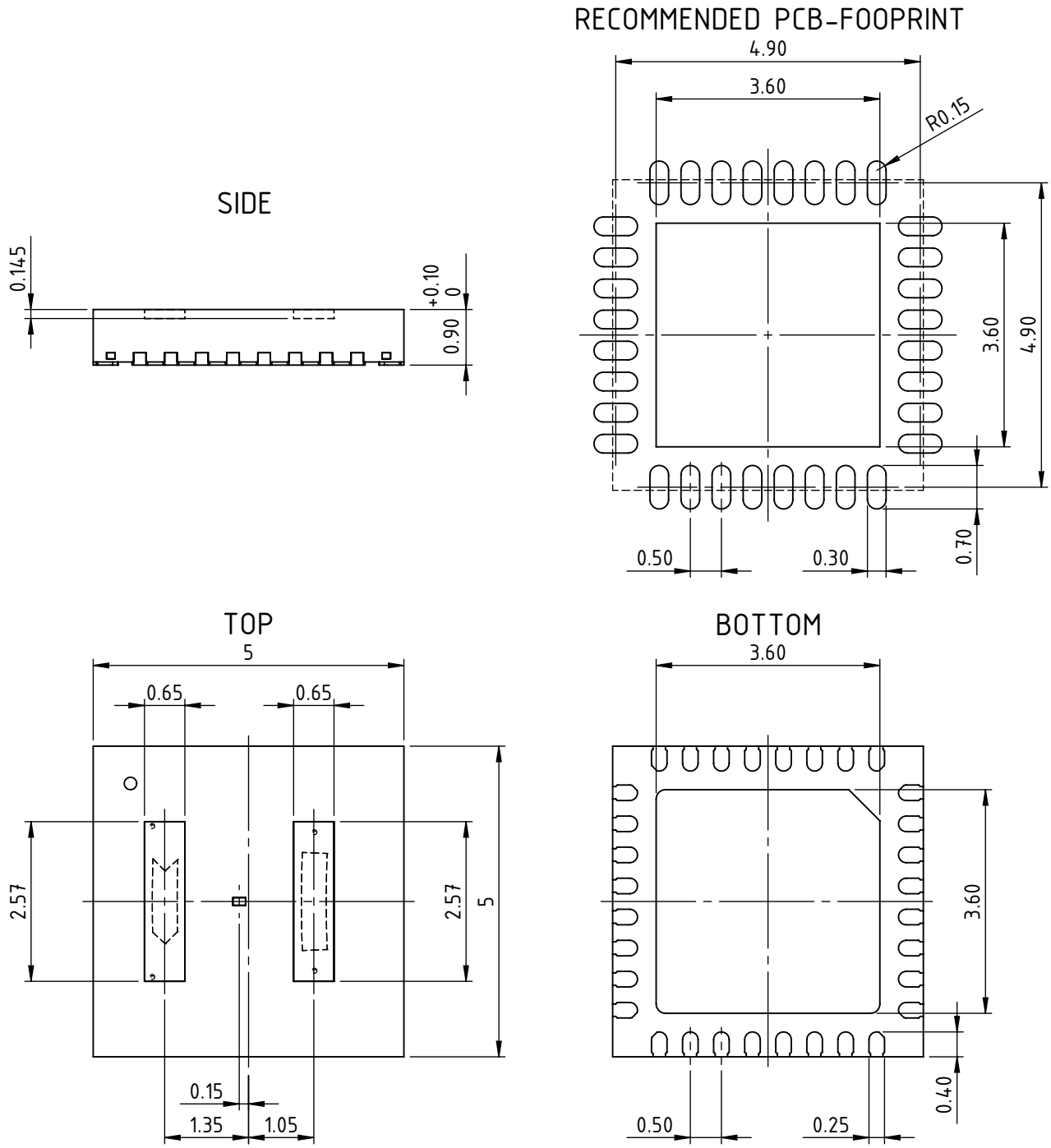


PIN FUNCTIONS

No.	Name	Function
1	CFG(0)	Port Configuration Input
8	PORTA(3)	Interface Port A
9	PORTA(2)	Interface Port A
10	PORTA(1)	Interface Port A
11	PORTA(0)	Interface Port A
12	C1V8	Core Voltage Buffer Capacitance (see Elec. Char. R01)
13	GNDIO[3]	Digital I/O Ground
14	VDDIO	+2.25 V. . . +5.5 V Digital I/O Supply Voltage Input
15	PORTB(2)	Interface Port B
16	PORTB(1)	Interface Port B
17	PORTB(0)	Interface Port B
18	ACL	Absolute Data Interface, clock line
19	ADA	Absolute Data Interface, data line
20	GPIO(1)	General Purpose I/O
21	GPIO(0)	General Purpose I/O
22	NRES	Reset Input
23	PORTC(3)	Interface Port C
24	PORTC(2)	Interface Port C
25	PORTC(1)	Interface Port C
26	PORTC(0)	Interface Port C
27	SCL	I2C Master, clock line
28	SDA	I2C Master, data line
29	GNDA[3]	Analog Ground
30	VDDA	+4.5 V. . . +5.5 V Analog Supply Voltage Input
31	CFG(2)	Port Configuration Input
32	CFG(1)	Port Configuration Input
2..7	n.c.[1]	
	BP[2]	Backside Pad / Exposed Pad

IC top marking: <P-CODE> = product code, <A-CODE> = assembly code (subject to changes);
[1] Pin numbers marked with n.c. are not connected.
[2] The backside pad has to be connected by a single link to GNDA. A current flow across the pad is not permissible.
[3] GNDA and GNDIO must be at the same potential but should be connected with separate lines from a star point on the PCB.

PACKAGE DIMENSIONS



All dimensions given in mm. General Tolerances of form and position according to JEDEC MO-220.
Positional tolerance of sensor pattern: ±70µm / ±1° (with respect to center of backside pad).
Maximum molding excess +20µm / -75µm versus surface of glass. Small pits in the mold surface, which may occasionally appear due to the manufacturing process, are cosmetic in nature and do not affect reliability.

dra_oqfn32-5x5-4_pzxxxx_0_pack_1, 10:1

ABSOLUTE MAXIMUM RATINGS

Beyond these values damage may occur; device operation is not guaranteed.

Item No.	Symbol	Parameter	Conditions	Min.	Max.	Unit
G001	VDDA	Voltage at VDDA	Referenced to GNDA	-0.3	6	V
G002	I(VDDA)	Current in VDDA		-20	100	mA
G003	VDDIO	Voltage at VDDIO	Referenced to GNDA	-0.3	6	V
G004	I(VDDIO)	Current in VDDIO		-20	100	mA
G005	GNDIO	Voltage at GNDIO	Referenced to GNDA Supply voltage at VDDA or VDDIO applied	-0.3	0.3	V
G006	V(C1V8)	Voltage at C1V8	Referenced to GNDIO	-0.3	2.0	V
G007	I(C1V8)	Current in C1V8		-20	20	mA
G008	V(PORTC)	Voltage at PORTC(3:0)	Referenced to GNDA	-0.3	VDDA + 0.3	V
G009	I(PORTC)	Current in PORTC(3:0)		-20	20	mA
G010	V()	Pin Voltage, all remaining pins	Referenced to GNDA	-0.3	VDDIO + 0.3	V
G011	I()	Pin Current, all remaining pins		-20	20	mA
G012	Vd()	ESD Susceptibility	HBM, 100 pF discharged through 1.5 kΩ		2	kV
G013	Tj	Junction Temperature		-40	140	°C

[1] JEDEC document JEP 155: 500V HBM allows safe manufacturing with a standard ESD control process

THERMAL DATA

Item No.	Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
T01	Ta	Operating Ambient Temperature Range		-40		125	°C
T02	Ts	Permissible Storage Temperature Range		-40		125	°C
T03	Tpk	Soldering Peak Temperature	tpk < 20 s, convection reflow MSL 3 (max. floor life 168 h at 30 °C and 60 % RH); Refer to Handling and Soldering Conditions for details.			245	°C
T04	Rthja	Thermal Resistance Chip to Ambient	Package mounted on PCB according to JEDEC standard		50		K/W

All voltages are referenced to ground unless otherwise stated.
All currents flowing into the device pins are positive; all currents flowing out of the device pins are negative.

ELECTRICAL CHARACTERISTICS

Operating conditions: VDDA = 4.5...5.5 V, VDDIO = 2.25...VDDA V, GNDA = GNDIO = 0 V, Tj = -40...140 °C, unless otherwise noted

Item No.	Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
General							
001	VDDA	Analog Supply Voltage	referenced to GNDA	4.5	5.0	5.5	V
002	I(VDDA)	Analog Supply Current	no external load, LED off refer to Table 145 for details without analog output buffer with analog output buffer		 18.4 22.2		 mA mA
003	VDDIO	I/O Supply Voltage	referenced to GNDIO	2.25		VDDA	V
004	I(VDDIO)	I/O Supply Current	ports configured to BiSS/ABZ/Analog, default register values, 600 RPM (iC-PZ2656) VDDIO = 5.5 V, no external load, NRES = low VDDIO = 2.25 V, no external load, NRES = high VDDIO = 5.5 V, no external load, NRES = high		 3.8 14.5 15.0		 mA mA mA
005	SR(VDDIO)	Slewrate of VDDIO	in range 1.0 V..VDDIOon	25			V/s
006	V(C1V8)	Digital Core Voltage	generated internally	1.62	1.8	1.98	V
007	α()e,mx	Maximum Permissible Acceleration	$\alpha()e = \frac{d\omega}{dt}$ for sine/cosine for linear systems: a()mx = $\frac{\alpha()e,mx}{2\pi} \cdot r_{nat}$ with r_{nat} native resolution, i.e. line distance of the incremental track on the scale PZ01L: r_{nat} = 204.8 µm → a()mx = 6 500 $\frac{m}{s^2}$			200	10^6 rade/s^2
Digital I/O Pads							
201	V()	Pin-Open Voltage CFG(2:0)		40	50	60	%VDDIO
202	Vt()hi	Threshold high CFG(2:0)				90	%VDDIO
203	Vt()med	Threshold medium CFG(2:0)		40		60	%VDDIO
204	Vt()lo	Threshold low CFG(2:0)		10			%VDDIO
205	Vt()hys	Threshold Hysteresis medium/high or low/medium CFG(2:0)			10		%VDDIO
211	Rpu()	Pull-Up Resistor CFG(2:0)	V(CFG) = 0 V	130	200	280	kΩ
212	Rpd()	Pull-Down Resistor CFG(2:0)	V(CFG) = VDDIO	130	200	280	kΩ
213	Vt()hi	Threshold high NRES, GPIO(1:0), SCL, SDA, ADA, PORTA(3:0), PORTB(2:0), PORTC(3:0)	pins of PORTA/B/C only if configured as inputs			70	%VDDIO
215	Vt()lo	Threshold low NRES, GPIO(1:0), SCL, SDA, ADA, PORTA(3:0), PORTB(2:0), PORTC(3:0)	pins of PORTA/B/C only if configured as inputs	30			%VDDIO
217	Vt()hys	Threshold Hysteresis NRES, GPIO(1:0), SCL, SDA, ADA, PORTA(3:0), PORTB(2:0), PORTC(3:0)	pins of PORTA/B/C only if configured as inputs		15		%VDDIO
219	Ipu()	Pull-Up Current NRES, GPIO(1:0), ADA, PORTA(3:0), PORTB(2:0), PORTC(3:0)	V() = GNDIO pins of PORTA/B/C only if configured as inputs pin GPIO(0) only for GPIO0_CFG = 00/01 pin GPIO(1) only for GPIO1_CFG = 00/01 and IC not in reset	-50		-8	uA
220	Ipd()	Pull-Down Current GPIO(1:0)	V() = VDDIO pin GPIO(0) only for GPIO0_CFG = 10 pin GPIO(1) only for GPIO1_CFG = 10 or IC in reset	8		50	uA
222	Isc()hi	Short-Circuit Current high GPIO(1:0), ACL, PORTA(3:0), PORTB(2:0), PORTC(3:0)	V() = GNDIO, pins of PORTA/B/C only if configured as outputs VDDIO = 2.5 V ±10 % VDDIO = 3.3 V ±10 % VDDIO = 5 V ±10 %	 -55 -75 -120			 mA mA mA

ELECTRICAL CHARACTERISTICS

Operating conditions: VDDA = 4.5...5.5 V, VDDIO = 2.25...VDDA V, GNDA = GNDIO = 0 V, Tj = -40...140 °C, unless otherwise noted

Item No.	Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
224	Isc()lo	Short-Circuit Current lo GPIO(1:0), SCL, SDA, ACL, PORTA(3:0), PORTB(2:0), PORTC(3:0)	V() = VDDIO, pins of PORTA/B/C only if configured as outputs VDDIO = 2.5 V ±10 % VDDIO = 3.3 V ±10 % VDDIO = 5 V ±10 %			 55 75 120	 mA mA mA
226	Vs()hi	Saturation Voltage high GPIO(1:0), ACL, PORTA(3:0), PORTB(2:0), PORTC(3:0)	Vs()hi = VDDIO - V() I() = -4 mA			0.4	V
227	Vs()lo	Saturation Voltage low GPIO(1:0), ACL, PORTA(3:0), PORTB(2:0), PORTC(3:0)	I() = 4 mA			0.4	V
228	Is()lo	Saturation Current low SCL, SDA	V() = 400 mV V() = 600 mV	3 6			mA mA
229	tr()	Rise Time GPIO(1:0), ACL, PORTA(3:0), PORTB(2:0), PORTC(3:0)	CL = 20 pF, rise 30..70 % VDDIO PADx_CFG = 00 and GPIO(1:0) PADx_CFG = 01 PADx_CFG = 10 PADx_CFG = 11			 220 75 15 3.5	 ns ns ns ns
230	tf()	Fall Time GPIO(1:0), ACL, PORTA(3:0), PORTB(2:0), PORTC(3:0)	CL = 20 pF, fall 70..30 % VDDIO PADx_CFG = 00 and GPIO(1:0) PADx_CFG = 01 PADx_CFG = 10 PADx_CFG = 11			 220 75 15 3.5	 ns ns ns ns
231	tf()	Fall Time SCL, SDA	CL = 10..100 pF, fall 70..30 % VDDIO VDDIO = 2.25..3.0 V VDDIO = 3.0..5.5 V	 15 20		 150 250	 ns ns
PRC Photocurrent Amplifiers and Comparators							
306	fc,r()hi	Cut-Off Frequency PRC (-3 dB)		1000			kHz
Quad Photocurrent Amplifier							
501	fc,a()hi	Cut-Off Frequency Analog (-3 dB)		240			kHz
505	Vv()dc,eff	Effective DC Signal Level	LED_CTRL = 1 and LED_CUR = 0 (sum control) Vv()dc,eff = Vv()dc - Vv()d with Vv()d dark signal level	280		480	mV
Analog Output							
A01	Vout()dc	Output Signal DC Level	ANA_SEL = 00	48	50	52	%VDDA
A02	Vout()ac	Output Signal AC Amplitude	ANA_SEL = 00 ANA_OS = 0 ANA_OS = 1		 1000 250		 mV mV
A03	I()mx	Permissible Load Current	ANA_SEL = 00 ANA_OS = 0 ANA_OS = 1	 -1 -6		 1 6	 mA mA
A04	C()mx	Permissible Capacitive Load	ANA_SEL = 00			50	pF
ABZ Generator							
C01	AAabs (INL)	Absolute Angle Accuracy (Integral Nonlinearity)	Ideal waveform, f()sin ≤ 60 kHz IPO_FILT1 = 0xEA, IPO_FILT2 = 0x4		0.5		°e
C02	AArel (DNL)	Relative Angle Accuracy (Differential Nonlinearity)	Ideal waveform IPO_FILT1 = 0xEA, IPO_FILT2 = 0x4 ABZ_PER ≤ 2^{SYS_eff} x 256, f()sin = 128 Hz ABZ_PER ≤ 2^{SYS_eff} x 256, f()sin = 2.56 kHz ABZ_PER ≤ 2^{SYS_eff} x 1024, f()sin = 128 Hz ABZ_PER ≤ 2^{SYS_eff} x 1024, f()sin = 2.56 kHz see also Figure 1		 15 2.5 35 7		 % % % %
C03	fout()	Maximum Frequency per Output	ABZ_MTD = 0x0 (default), f()sin ≤ 240 kHz	6			MHz
LED Power Control							
L01	Iop()	Permissible LED Current	except startup	0.5		30	mA
L02	Ictrl()	Controlled LED Output Current	refer to Table 145 for details		5..10		mA
L03	Iop()min	Minimum LED Current			50		%Iop()

ELECTRICAL CHARACTERISTICS

Operating conditions: VDDA = 4.5...5.5 V, VDDIO = 2.25...VDDA V, GNDA = GNDIO = 0 V, Tj = -40...140 °C, unless otherwise noted

Item No.	Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
L07	Ic,led	LED Constant Current	LED_CUR = 0x0 LED_CUR = 0x1 LED_CUR = 0x2 LED_CUR = 0x3 LED_CUR = 0x4 LED_CUR = 0x5 LED_CUR = 0x6 LED_CUR = 0x7	30 0 0.75 1.5 3 6 12 24	40 0 1 2 4 8 16 32	70 0.1 2.3 4.3 8 16 29 56	mA mA mA mA mA mA mA mA
Oscillator							
O01	fosc	Oscillator Frequency		72	80	88	MHz
Power-On Reset & Voltage Monitoring							
P01	VDDAon	Turn-On Threshold VDDA (power-on release)	increasing voltage at VDDA			3.95	V
P02	VDDAoff	Turn-Off Threshold VDDA (power-down reset)	decreasing voltage at VDDA	3.00			V
P03	VDDAhys	Threshold Hysteresis VDDA	VDDAhys = VDDAon - VDDAoff	200	300	600	mV
P04	VDDIOpor	Threshold VDDIO for Voltage Regulator (power-on)	increasing voltage at VDDIO			2.20	V
P05	VDDIOon	Turn-On Threshold VDDIO (diagnosis-ok)	increasing voltage at VDDIO VDDIOSEL = 00 (2.5 V) VDDIOSEL = 01 (3.3 V) VDDIOSEL = 10 (5.0 V)			 2.20 2.95 3.95	 V V V
P06	VDDIOoff	Turn-Off Threshold VDDIO (diagnosis-error)	decreasing voltage at VDDIO VDDIOSEL = 00 (2.5 V) VDDIOSEL = 01 (3.3 V) VDDIOSEL = 10 (5.0 V)	 1.3 2.2 3.0			 V V V
P07	VDDIOhys	Threshold Hysteresis VDDIO	VDDIOhys = VDDIOon - VDDIOoff VDDIOSEL = 00 (2.5 V) VDDIOSEL = 01 (3.3 V) VDDIOSEL = 10 (5.0 V)		 250 200 250		 mV mV mV
Linear Regulator							
R01	C(C1V8)	Recommended Capacity at C1V8			100		nF
Adjustment Analog							
S01	COROS()min	Minimum Offset Correction	COS_OFF(9:0) = 0x3FF and/or SIN_OFF(9:0) = 0x3FF			-100	mV
S02	COROS()mx	Maximum Offset Correction	COS_OFF(9:0) = 0x1FF and/or SIN_OFF(9:0) = 0x1FF	100			mV
S03	CFA()min	Minimum Amplitude Correction Factor	SC_GAIN = 0x200			0.825	
S04	CFA()mx	Maximum Amplitude Correction Factor	SC_GAIN = 0x1FF	1.20			
S05	CORPH()min	Minimum Shift of Phase	SC_PHASE(9:0) = 0x1FF			-10	°e
S06	CORPH()mx	Maximum Shift of Phase	SC_PHASE(9:0) = 0x3FF	10			°e
Temperature Sensor							
T01	Trng	Temperature Sensor Range		-50		175	°C
T02	Tres	Temperature Sensor Resolution			0.1		°C
T03	Tacc	Temperature Sensor Accuracy	Tj = -40..140 °C and after adjustment at iC-Haus	-3		3	°C
Startup							
W01	tstart()	Startup Time	VDDA > VDDAon VDDIO > VDDIOpor EEPROM with valid configuration attached to SCL/SDA		14		ms

ELECTRICAL CHARACTERISTICS

Operating conditions: VDDA = 4.5...5.5 V, VDDIO = 2.25...VDDA V, GNDA = GNDIO = 0 V, Tj = -40...140 °C, unless otherwise noted

Item No.	Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Serial Interfaces							
Z01	fBISS	Permissible BiSS-Slave Frequency	point-to-point configuration			20	MHz
			bus configuration (chaining multiple chips)			10	MHz
Z02	fSSI	Permissible SSI-Slave Frequency				10	MHz
Z03	fSPI	Permissible SPI-Slave Frequency	point-to-point configuration			12	MHz
			bus configuration (chaining multiple chips), as of t_{P1} and t_{P3}				
			2 chips			10	MHz
			3 chips			5.88	MHz
			4 chips			4.17	MHz
			n chips, n≥2: $f = \frac{100}{7n-4}$			f	MHz
Z04	fI2C	I2C-Master Frequency	EEPROM attached to SCL/SDA		220	400	kHz
Z05	tsample	Period of Adaptive Timeout Sampling Clock (for EDS)	refer to characteristics in BiSS SLAVE on page 43	50	67	75	ns
Z06	tout()adapt	Adaptive Slave Timeout at SLO	BISS_NTOA = 0 refer to timing Figure 4 t_{init} measured as first 1.5 · T(MA) each frame	0.075	t_{init} + 0.2	24	µs
Z07	tout()fixed	Fixed Slave Timeout at SLO	BISS_NTOA = 1 refer to timing Figure 4	16	20	24	µs

ELECTRICAL CHARACTERISTICS: Diagrams

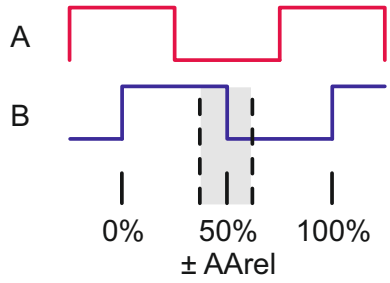


Figure 1: Definition of AB duty cycle variation.

OPERATING REQUIREMENTS: Supply Voltages

Item No.	Symbol	Parameter	Conditions	Min.	Max.	Unit
Supply Voltages						
I001	$t_{r,VDDIO}$	VDDIO Rise Time		refer to Elec. Char. 005		
I002	VDDIO(t)	Voltage VDDIO at time t			VDDA(t)	V

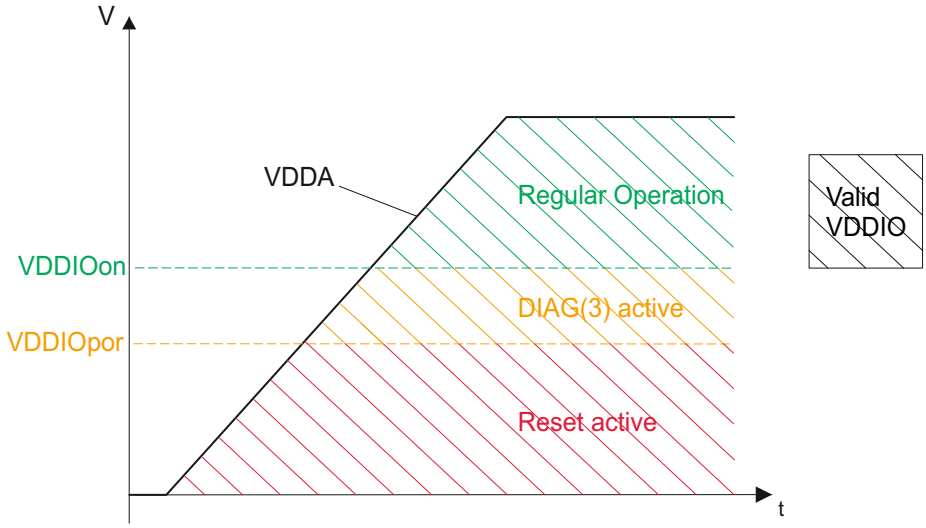


Figure 2: Supply voltages at startup

OPERATING REQUIREMENTS: BiSS Slave

Item No.	Symbol	Parameter	Conditions	Min.	Max.	Unit
BiSS protocol						
I101	t_{frame}	Permissible Frame Repetition		(*)	indefinite	
I102	t_C	Permissible Clock Period		50		ns
I103	t_{L1}	Clock Signal hi Level Duration		20	t_{out}	ns
I104	t_{L2}	Clock Signal lo Level Duration		20	t_{out}	ns
I105	t_{busy}	Processing Time with Start Bit Delay			$5 \cdot t_C$	
I106	t_{P3}	Propagation Delay: SLO stable after MA lo → hi	CL = 20 pF, rise to 70 % VDDIO or fall to 30 % VDDIO PADx_CFG = 00 PADx_CFG = 01 PADx_CFG = 10 PADx_CFG = 11		 400 150 60 35	 ns ns ns ns
I107	t_{out}	Adaptive Slave Timeout		refer to Elec. Char. Z06		
I108	t_{S1}	Setup Time: SLI stable before MA hi → lo		5		ns
I109	t_{H1}	Hold Time: SLI stable after MA hi → lo		10		ns

(*) Allow t_{out} to elapse.

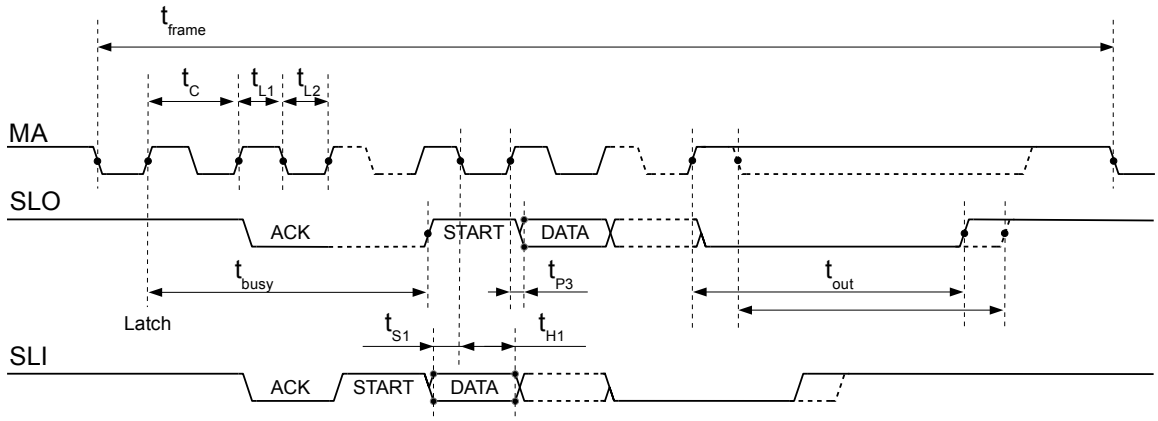


Figure 3: BiSS timing

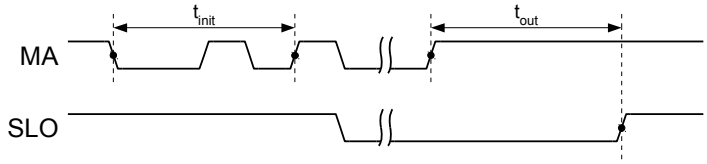


Figure 4: BiSS slave timeout

OPERATING REQUIREMENTS: SSI Slave

Item No.	Symbol	Parameter	Conditions	Min.	Max.	Unit
SSI protocol						
I201	t_{frame}	Permissible Frame Repetition		(*)	indefinite	
I202	t_C	Permissible Clock Period		100		ns
I203	t_{L1}	Clock Signal hi Level Duration		25	t_{out}	ns
I204	t_{L2}	Clock Signal lo Level Duration		25	t_{out}	ns
I205	t_{RQ}	REQ Signal lo Level Duration		50		ns
I206	t_{P3}	Propagation Delay: SLO stable after MA lo → hi	CL = 20 pF, rise to 70 % VDDIO or fall to 30 % VDDIO PADx_CFG = 00 PADx_CFG = 01 PADx_CFG = 10 PADx_CFG = 11		 400 150 60 35	 ns ns ns ns
I207	t_{out}	Adaptive Slave Timeout		refer to Elec. Char. Z06		

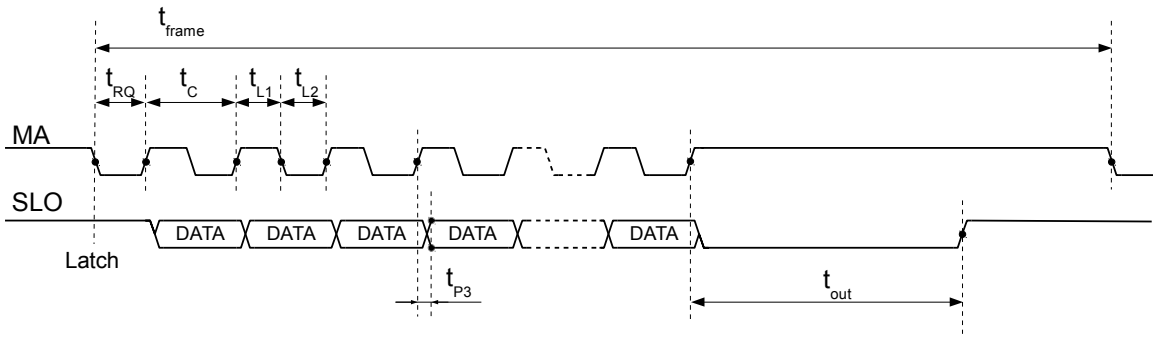


Figure 5: SSI timing

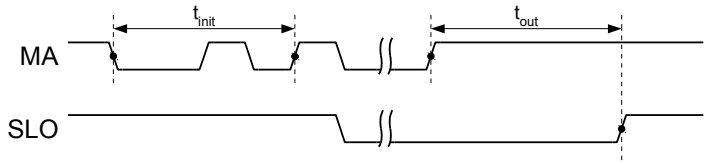


Figure 6: SSI slave timeout

OPERATING REQUIREMENTS: SPI Slave

Item No.	Symbol	Parameter	Conditions	Min.	Max.	Unit
SPI protocol						
I301	t_{C1}	Permissible Clock Cycle Time		83.33		ns
I302	t_{L1}	Clock Signal lo Level Duration		30		ns
I303	t_{L2}	Clock Signal hi Level Duration		30		ns
I304	t_{S1}	Setup Time: NCS lo before SCLK lo → hi		41.67		ns
I305	t_{H1}	Hold Time: NCS lo after SCLK lo → hi	valid for SPI mode 3	41.67		ns
I306	t_{H3}	Hold Time: NCS lo after SCLK hi → lo	valid for SPI mode 0	41.67		ns
I307	t_{W2}	Wait Time: NCS hi before SCLK change		200		ns
I308	t_{W1}	Wait Time: between NCS lo → hi and NCS hi → lo		200		ns
I309	t_{H2}	Hold Time: MOSI stable after SCLK lo → hi		5		ns
I310	t_{S2}	Setup Time: MOSI stable before SCLK lo → hi		15		ns
I311	t_{P1}	Propagation Delay: MISO stable after SCLK hi → lo	CL = 20 pF, rise to 70 % VDDIO or fall to 30 % VDDIO PADA_CFG = 00 PADA_CFG = 01 PADA_CFG = 10 PADA_CFG = 11		 400 150 60 35	 ns ns ns ns
I312	t_{P3}	Propagation Delay: MISO stable after MOSI change	CL = 20 pF, rise to 70 % VDDIO or fall to 30 % VDDIO PADA_CFG = 00 PADA_CFG = 01 PADA_CFG = 10 PADA_CFG = 11		 400 150 60 35	 ns ns ns ns
I313	t_{P4}	Propagation Delay: MISO stable after NCS hi → lo	CL = 20 pF, rise to 70 % VDDIO or fall to 30 % VDDIO PADA_CFG = 00 PADA_CFG = 01 PADA_CFG = 10 PADA_CFG = 11		 400 150 60 35	 ns ns ns ns
I314	t_{P2}	Propagation Delay: MISO hi impedance after NCS lo → hi			35	ns

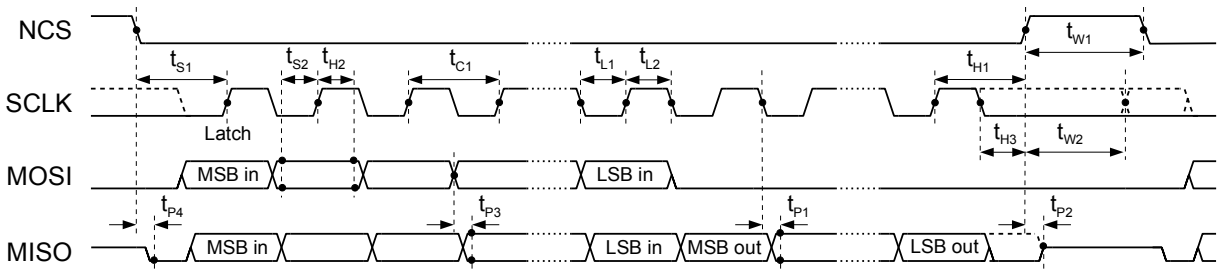


Figure 7: SPI timing

OPERATING REQUIREMENTS: Absolute Data Interface (ADI)

Item No.	Symbol	Parameter	Conditions	Min.	Max.	Unit
ADI protocol (SSI)						
I401	f_{ACL}	ADI clock frequency	ADI_CFG(6) = 0 (slow mode) ADI_CFG(6) = 1 (fast mode)	150 1500		kHz kHz
I402	T_{ACL}	ADI clock period		$1/f_{ACL}$		
I403	t_{hi}, t_{lo}	ADI clock hi/lo level duration		50		$\%T_{ACL}$
I404	T_{frame}	Frame repetition period	Normal operation Startup, if ADI_CFG(1) = 0 Startup, if ADI_CFG(1) = 1	1500 1500 200		µs µs µs
I405	t_s	Setup time: ADA stable before falling ACL edge		100		ns
I406	t_h	Hold time: ADA stable after falling ACL edge		100		ns
I407	t_{out}	Permissible slave timeout	Rising-edge-triggered monoflop Falling-edge-triggered monoflop Dual-edge-triggered monoflop	11.5 11.5 5.75	40 40 40	µs µs µs

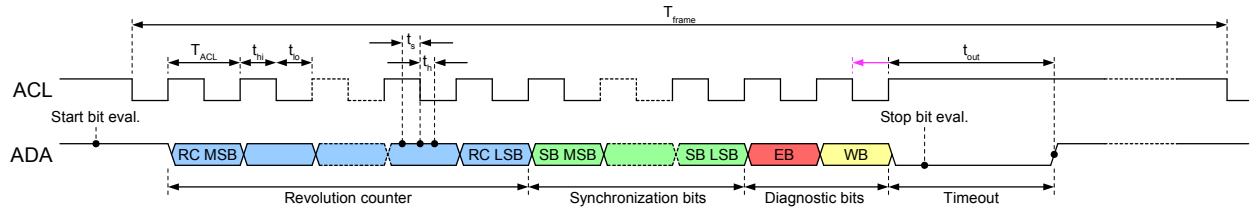


Figure 8: ADI timing with SSI protocol

ADA sampling and setup/hold times

ADA is sampled with the double frequency of ACL. With each rising ACL edge iC-PZ processes the previously sampled ADA, i.e., the ADA that has been sampled with the previous falling ACL edge. As a consequence, ADA has to be stable after $t = (T_{ACL}/2 - t_s)$ after a rising ACL edge.

SIGNAL DEFINITIONS

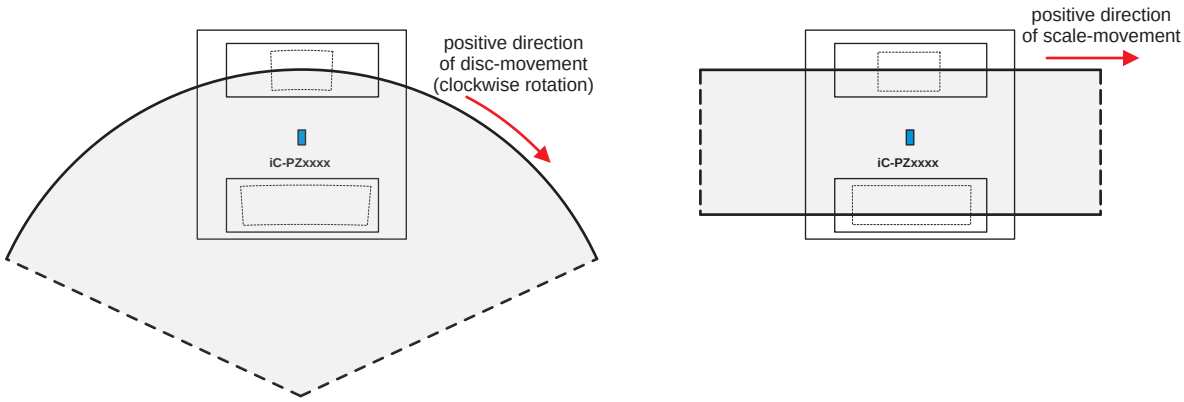


Figure 9: Definition of positive direction of movement

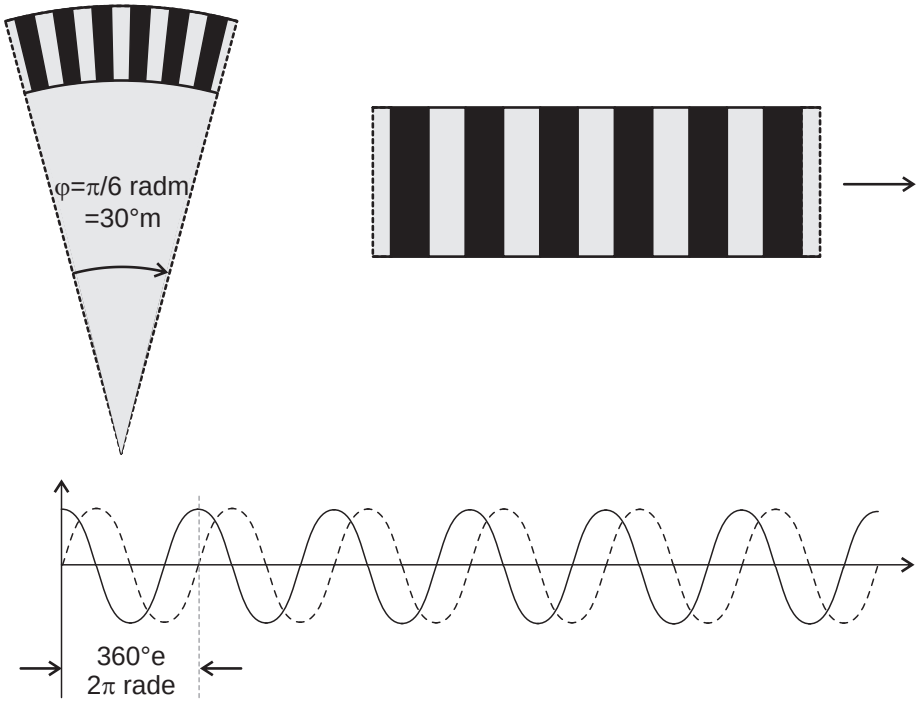


Figure 10: Definition of mechanical degrees / radians (°m / radm) and electrical degrees / radians (°e / rade)

A section of a code disc and a section of a linear scale are shown in Figure 10. Six sine/cosine periods are generated by either of them as illustrated. In this example, the code disc has to be moved by 30 mechanical degrees (°m) to generate those six signal periods. Each period represents 360 electrical degrees (°e).

If radians are used instead of degrees, the code disc has to be moved by $\frac{\pi}{6}$ mechanical radians (radm). Respectively, each period represents 2π electrical radians (rade).

In this document, the frequency of sine/cosine signals is denoted as f()sin.

LINEAR REGULATOR

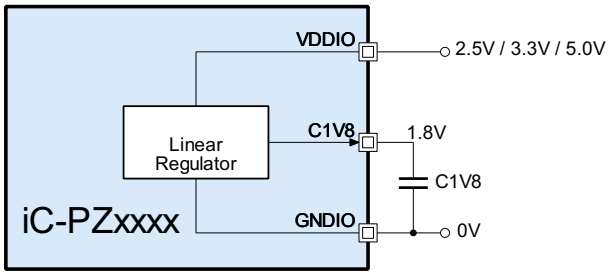


Figure 11: External capacitance blocking pin C1V8

An integrated linear regulator generates the digital core voltage of 1.8 V from the digital supply VDDIO/GNDIO. To ensure a stable regulated voltage, a blocking capacitor at pin C1V8 is required. The recommended capacitance is given in R01 on page 11.

Note: The regulated voltage is for internal use only and must not be used to supply additional circuitry. Sensing the regulated voltage with a high impedance, e. g. for safety reasons, is possible.

EEPROM SELECTION

For proper usage of iC-PZ, an external I2C-EEPROM with the characteristics defined below is required:

- Size of 2 kbit up to 16 kbit (larger sizes are recommended to provide storage for BiSS EDS and user data).
- Supply voltage from 1.8 V up to desired VDDIO. If VDDIO is shorted to VDDA, the supply voltage may begin at 3.0 V (see P02 on page 9).
- Compatible with 400 kHz I2C bus mode.
- Page size $\geq$ 8 byte.
- 7-bit I2C device address is set to 0x50.
- Protocol with one address byte only, as shown in Figure 48

ATTENTION: EEPROMs which consider block selection bits as don't care should not be used. This can be the case with 8-pin devices, as well as with 5-pin devices not featuring A2, A1, A0 pins.
Be aware of potential conflicts:
If a user addresses memory beyond the 2 kbit range, iC-PZ configuration data will be overwritten.
If further I2C slave devices are operated on the same bus, higher device addresses may be occupied.
RPL (register protection level) may be passed over.

POWER-ON RESET

To ensure correct startup, the system is reset until all power-on thresholds defined in ELECTRICAL CHARACTERISTICS section Power-On Reset are exceeded:

- VDDA must exceed threshold VDDAon
- VDDIO must exceed threshold VDDIOpor

STARTUP

A system-restart is triggered by one of the following events:

- Power-on reset (VDDA, VDDIO)
- Pin NRES (0 = reset, 1 = active)
- Command REBOOT via serial interface

While iC-PZ is in reset state or during power-up phase, pin GPIO(0) is low, indicating that the system is not yet ready. Communication using one of the serial interfaces is not possible at this time. After leaving the reset state, iC-PZ performs its internal startup routines, including reading the configuration stored in the external EEPROM and optionally the multiturn position from an external multiturn-device. During startup, communication using one of the serial interfaces is not allowed. Afterwards, pin GPIO(0) goes high and iC-PZ is ready.

In case the communication with the EEPROM fails, iC-PZ will load its default configuration.

INTERFACE PORTS

Five interfaces, of which three are multiplexed to ports A, B, and C, are provided by iC-PZ. The individual port configuration is made via pins CFG(2:0). By connecting those pins to the appropriate levels GNDIO (L), VDDIO/2 (M), or VDDIO (H), one of the configurations shown in Table 1 is selected. The pin assignment to the corresponding configuration is defined in Table 2. For further configurations refer to INTERFACE PORTS CONFIGURATION on page 29.

Note: As BiSS and SSI share its physical ports, the interface of choice has to be enabled additionally via SSI_EN. Refer to BiSS SLAVE on page 43.

Pin Level			Port Function		
CFG(2)	**CFG(1)**	**CFG(0)**	**Port A**	**Port B**	**Port C**
L	L	L	SPI	BiSS/SSI	ABZ
L	L	M	SPI	BiSS/SSI	Analog
L	L	H	SPI	BiSS/SSI	UVW
H	L	L	BiSS/SSI	ABZ	UVW
H	L	M	BiSS/SSI	ABZ	Analog
H	L	H	BiSS/SSI	UVW	Analog
H	H	L	SPI	ABZ	UVW
H	H	M	SPI	ABZ	Analog
H	H	H	SPI	UVW	Analog
M	L	H	ABZ	UVW	Analog
Others			Reserved (do not use)		

Table 1: Pin configured port function

	Pin Assignment			
Port A	PORTA(3)	PORTA(2)	PORTA(1)	PORTA(0)
Port B	-	PORTB(2)	PORTB(1)	PORTB(0)
Port C	PORTC(3)	PORTC(2)	PORTC(1)	PORTC(0)
Interface	**Interface Signal**			
BiSS/SSI	-	MA	SLI	SLO
SPI	NCS	SCLK	MOSI	MISO
ABZ	-	A	B	Z
UVW	-	U	V	W
Analog	NSIN	PSIN	NCOS	PCOS

Table 2: Pin assignment to interface signal

CIRCUIT DESIGN PROPOSALS

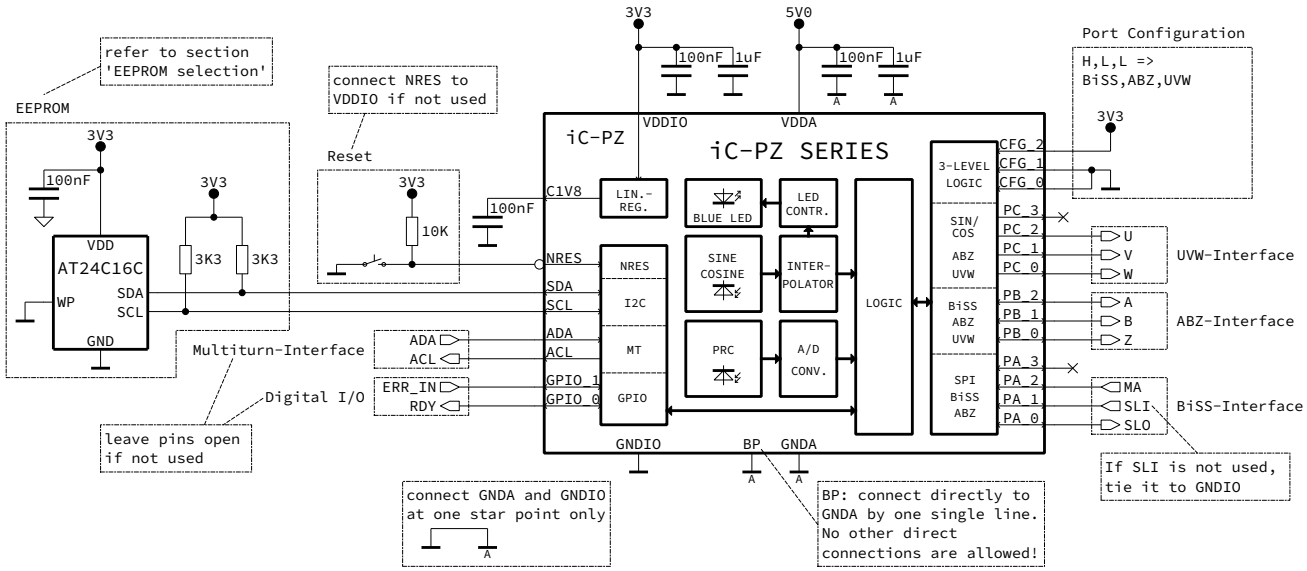


Figure 12: Circuit schematic with BiSS, ABZ and UVW port configuration

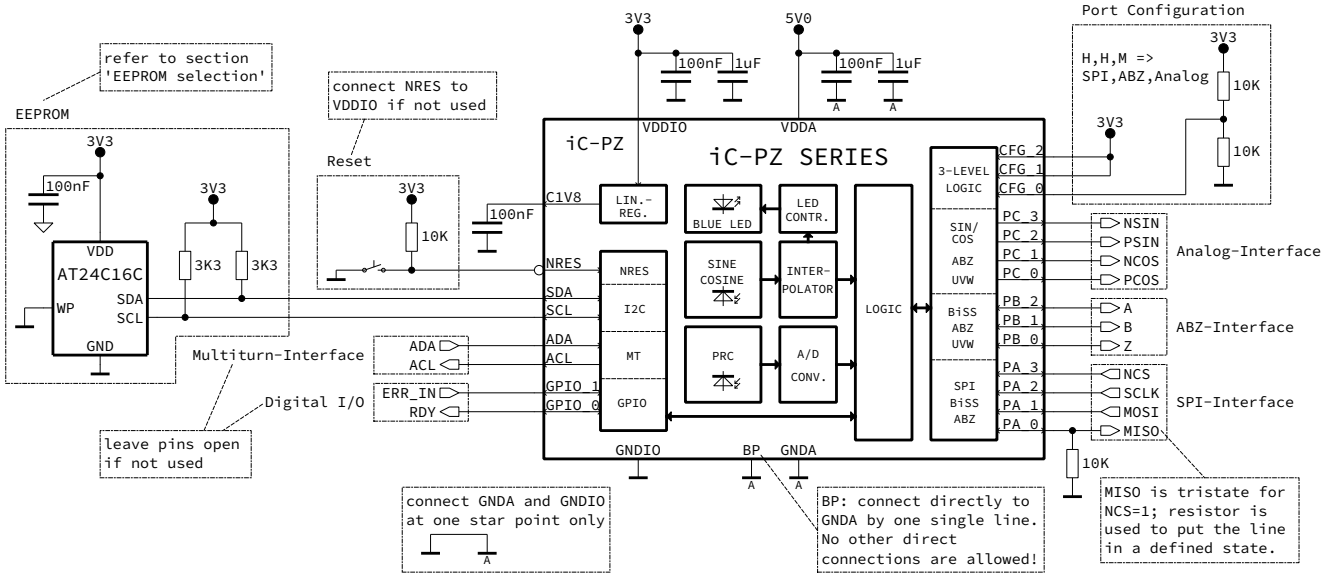


Figure 13: Circuit schematic with SPI, ABZ and analog port configuration

MEMORY ORGANIZATION

Besides the on-chip RAM, data from an external EEPROM or other I2C devices can be accessed via iC-PZ. An overview of the memory organization is given in Table 3.
Registers are organized in banks. Banks 0x00..0x0E contain device configuration registers, which are located in the on-chip RAM. Registers 0x40..0x7F are not assigned to banks and are accessed directly disregarding the active bank. Banks 0x20..0x3F can be used to access registers in an external EEPROM. Additional MT devices can be configured via bank 0x20. EDS and user data is stored in banks 0x24..0x3F. Additionally, data from up to four external I2C devices can be accessed using banks 0x40..0x4F.

Bank	Address	Content	Location	RPL
0x00..0x0E	0x00..0x3F	iC-PZ Device Configuration (volatile)	On-chip RAM	r / w
all	0x40..0x7F	iC-PZ Direct Access	On-chip RAM	n. a.
0x20	0x00..0x3F	MT Device Configuration (e. g. iC-PV)	EEPROM: 0x000 - 0x03F	r / w
X	X	iC-PZ Device Configuration (non-volatile)	EEPROM: 0x040 - 0x0FF	n. a.
0x24..0x3F	0x00..0x3F	EDS, User Data	EEPROM: 0x100 - 0x7FF	r / w
0x40..0x43	0x00..0x3F	I2C device 0 data	I2C device memory	n. a.
0x44..0x47	0x00..0x3F	I2C device 1 data	I2C device memory	n. a.
0x48..0x4B	0x00..0x3F	I2C device 2 data	I2C device memory	n. a.
0x4C..0x4F	0x00..0x3F	I2C device 3 data	I2C device memory	n. a.

Table 3: Memory organization overview

EEPROM Access

The external EEPROM is used to store the iC-PZ device configuration non-volatile, so that the data will be remaining after power-down. The memory addressing and data transmission to exchange the device configuration with the EEPROM is fully handled by iC-PZ, when receiving the appropriate command from any serial interface. Either a single bank or the complete device configuration can be read or written. When writing a bank to the EEPROM, the CRC value is calculated automatically by iC-PZ. Refer to COMMANDS on page 53 for details.
The device configuration data is secured by an 8-bit CRC value for every bank. Each CRC value has a Hamming Distance of 3 bits. After power-on, the data is read in bank by bank. In case a CRC value is incorrect, the bank is read again up to 3 times in total. If the CRC value of a bank is correct, the data is used. Otherwise, the bank uses its default data values. Invalid value are marked individually for each bank in CRC_STAT and as an error bit in DIAG.
The EDS and user data is read and written immediately to/from the EEPROM, when accessing an address in the appropriate bank. As I2C is used for the communication between iC-PZ and EEPROM, data transmission will take a certain amount of time until completed. The corresponding address accessed in the EEPROM can be calculated according to the formula below:

$$EEPROM\_ADR = (BSEL - 0x20) * 0x40 + ADR$$

Bank Selection

The active bank is selected via BSEL. Registers 0x40..0x7F are not affected and can always be accessed disregarding the active bank.

BSEL(7:0)	Addr. 0x40; bit 7:0	default: 0x00
Code	Value	
0x00..0x4F	Active bank	

Table 4: Bank Selection

Register Protection Level (RPL)

The banks containing device configuration, EDS and user data, can be individually protected from write and/or read access. Therefore, a Register Protection Level (RPL) can be set to the active bank by either executing the command RPL_SET_RO (read only) or RPL_SET_NA (no access, neither read nor write). To become persistent, the RPL settings have to be written to the EEPROM. When writing a complete bank from the on-chip RAM to the EEPROM, the RPL is stored automatically. For any other bank located in external memory, the RPL settings are stored in bank 0xF. By writing all banks to the EEPROM, all RPL settings become persistent. To check the RPL that is set for the active bank, the command RPL_GET can be executed.

Once the RPL is stored in the EEPROM, it can not be removed anymore. Nevertheless, setting the RPL from read only (RO) to no access (NA) is possible.

REGISTER MAP

Register map

Bank,Addr	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Interface Ports Configuration								
0x0, 0x00	PADM_CFG(1:0)		PADC_CFG(1:0)		PADB_CFG(1:0)		PADA_CFG(1:0)	
0x0, 0x01	-	PORTC_DIS	PORTB_DIS	PORTA_DIS	-		VDDIOSEL(1:0)	
Interpolator								
0x0, 0x02	*reserved [0x21]* [1]							
0x0, 0x03	IPO_FILT1(7:0)							
0x0, 0x04	*reserved [00000]* [1]					IPO_FILT2(2:0)		
0x0, 0x05	*reserved [0xE6]* [1]							
0x0, 0x06	*reserved [0x10]* [1]							
System Definition								
0x0, 0x07	SYS_OVR(3:0)				-		CD_FLIP	CD_INV
Position Data Length								
0x0, 0x08	-		ST_PDL(5:0)					
0x0, 0x09	-		MT_PDL(5:0)					
Absolute Data Interface (ADI)								
0x0, 0x0A	ADI_OS(4:0)					ADI_SBL(2:0)		
0x0, 0x0B	ADI_MSO(2:0)			ADI_EBP	ADI_EBL(3:0)			
0x0, 0x0C	ADI_CFG(7:1)							*reserved [0]* [1]
0x0, 0x0D	-							ADI_CFG(8)
Singleturn Position Evaluation								
0x0, 0x0E	-				*reserved [0x0]* [1]			
0x0, 0x0F	RAN_FLD	*reserved [001]* [1]			RAN_TOL(3:0)			
0x0, 0x10	CFG_CRC_0(7:0)							
Adjustment Analog (static)								
0x1, 0x00	COS_OFF(1:0)		-					
0x1, 0x01	COS_OFF(9:2)							
0x1, 0x02	SIN_OFF(1:0)		-					
0x1, 0x03	SIN_OFF(9:2)							
0x1, 0x04	SC_GAIN(1:0)		-					
0x1, 0x05	SC_GAIN(9:2)							
0x1, 0x06	SC_PHASE(1:0)		-					
0x1, 0x07	SC_PHASE(9:2)							
Adjustment Digital (static)								
0x1, 0x08	AI_PHASE(1:0)		-					
0x1, 0x09	AI_PHASE(9:2)							
0x1, 0x0A	AI_SCALE(0)	-						
0x1, 0x0B	AI_SCALE(8:1)							
0x1, 0x10	CFG_CRC_1(7:0)							
Adjustment Analog (static + dynamic) – read-only, not stored in EEPROM								
0x1, 0x20	COS_OFFS(1:0)		-					
0x1, 0x21	COS_OFFS(9:2)							
0x1, 0x22	SIN_OFFS(1:0)		-					
0x1, 0x23	SIN_OFFS(9:2)							

[1] Reserved registers must not be changed (default value in square brackets).

Register map								
Bank,Addr	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0x1, 0x24	SC_GAINS(1:0)		-					
0x1, 0x25	SC_GAINS(9:2)							
0x1, 0x26	SC_PHASES(1:0)		-					
0x1, 0x27	SC_PHASES(9:2)							
Adjustment Digital (static + dynamic) – read-only, not stored in EEPROM								
0x1, 0x28	AI_PHASES(1:0)		-					
0x1, 0x29	AI_PHASES(9:2)							
0x1, 0x2A	AI_SCALES(0)	-						
0x1, 0x2B	AI_SCALES(8:1)							
Adjustment Analog Configuration								
0x2, 0x00	SC_GAIN_SEL(3:0)				SC_OFF_SEL(3:0)			
0x2, 0x01	-				SC_PHASE_SEL(3:0)			
0x2, 0x02	*reserved [0x00]* [1]							
Adjustment Digital Configuration								
0x2, 0x03	AI_S_SEL(3:0)				AI_P_SEL(3:0)			
Adjustment Eccentricity (static)								
0x2, 0x04	ECC_AMP(7:0)							
0x2, 0x05	ECC_AMP(15:8)							
0x2, 0x06	ECC_AMP(23:16)							
0x2, 0x07	ECC_AMP(31:24)							
0x2, 0x08	ECC_PHASE(5:0)						-	
0x2, 0x09	ECC_PHASE(13:6)							
0x2, 0x0A	-							ECC_EN
0x2, 0x10	CFG_CRC_2(7:0)							
Analog Output								
0x3, 0x00	-			LED_CONST	LED_CUR(2:0)			LED_CTRL
0x3, 0x01	-					ANA_OS	ANA_SEL(1:0)	
0x3, 0x10	CFG_CRC_3(7:0)							
ABZ Generator								
0x4, 0x00	ABZ_PER(7:0)							
0x4, 0x01	ABZ_PER(15:8)							
0x4, 0x02	ABZ_PER(23:16)							
0x4, 0x03	*reserved [00000]* [1]					ABZ_PER(26:24)		
0x4, 0x04	ABZ_HYS(7:0)							
0x4, 0x05	-				ABZ_MTD(3:0)			
0x4, 0x06	*reserved [0]* [1]	ABZ_CFG(2:0)			ABZ_ZGATE(3:0)			
0x4, 0x08	ABZ_OFF(7:0)							
0x4, 0x09	ABZ_OFF(15:8)							
0x4, 0x10	CFG_CRC_4(7:0)							
UVW Generator								
0x5, 0x00	-			UVW_PP(4:0)				
0x5, 0x01	-						UVW_CFG(1:0)	
0x5, 0x02	UVW_OFF(7:0)							
0x5, 0x03	UVW_OFF(15:8)							
0x5, 0x10	CFG_CRC_5(7:0)							

[1] Reserved registers must not be changed (default value in square brackets).

Register map								
Bank,Addr	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
BiSS/SSI Slave								
0x6, 0x00	BISS_EM(7:0)							
0x6, 0x01	BISS_EM(15:8)							
0x6, 0x02	BISS_EM(23:16)							
0x6, 0x03	BISS_EM(31:24)							
0x6, 0x04	BISS_WM(7:0)							
0x6, 0x05	BISS_WM(15:8)							
0x6, 0x06	BISS_WM(23:16)							
0x6, 0x07	BISS_WM(31:24)							
0x6, 0x08	-		BISS_ST_DL(5:0)					
0x6, 0x09	-		BISS_MT_DL(5:0)					
0x6, 0x0A	-	SSI_EN	SSI_EXT	SSI_GRAY	-	BISS_NTOA	BISS_CRC16	BISS_ENSOL
0x6, 0x0B	-		BISS_CRCS(5:0)					
0x6, 0x10	CFG_CRC_6(7:0)							
SPI Slave								
0x7, 0x00	SPI_EM(7:0)							
0x7, 0x01	SPI_EM(15:8)							
0x7, 0x02	SPI_EM(23:16)							
0x7, 0x03	SPI_EM(31:24)							
0x7, 0x04	SPI_WM(7:0)							
0x7, 0x05	SPI_WM(15:8)							
0x7, 0x06	SPI_WM(23:16)							
0x7, 0x07	SPI_WM(31:24)							
0x7, 0x08	-		SPI_ST_DL(5:0)					
0x7, 0x09	-		SPI_MT_DL(5:0)					
0x7, 0x0A	-							SPI_EXT
0x7, 0x0B	-		SPI_CRCS(5:0)					
0x7, 0x10	CFG_CRC_7(7:0)							
FlexCode®								
0x8, 0x00	FCL(7:0)							
0x8, 0x01	-	FCL(14:8)						
0x8, 0x02	FCS(7:0)							
0x8, 0x03	-	FCS(14:8)						
0x8, 0x10	CFG_CRC_8(7:0)							
GPIO								
0x9, 0x00	GPIO0_M(7:0)							
0x9, 0x01	GPIO0_M(15:8)							
0x9, 0x02	GPIO0_M(23:16)							
0x9, 0x03	GPIO0_M(31:24)							
0x9, 0x04	GPIO1_M(7:0)							
0x9, 0x05	GPIO1_M(15:8)							
0x9, 0x06	GPIO1_M(23:16)							
0x9, 0x07	GPIO1_M(31:24)							
0x9, 0x08	GPIO1_SEL	GPIO1_DIAG	GPIO1_CFG(1:0)		GPIO0_SEL	GPIO0_DIAG	GPIO0_CFG(1:0)	
0x9, 0x10	CFG_CRC_9(7:0)							
I2C Master								
0xA, 0x00	I2C_DEV_ID_0(7:0)							

Register map								
Bank,Addr	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0xA, 0x01	I2C_DEV_ID_1(7:0)							
0xA, 0x02	I2C_DEV_ID_2(7:0)							
0xA, 0x03	I2C_DEV_ID_3(7:0)							
0xA, 0x04	I2C_T_0(6:0)							I2C_F_0
0xA, 0x05	I2C_T_1(6:0)							I2C_F_1
0xA, 0x06	I2C_T_2(6:0)							I2C_F_2
0xA, 0x07	I2C_T_3(6:0)							I2C_F_3
0xA, 0x10	CFG_CRC_A(7:0)							
Position Offset Singleturn								
0xB, 0x00	ST_OFF(7:0)							
0xB, 0x01	ST_OFF(15:8)							
0xB, 0x02	ST_OFF(23:16)							
0xB, 0x03	ST_OFF(31:24)							
0xB, 0x10	CFG_CRC_B(7:0)							
Position Offset Multiturn								
0xC, 0x00	MT_OFF(7:0)							
0xC, 0x01	MT_OFF(15:8)							
0xC, 0x02	MT_OFF(23:16)							
0xC, 0x03	MT_OFF(31:24)							
0xC, 0x10	CFG_CRC_C(7:0)							
Temperature Monitoring								
0xD, 0x00	TEMP_L_1(7:0)							
0xD, 0x01	-				TEMP_L_1(11:8)			
0xD, 0x02	TEMP_L_2(7:0)							
0xD, 0x03	-				TEMP_L_2(11:8)			
0xD, 0x04	-						TEMP_LT_2	TEMP_LT_1
0xD, 0x10	CFG_CRC_D(7:0)							
Profile (to be modified)								
0xE, 0x01	EDS_BANK_X(7:0)							
0xE, 0x02	BISS_PROFILE_ID_1_X(7:0)							
0xE, 0x03	BISS_PROFILE_ID_0_X(7:0)							
0xE, 0x04	SERIAL_3_X(7:0)							
0xE, 0x05	SERIAL_2_X(7:0)							
0xE, 0x06	SERIAL_1_X(7:0)							
0xE, 0x07	SERIAL_0_X(7:0)							
BiSS Identifier (to be modified)								
0xE, 0x08	DEV_ID_5_X(7:0)							
0xE, 0x09	DEV_ID_4_X(7:0)							
0xE, 0x0A	DEV_ID_3_X(7:0)							
0xE, 0x0B	DEV_ID_2_X(7:0)							
0xE, 0x0C	DEV_ID_1_X(7:0)							
0xE, 0x0D	DEV_ID_0_X(7:0)							
0xE, 0x0E	MFG_ID_1_X(7:0)							
0xE, 0x0F	MFG_ID_0_X(7:0)							
0xE, 0x10	CFG_CRC_E(7:0)							

Register map								
Bank,Addr	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Bank Selection								
0x40	BSEL(7:0)							
Profile								
0x41	EDS_BANK(7:0)							
0x42	BISS_PROFILE_ID_1(7:0)							
0x43	BISS_PROFILE_ID_0(7:0)							
0x44	SERIAL_3(7:0)							
0x45	SERIAL_2(7:0)							
0x46	SERIAL_1(7:0)							
0x47	SERIAL_0(7:0)							
Revision & Identification								
0x48	ID(7:0)							
0x49	ID(15:8)							
0x4A	ID(23:16)							
0x4B	ID(31:24)							
0x4C	SYS(3:0)				REV(3:0)			
GPIO								
0x4D	-				GPIO_IN(1:0)		GPIO_OUT(1:0)	
Temperature Sensor								
0x4E	TEMP(7:0)							
0x4F	TEMP(15:8)							
Presets								
0x50	ST_PRE(7:0)							
0x51	ST_PRE(15:8)							
0x52	ST_PRE(23:16)							
0x53	ST_PRE(31:24)							
0x54	MT_PRE(7:0)							
0x55	MT_PRE(15:8)							
0x56	MT_PRE(23:16)							
0x57	MT_PRE(31:24)							
0x58	ABZ_PRE(7:0)							
0x59	ABZ_PRE(15:8)							
0x5A	UVW_PRE(7:0)							
0x5B	UVW_PRE(15:8)							
Autocalibration Configuration								
0x5C	AC_SEL2(3:0)				AC_SEL1(3:0)			
0x5D	AC_ETO	*reserved [000]* [1]			AC_COUNT(3:0)			
Absolute Data Interface (ADI) – received synchronization bits								
0x5E	-				ADI_SB(3:0)			
I2C Device Data								
0x60	I2C_DATA_0(7:0)							
0x61	I2C_DATA_0(15:8)							
0x62	I2C_DATA_1(7:0)							
0x63	I2C_DATA_1(15:8)							
0x64	I2C_DATA_2(7:0)							

[1] Reserved registers must not be changed (default value in square brackets).

Register map								
Bank,Addr	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0x65	I2C_DATA_2(15:8)							
0x66	I2C_DATA_3(7:0)							
0x67	I2C_DATA_3(15:8)							
Diagnosis								
0x68	DIAG(7:0)							
0x69	DIAG(15:8)							
0x6A	DIAG(23:16)							
0x6B	DIAG(31:24)							
0x6C	ERR(7:0)							
0x6D	ERR(15:8)							
0x6E	ERR(23:16)							
0x6F	ERR(31:24)							
0x70	WARN(7:0)							
0x71	WARN(15:8)							
0x72	WARN(23:16)							
0x73	WARN(31:24)							
Bank CRC Status								
0x74	CRC_STAT(7:0)							
0x75	CRC_STAT(15:8)							
Commands								
0x76	CMD_STAT(7:0)							
0x77	CMD(7:0)							
BiSS Identifier								
0x78	DEV_ID_5(7:0)							
0x79	DEV_ID_4(7:0)							
0x7A	DEV_ID_3(7:0)							
0x7B	DEV_ID_2(7:0)							
0x7C	DEV_ID_1(7:0)							
0x7D	DEV_ID_0(7:0)							
0x7E	MFG_ID_1(7:0)							
0x7F	MFG_ID_0(7:0)							

Table 5: Register map

Please note: Register marked with '-' are not implemented. They cannot be written to and are always read as '0'.

INTERFACE PORTS CONFIGURATION

Slew Rate I/O-Pads

The output slew rates for the digital I/O pads of PORTA, PORTB, PORTC, and the Absolute Data Interface are configured via PADx_CFG(1:0). Refer to ELECTRICAL CHARACTERISTICS 229 and 230 for details. Faster drivers support higher output frequencies but may increase interference.

PADA_CFG(1:0)	Addr. 0x0, 0x00;	bit 1:0	default: 10
PADB_CFG(1:0)	Addr. 0x0, 0x00;	bit 3:2	default: 10
PADC_CFG(1:0)	Addr. 0x0, 0x00;	bit 5:4	default: 10
PADM_CFG(1:0)	Addr. 0x0, 0x00;	bit 7:6	default: 01

Code	Description
00	Slow output driver (e.g. I2C, ADI-slow)
01	Medium output driver (e.g. ADI-fast)
10	Fast output driver (e.g. BiSS, ABZ)
11	Ultra fast output driver

Table 6: I/O Pads Configuration

Port Disabling

If ports are not used, disabling them via PORTx_DIS is recommended to prevent noise caused by potential crosstalk.

PORTA_DIS	Addr. 0x0, 0x01;	bit 4	default: 0
PORTB_DIS	Addr. 0x0, 0x01;	bit 5	default: 0
PORTC_DIS	Addr. 0x0, 0x01;	bit 6	default: 0

Bit	Description
0	Port is enabled
1	Port is disabled

Table 7: Port Disabling

VDDIO Monitoring

The VDDIO supply voltage can be monitored for undervoltage. Therefore, VDDIOSEL has to be set accordingly. In table 8 the nominal supply voltages for VDDIO are given. For details on the monitored undervoltage-levels, refer to section Power-On Reset & Voltage Monitoring in the ELECTRICAL CHARACTERISTICS.

VDDIOSEL(1:0)	Addr. 0x0, 0x01;	bit 1:0	default: 00

Code	Description
00	VDDIO = 2.5 V
01	VDDIO = 3.3 V
10	VDDIO = 5.0 V
11	Illegal

Table 8: VDDIO Selection

LED POWER CONTROL

The embedded blue LED is controlled by an on-chip regulator. One of two control modes can be selected via LED_CTRL. The signal path is shown in Figure 14.

In Square Control Mode, the amplitudes of the analog signals are kept at a constant level. The LED power control uses the signal at the input of the interpolator as process value. Signal amplitude is typically 1000 mV.

In Sum Control Mode, the DC values of the analog signals are kept constant. In that case, the LED power control uses the signals at the outputs of the photocurrent amplifiers as process value. Signal amplitudes vary depending on the contrast of the system.

The control current of the LED can be limited to a maximum level via LED_CUR. This is useful to avoid peak LED currents, especially during startup.

The LED power control can be switched off via LED_CONST. If so, the LED is running with a constant current. In that case the current is set according to the value for LED_CUR. Signal DC levels and amplitudes depend on the contrast of the system and the distance of the chip to the code disc. As the LED current is not controlled in a closed loop, this mode is suitable for signal adjustment and alignment. By setting LED_CUR to 0x1 (0 mA), the LED can be switched off.

LED_CTRL	Addr. 0x3, 0x00; bit 0	default: 0
Code	Description	
0	Square Control Mode	
1	Sum Control Mode	

Table 9: LED Control Mode

LED_CUR(2:0)	Addr. 0x3, 0x00; bit 3:1	default: 0x0
Code	Description	
0x0	40 mA	
0x1	0 mA	
0x2	1 mA	
0x3	2 mA	
0x4	4 mA	
0x5	8 mA	
0x6	16 mA	
0x7	32 mA	

Table 10: LED Current Limit

LED_CONST	Addr. 0x3, 0x00; bit 4	default: 0
Code	Description	
0	Controlled current with limit	
1	Constant LED current	

Table 11: LED Constant Current

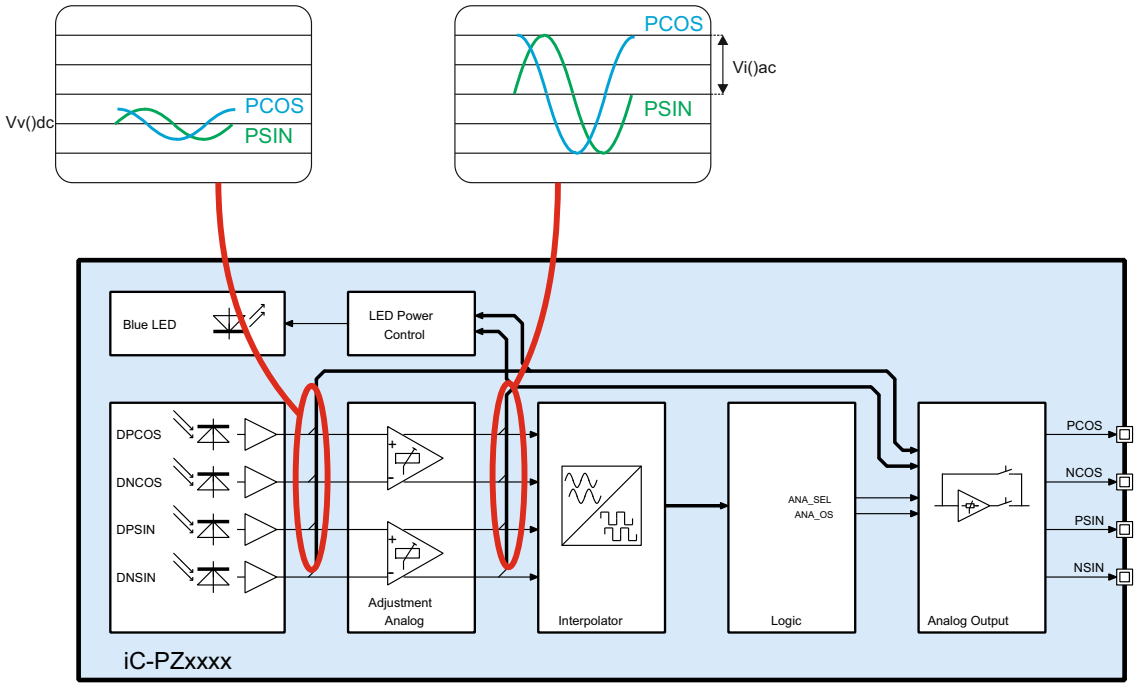


Figure 14: Analog signal paths and LED control in square and sum control mode

INTERPOLATOR

A digital control loop provides a filtered interpolator position. For setting up the filter, two use cases are distinguished:

Use case	Description
Before analog adjustment	First system startup, analog autocalibration not yet executed
After analog adjustment	Analog autocalibration completed

Parameters IPO_FILT1 and IPO_FILT2 should be set according to the use-cases above. The default values IPO_FILT1 = 0x6E and IPO_FILT2 = 0x4 ensure stable filter operation before the first analog autocalibration after startup is executed. After the first analog autocalibration has been completed, the parameters should be changed to IPO_FILT1 = 0xEA and IPO_FILT2 = 0x4.

IPO_FILT1(7:0)	Addr. 0x0, 0x03; bit 7:0	default: 0x6E
Code	Use case	
0x6E	Before analog adjustment	
0xEA	After analog adjustment	

Table 12: Filter Parameter 1

IPO_FILT2(2:0)	Addr. 0x0, 0x04; bit 2:0	default: 0x4
Code	Use case	
0x4	Suitable for any use case	

Table 13: Filter Parameter 2

SINGLETURN POSITION EVALUATION

The absolute position information is provided by the sampled Pseudo Random Code (PRC) track. The sampled incremental track is interpolated to increase the resolution of the singleturn position. An internal counter is implemented that is incremented with each new sample of the incremental track. That counter is initialized during startup with the first sampled absolute position.

During operation, each sampled absolute position is compared to the internally counted position. In case both values do not match, the counted position is replacing the sampled position. This way the system provides a mechanism to mask single misreadings during PRC sampling.

An error is reported in DIAG(11) as soon as the tolerance for mismatches of the sampled and counted position set via RAN_TOL is exceeded. In case of an error, the counter value is either kept (RAN_FLD = 0) or reloaded with the sampled absolute position (RAN_FLD = 1). This feature is meant to provide increased availability of a valid position information in test environments, e. g. using a dirty code disc in the lab.

Setting RAN_TOL = 0x0 and not receiving an error in DIAG(11) during operation indicates that zero misreadings have occurred.

If the internal counter is initialized with a wrong absolute position during startup (e. g. due to dirt on the PRC track of the disc), the error in DIAG(11) will not be set until RAN_TOL is exceeded.

RAN_TOL(3:0)	Addr. 0x0, 0x0F; bit 3:0	default: 0x4
Code	Value	
0x0	No mismatches tolerated	
0x1	Low mismatching tolerance	
...	...	
0x4	Medium mismatching tolerance	
...	...	
0xF	High mismatching tolerance	

Table 14: PRC Mismatching Tolerance

RAN_FLD	Addr. 0x0, 0x0F; bit 7	default: 1
Code	Description	
0	Internal counter will never be reloaded after startup	
1	Internal counter is reloaded in case of error DIAG(11)	

Table 15: PRC Forced Loading

ANALOG OUTPUT

Signal Routing

The signals routed to the analog output port can be selected via ANA_SEL. As shown in Figure 15, three routings along the analog signal path are selectable.

ANA_SEL(1:0) Addr. 0x3, 0x01; bit 1:0 default: 00	
Code	Description
00	Buffered signals, amplitude and driver set by ANA_OS
10	Pre Signal Conditioning signals (photocurrent amplifiers, weak output)
11	Post Signal Conditioning signals (weak output)

Table 16: Analog Signal Selection

By setting ANA_SEL = 00, the analog signals are adjusted and amplified before being routed to the analog output port. This setting is recommended to be used during operation. Driver strength is selected via ANA_OS.

By setting ANA_SEL = 10, the raw signals of the photocurrent amplifiers are routed to the analog output port. Those signals can be used for testing and alignment purposes only and may not see any load, as they do only have weak drivers.

By setting ANA_SEL = 11, the signals being affected by the analog adjustment are routed to the analog output port. Those signals can also be used for testing and alignment purposes only and may not see any load, as they do only have weak drivers.

Output Driver

The driver strength and amplitude of the analog output port is set via ANA_OS. The driver is only applied to the routing ANA_SEL = 00.

ANA_OS Addr. 0x3, 0x01; bit 2 default: 1	
Code	Description
0	1 mA, 1000 mV amplitude (amplification x1), 2.5 V dc
1	6 mA, 250 mV amplitude (amplification x0.25), 2.5 V dc

Table 17: Analog Output Setting

Note: The amplitudes described for ANA_OS are only valid for LED_CTRL = 0 and LED_CONST = 0. For other settings, the amplitudes are not controlled and depend on the system properties like the chosen LED power control (sum or constant LED current) or the contrast of the system.

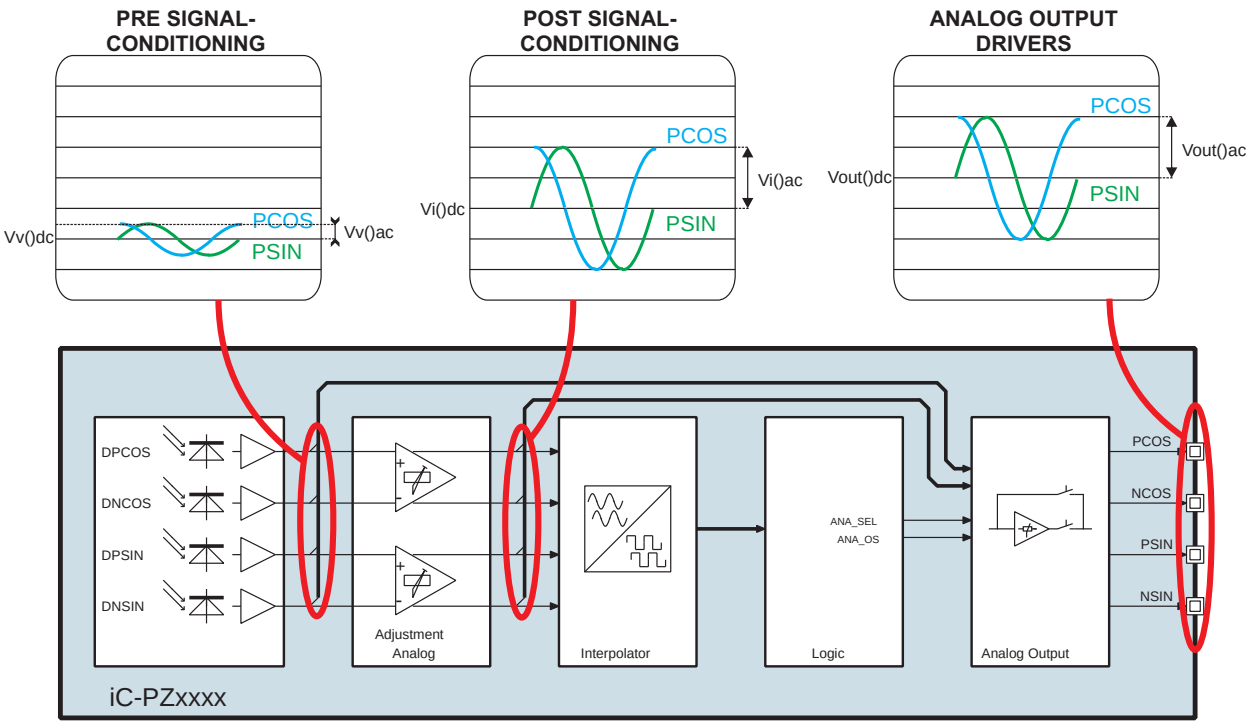


Figure 15: Analog signal path with single-ended signals referenced to GNDA (NCOS and NSIN not shown)

ABZ GENERATOR

AB Periods

Making use of the FlexCount® feature, the resolution of the incremental (quadrature) signals can be arbitrarily adjusted. The AB periods per mechanical revolution (rotary) or per maximum scale length (linear) can be set via ABZ_PER.

ABZ_PER(7:0)	Addr. 0x4, 0x00; bit 7:0	default:
ABZ_PER(15:8)	Addr. 0x4, 0x01; bit 7:0	0x0002000
ABZ_PER(23:16)	Addr. 0x4, 0x02; bit 7:0	
ABZ_PER(26:24)	Addr. 0x4, 0x03; bit 2:0	
Code	AB periods	
0x0000000	2^{27}	
0x0000001	1	
0x0000002	2	
...	...	
0x0002000	8192	
...	...	
0x7FFFFFD	$2^{27} - 3$	
0x7FFFFFE	$2^{27} - 2$	
0x7FFFFFF	$2^{27} - 1$	

Note: The maximum value allowed for the AB periods depends on the resolution of the system: ABZ_PER $\leq 2^{SYS\_eff+12}$.

Example: For the rotary system with ⌀ 26 mm (SYS_eff = 8), the maximum value allowed is = $2^{8+12} = 2^{20}$.

Table 18: AB Periods

For rotary systems, ABZ_PER defines the number of AB periods per mechanical revolution.

For linear systems with a native resolution of r_{nat} (line distance of the incremental track on the scale), one AB period corresponds to the length l_{AB} of:

$$l_{AB} = \frac{2^{SYS\_eff}}{ABZ\_PER} \cdot r_{nat}$$

Example:
For iC-PZ205, r_{nat} = 204.8 µm and SYS_eff = 15
To set one AB period corresponding to the length l_{AB} = 1.6µm, ABZ_PER has to be set to:

$$ABZ\_PER = \frac{r_{nat}}{l_{AB}} \cdot 2^{SYS\_eff} = \frac{204.8\mu m}{1.6\mu m} \cdot 2^{15} = 2^{22}$$

The speed of a linear system is limited to

$$v_{max} = \frac{l_{AB}}{4 \cdot MTD}$$

Example:
In the above example with l_{AB} = 1.6µm and the maximum MTD = 37.5 ns, the maximum possible speed is

$$v_{max} = \frac{1.6\mu m}{4 \cdot 37.5ns} = 10.7 \frac{m}{s}$$

Independent of the above calculation, the speed must not exceed the limit given in Table 145.

AB Direction

The direction of the incremental signals can be switched via ABZ_CFG(0). The signals for all possible use cases are illustrated in Figure 16.

ABZ_CFG(0)	Addr. 0x4, 0x06; bit 4	default: 0
Code	AB direction	
0	A leading B for pos. mech. direction of movement	
1	B leading A for pos. mech. direction of movement	

Table 19: AB Direction

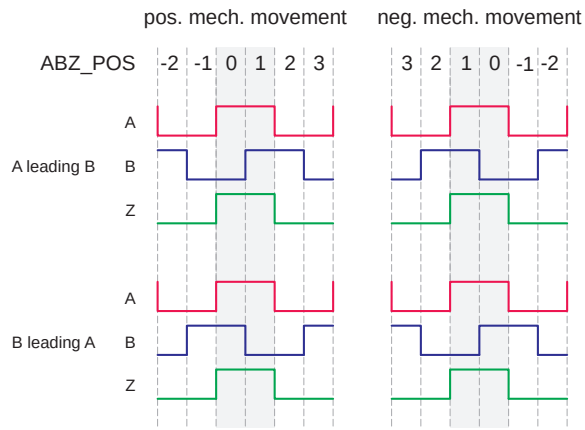


Figure 16: ABZ signals for different mechanical and electrical directions of movement (here: ABZ_ZGATE = 0x4)

Z Gating

Several gating options for the index signal Z can be configured via ABZ_ZGATE.

ABZ_ZGATE(3:0)	Addr. 0x4, 0x06; bit 3:0	default: 0x0
Code	Function	
0x0 0x1 0x2 0x3	Z at AB = 10 Z at AB = 11 Z at AB = 01 Z at AB = 00	90° Z gating options
0x4 0x5 0x6 0x7	Z at A = 1 Z at A = 0 Z at B = 1 Z at B = 0	180° Z gating options
0x8 0x9	Z at A Z at B	360° Z gating options (ungated)
Others	Not allowed	
Note: Z is always located at the internal zero position, AB is adapted with respect to Z.		

Table 20: Z Gating

ABZ signals for mechanical movement in positive direction (see SIGNAL DEFINITIONS on page 18) and ABZ_CFG(0) = 0 (A leading B) are shown in Figure 17.

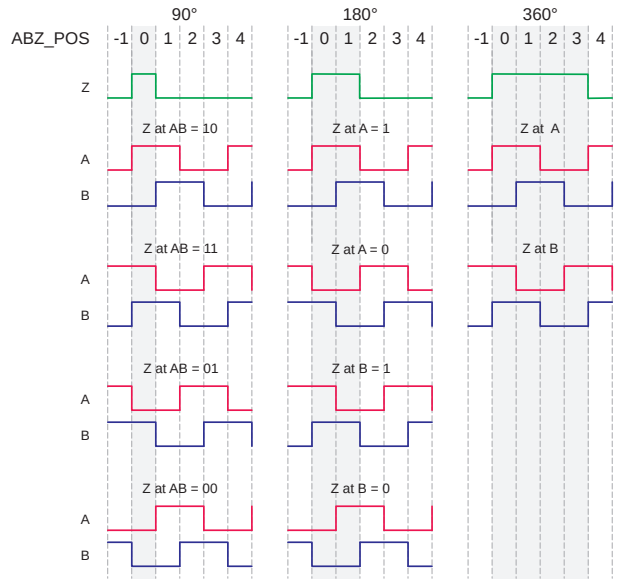


Figure 17: Gating and position of the Z signal

Z Polarity

The polarity of Z can be switched via ABZ_CFG(1).

ABZ_CFG(1)	Addr. 0x4, 0x06; bit 5	default: 0
Code	Z polarity	
0	Standard output (Z active high)	
1	Inverted output (Z active low)	

Table 21: Z Polarity

Hysteresis

As illustrated in Figure 18, the configurable hysteresis ABZ_HYS corresponds to a slip existing between the two rotating directions. In this way multiple switching of the ABZ signals at the reversing point of a changing direction of movement can be prevented.

ABZ_HYS(7:0)	Addr. 0x4, 0x04; bit 7:0	default: 0x20
Code	ABZ hysteresis	Value
unsigned	2 · ABZ_HYS · LSB	$\frac{2 \cdot ABZ\_HYS}{2^{14}} \cdot 360°e$
0x00 0x01 ... 0x20 ... 0xFE 0xFF	0 LSB 2 LSB ... 64 LSB ... 508 LSB 510 LSB	0.000°e 0.044°e ... 1.406°e ... 11.162°e 11.206°e
Note: In FlexCode®-systems, "Value" changes as described in FLEXCODE® on page 69.		

Table 22: ABZ Hysteresis

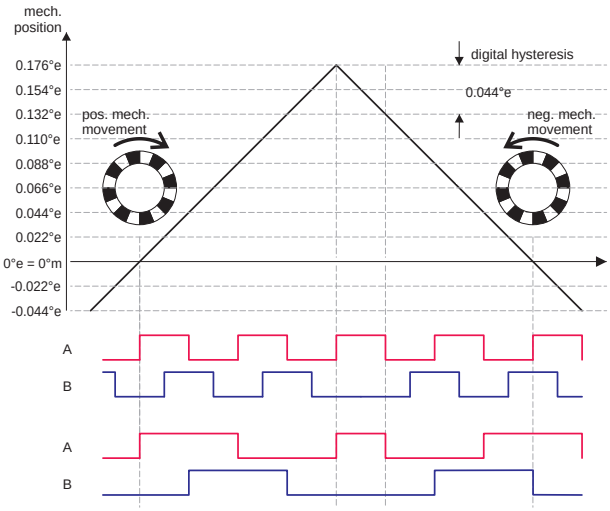


Figure 18: AB signals with 2 LSB hysteresis. Signals for max. AB resolution (top, 2^{12} AB-Periods per sine-period) and for half of the max. resolution (bottom, 2^{11} AB-Periods per sine-period)

Minimum Transition Distance

The Minimum Transition Distance (MTD) sets the minimum time between two successive edges of the A and B signals. Setting ABZ_MTD is useful to avoid errors in the motor controller. Some controllers need a Minimum Transition Distance, and at speeds close to the maximum controllable speed AB-jitter may cause some faster edges.

ABZ_MTD(3:0)	Addr. 0x4, 0x05; bit 3:0	default: 0
Code	ABZ minimum transition distance	
0x0	37.5 ns	
0x1	50.0 ns	
0x2	62.5 ns	
0x3	75.0 ns	
0x4	87.5 ns	
0x5	100.0 ns	
0x6	112.5 ns	
0x7	125.0 ns	
0x8	250.0 ns	
0x9	500.0 ns	
0xA	750.0 ns	
0xB	1.0 µs	
0xC	2.5 µs	
0xD	5.0 µs	
0xE	7.5 µs	
0xF	10.0 µs	
Note: The given times are typical values, i.e., they hold for fosc = 80 MHz.		

Table 23: ABZ Minimum Transition Distance

If the movement of the motor causes faster AB signals than the MTD (fine-dashed signals in Figure 19), the AB-edges will be output **incorrectly** with the fixed MTD between two successive edges. However, if AB-signals are continuously output with MTD, the internal AB-position increasingly differs from the actual absolute position. If the difference is too large, AB-calculation will no longer work correctly, and incorrect AB-signals will be output, e.g. with incorrect direction.

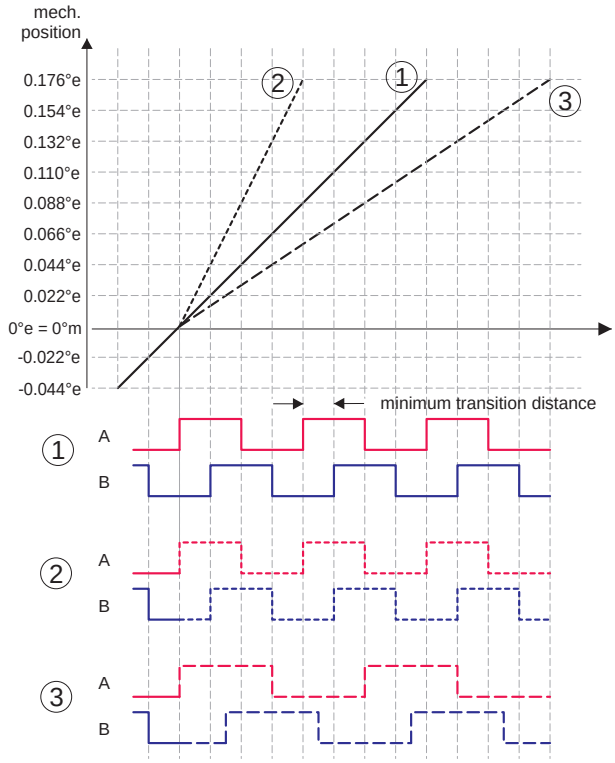


Figure 19: Minimum Transition Distance (MTD)
① equal to MTD
② faster than MTD
③ slower than MTD

ABZ Offset

An individual offset can be applied to the ABZ signals via ABZ_OFF. The offset is added before the ABZ signals are transferred, as shown in Figure 21.

ABZ_OFF(7:0) Addr. 0x4, 0x08; bit 7:0 default: 0x0000 **ABZ_OFF(15:8)** Addr. 0x4, 0x09; bit 7:0		
Code	ABZ offset	Value in °m
Unsigned		$\frac{\text{ABZ\_OFF}}{2^{16}} \cdot 360°\text{m}$
0x0000	0	0.0000
0x0001	1	0.0055
0x0002	2	0.0110
...	...	...
0xFFFD	$2^{16} - 3$	359.9835
0xFFFE	$2^{16} - 2$	359.9890
0xFFFF	$2^{16} - 1$	359.9945

Table 24: ABZ Offset

ABZ Preset

To automatically calculate the offset that is related to a certain position, a preset can be applied. First, the desired preset has to be set via ABZ_PRE. Then, by executing the command ABZ_PRESET, the offset is calculated so that the current position is set according to ABZ_PRE. Refer to COMMANDS on page 53 for details.

For linear systems, ABZ_OFF is calculated similarly, 360°m has to be replaced with the max. length of the scale. For iC-PZ205, e.g., the max. scale length is $204.8\,\mu\text{m} \cdot 2^{15} \approx 6.71\,\text{m}$.

ABZ_PRE(7:0) Addr. 0x58; bit 7:0 default: 0x0000 **ABZ_PRE(15:8)** Addr. 0x59; bit 7:0	
Value	Preset value for ABZ interface

Table 25: ABZ Preset

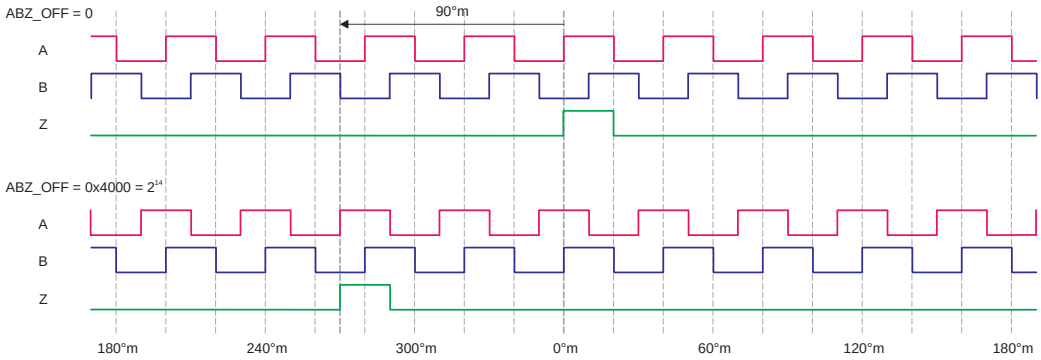


Figure 20: ABZ offset for a system with 9 periods

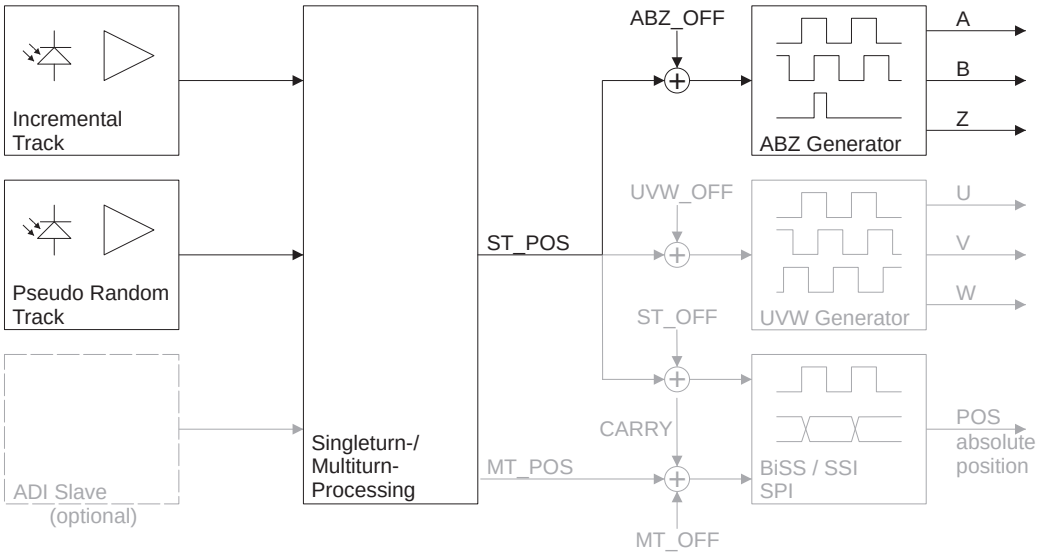


Figure 21: Programming of position offsets

Startup
The startup behavior of the ABZ generator is configured via ABZ_CFG(2).

ABZ_CFG(2)	Addr. 0x4, 0x06; bit 6	default: 0
Code	ABZ Startup Behavior	
0	AB = 11, Z = 0 during startup, until position found	
1	ABZ counting from 0 position to actual position with programmed MTD	

Table 26: ABZ Startup Behavior

Startup behavior of the ABZ generator for both settings of ABZ_CFG(2) is illustrated in Figure 22 and Figure 23. For better orientation, different phases of the system startup are distinguished:

RESET iC-PZ is in the reset state, either due to power-down, external pin NRES or command REBOOT.

READ CFG Configuration is read from an external EEPROM.

STUP POS Startup phase of the position processing (MT + ST).

WAIT Waiting time >50 µs, before the ABZ generator is enabled.

STUP ABZ Startup phase of the ABZ generator.

NORMAL OP Normal operation (output of valid ABZ signals, as configured).

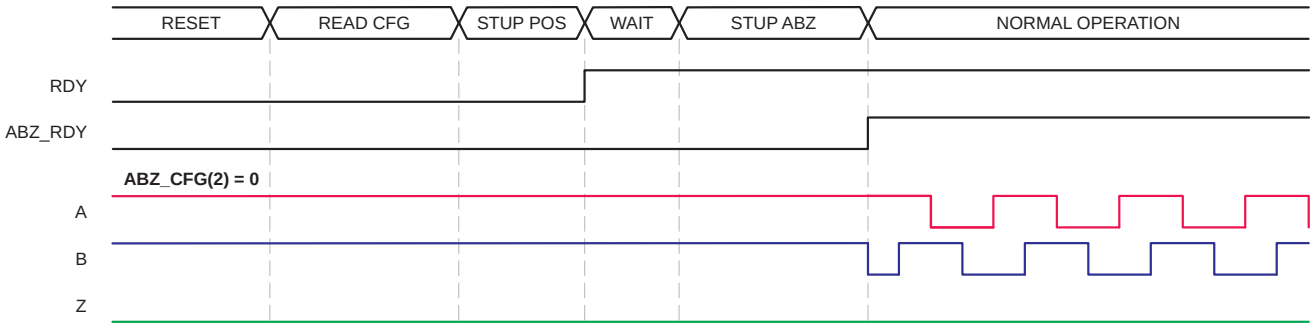


Figure 22: ABZ startup with ABZ_CFG(2) = 0

For ABZ_CFG(2) = 0 the fastest MTD of 37.5 ns is used internally to minimize the duration of the startup phase. Once the position is found, ABZ is then immediately output with the programmed MTD. At this point the invalid AB-transition 11 → 00 is possible. As illustrated in Figure 22, users can evaluate status bit DIAG(6) = not(ABZ_RDY) (e. g. via GPIO). Once this bit becomes 1, the ABZ startup is finished and valid signals are output henceforth.

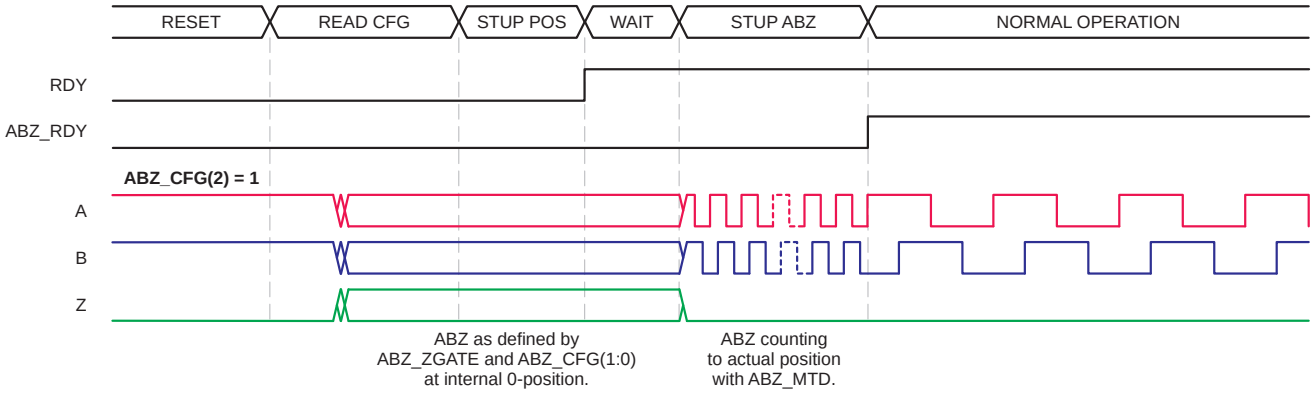


Figure 23: ABZ startup with ABZ_CFG(2) = 1

For ABZ_CFG(2) = 1 it is possible that ABZ changes during EEPROM readout, as the levels of ABZ at the 0 position depend on the configuration. As illustrated in Figure 23, users can evaluate status bit DIAG(24) = not(RDY) (e. g. via GPIO). Once this bit becomes 1, a valid position (ST + MT) is available via the serial interfaces and ABZ is enabled (begins to count to the position) at least 50 µs later.

UVW GENERATOR

Pole Pairs, Direction and Polarity

The UVW generator of iC-PZ provides motor commutation signals for up to 32 pole pairs.

UVW_PP(4:0)	Addr. 0x5, 0x00; bit 4:0	default: 0x04
Code	UVW Pole Pairs	
0x00	32	
0x01	1	
...	...	
0x04	4	
...	...	
0x1F	31	

Table 27: UVW Pole Pairs per Mechanical Revolution

For rotary systems, UVW_PP defines the number of UVW pole pairs per mechanical revolution.

For linear systems with a native resolution of r_{nat} (line distance of the incremental track on the scale), one UVW period corresponds to the length l_{UVW} of:

$$l_{UVW} = \frac{2^{SYS\_eff}}{UVW\_PP} \cdot r_{nat}$$

Example:
For iC-PZ205, r_{nat} = 204.8 µm and SYS_eff = 15.
For UVW_PP = 0x8, the length of one UVW period is:

$$l_{UVW} = \frac{2^{15}}{8} \cdot 204.8\mu m \approx 0.84\,m$$

Via UVW_CFG(0) the direction and via UVW_CFG(1) the polarity of the UVW signals can be adjusted, as shown in Figure 24.

UVW_CFG(0)	Addr. 0x5, 0x01; bit 0	default: 0
Code	UVW direction	
0	Standard direction	
1	Reversed direction	

Table 28: UVW Direction

UVW_CFG(1)	Addr. 0x5, 0x01; bit 1	default: 0
Code	UVW polarity	
0	Standard polarity	
1	Inverted polarity (180° phase shift)	

Table 29: UVW Polarity

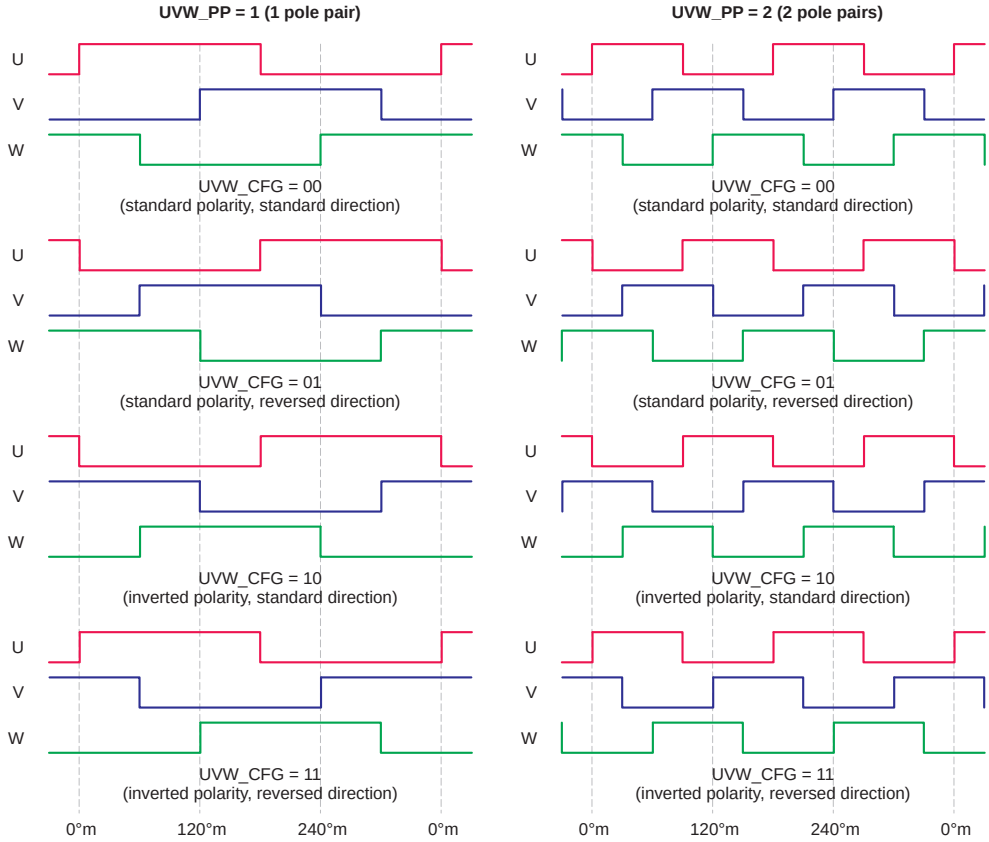


Figure 24: UVW pole pairs, direction and polarity for pos. mech. movement

UVW Offset

The offset UVW_OFF is added to the internal position before being used by the UVW generator (Figure 26). Figure 25 illustrates the effect of UVW_OFF.

UVW_OFF(7:0) Addr. 0x5, 0x02; bit 7:0 default: 0x0000 **UVW_OFF(15:8)** Addr. 0x5, 0x03; bit 7:0		
Code	UVW position offset	
Unsigned		$\frac{\text{UVW\_OFF}}{2^{16}} \cdot 360°\text{m}$
0x0000	0	0.0000
0x0001	1	0.0055
0x0002	2	0.0110
...	...	...
0xFFFD	$2^{16} - 3$	359.9835
0xFFFE	$2^{16} - 2$	359.9890
0xFFFF	$2^{16} - 1$	359.9945

Table 30: UVW Offset

For linear systems, UVW_OFF is calculated similarly, 360°m has to be replaced with the max. length of the scale. For iC-PZ205, e.g., the max. scale length is $204.8\mu\text{m} \cdot 2^{15} \approx 6.71\,\text{m}$

UVW Preset

To automatically calculate the offset that is related to a certain position, a preset can be applied. First, the desired preset has to be set via UVW_PRE. Then, by executing the command UVW_PRESET, the offset is calculated so that the current position is set according to UVW_PRE. Refer to COMMANDS on page 53 for details.

UVW_PRE(7:0) Addr. 0x5A; bit 7:0 default: 0x0000 **UVW_PRE(15:8)** Addr. 0x5B; bit 7:0	
Value	Preset value for UVW interface

Table 31: UVW Preset

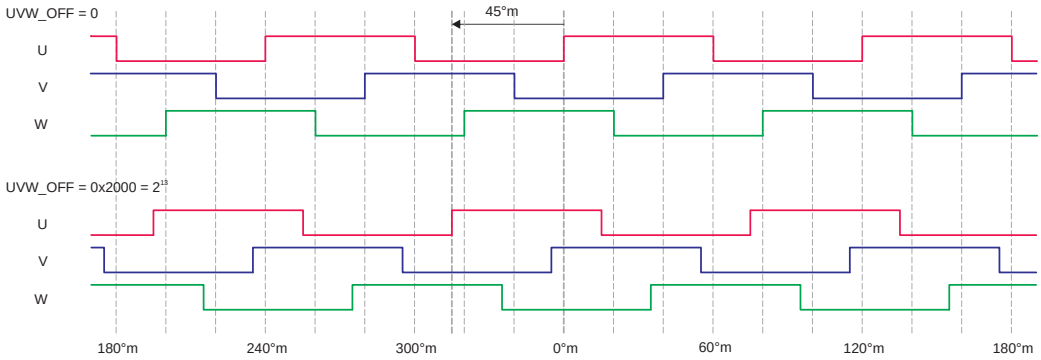


Figure 25: UVW offset for a system with 3 pole pairs

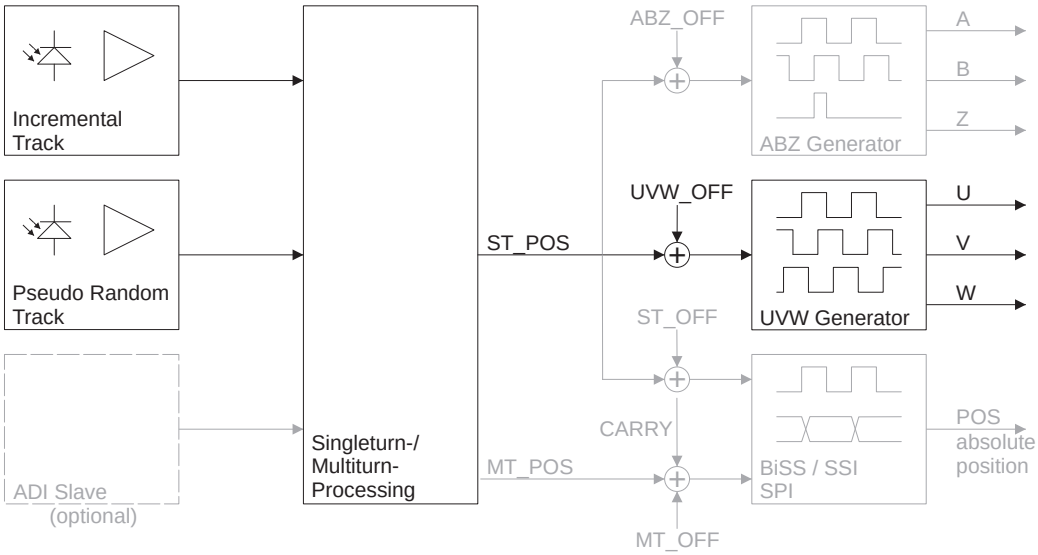


Figure 26: Programming of position offsets

Startup
During startup, the UVW generator outputs constant signal levels, i.e., UVW = 000, until valid signals can be output.

Figure 27 shows the UVW startup behavior in the context of the overall system startup, where different phases can be distinguished:

RESET iC-PZ is in the reset state, either due to power-down, external pin NRES or command REBOOT.

READ CFG The configuration is read from an external EEPROM.

STUP POS Startup phase of the position processing (MT + ST).

WAIT Waiting time >50 µs, before the UVW generator is enabled.

STUP UVW Startup phase of the UVW generator.

NORMAL OP Normal operation (output of valid UVW signals, as configured).

As illustrated in Figure 27, users can evaluate status bit DIAG(7) = not(UVW_RDY) (via GPIO). Once this bit becomes 1, the UVW startup is finished and valid signals are output henceforth.

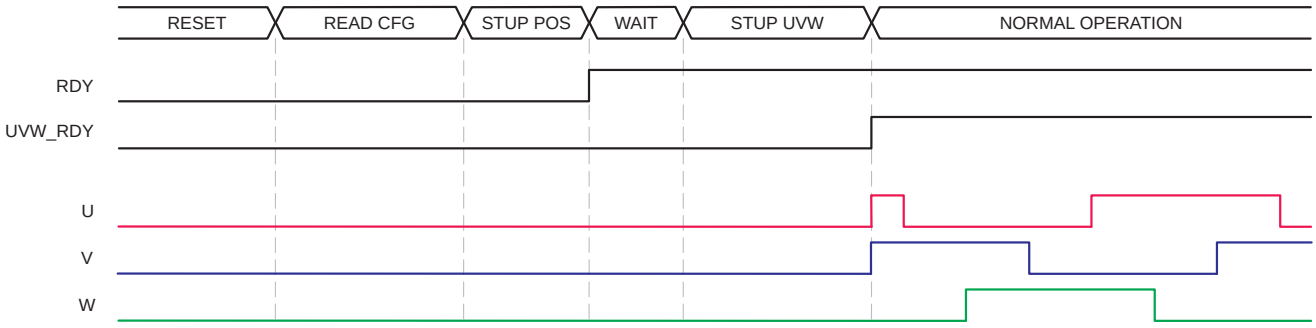


Figure 27: UVW startup

POSITION SETTINGS

Position Data Length

The number of bits used for the singleturn (ST) and multiturn (MT) position data can be set via ST_PDL and MT_PDL. Those settings affect the position data sent by any serial interface (BiSS, SSI and SPI). However, the position data format can be adjusted individually for any of those interfaces. Refer to BiSS SLAVE, SSI SLAVE and SPI SLAVE for details.

ST_PDL(5:0)	Addr. 0x0, 0x08; bit 5:0	default: 0x20
Code	Value	
0..32	Maximum number of singleturn position data bits. Unused bits are set to zero from right to left.	

Table 32: Singleturn Position Data Length

MT_PDL(5:0)	Addr. 0x0, 0x09; bit 5:0	default: 0x20
Code	Value	
0..32	Maximum number of multiturn position data bits. Unused bits are set to zero from left to right.	

Table 33: Multiturn Position Data Length

Note: Further hints on properly setting MT_PDL when using external MT slaves are given on page 55.

Position Offset

An individual offset can be applied to the ST and MT position via ST_OFF and MT_OFF. The offset is added before the position data is transferred by one of the serial interfaces as shown in Figure 28.

ST_OFF(7:0)	Addr. 0xB, 0x00; bit 7:0	default:
ST_OFF(15:8)	Addr. 0xB, 0x01; bit 7:0	0x00000000
ST_OFF(23:16)	Addr. 0xB, 0x02; bit 7:0	
ST_OFF(31:24)	Addr. 0xB, 0x03; bit 7:0	
Code	Singleturn position offset	
0x00000000	0	
0x00000001	1	
0x00000002	2	
...	...	
0xFFFFFFFD	$2^{32} - 3$	
0xFFFFFFFE	$2^{32} - 2$	
0xFFFFFFFF	$2^{32} - 1$	

Table 34: Singleturn Position Offset

MT_OFF(7:0)	Addr. 0xC,0x00; bit 7:0	default:
MT_OFF(15:8)	Addr. 0xC,0x01; bit 7:0	0x00000000
MT_OFF(23:16)	Addr. 0xC,0x02; bit 7:0	
MT_OFF(31:24)	Addr. 0xC,0x03; bit 7:0	
Code	Singleturn position offset	
0x00000000	0	
0x00000001	1	
0x00000002	2	
...	...	
0xFFFFFFFD	$2^{32} - 3$	
0xFFFFFFFE	$2^{32} - 2$	
0xFFFFFFFF	$2^{32} - 1$	

Table 35: Multiturn Position Offset

Position Preset

To automatically calculate the offset that is related to a certain position, a preset position can be applied. First, the desired preset position has to be set via ST_PRE and MT_PRE. Then, by executing either the command MT_PRESET or MTST_PRESET, the position offsets are calculated so that the current position is set according to ST_PRE and MT_PRE. Refer to COMMANDS on page 53 for details.

ST_PRE(7:0)	Addr. 0x50; bit 7:0	default:
ST_PRE(15:8)	Addr. 0x51; bit 7:0	0x00000000
ST_PRE(23:16)	Addr. 0x52; bit 7:0	
ST_PRE(31:24)	Addr. 0x53; bit 7:0	
Code	Singleturn position preset	

Table 36: Singleturn Position Preset

MT_PRE(7:0)	Addr. 0x54; bit 7:0	default:
MT_PRE(15:8)	Addr. 0x55; bit 7:0	0x00000000
MT_PRE(23:16)	Addr. 0x56; bit 7:0	
MT_PRE(31:24)	Addr. 0x57; bit 7:0	
Code	Multiturn position preset	

Table 37: Multiturn Position Preset

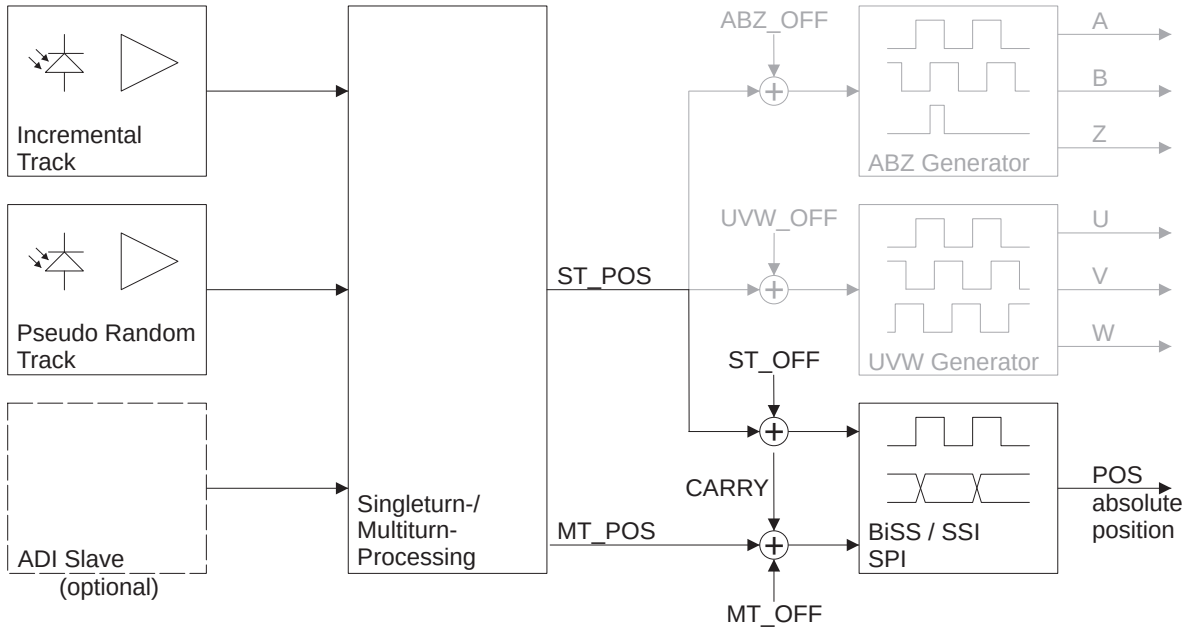


Figure 28: Programming of position offsets

BiSS SLAVE

The implemented BiSS slave interface can be selected via port configuration pins as described in INTERFACE PORTS on page 20. As BiSS and SSI share its physical ports, the interface of choice has to be enabled additionally via SSI_EN. A BiSS transmission is illustrated in Figure 29. Data is sampled on the first rising edge of MA and transferred with MSB first.

SSI_EN	Addr. 0x6, 0x0A; bit 6	default: 0
Code	Value	
0	BiSS enabled	
1	SSI enabled	

Table 38: SSI Enable

Note: For in-depth information about BiSS visit www.biss-interface.com.

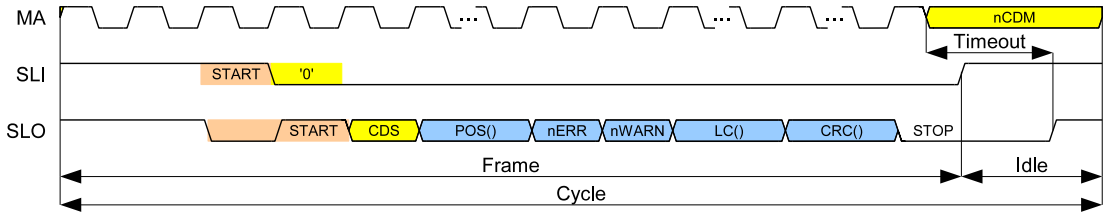


Figure 29: BiSS transmission sequence

BiSS Slave Performance		
Parameter	Symbol	Description
Clock Rate	$1 / t_C$	Refer to Item No. Z01 on page 12
Process.T.	t_{busy}	Refer to Item No. I105 on page 14
Timeout	t_{out}	Refer to Item No. Z06, Z07 on page 12
SCD Channel 1: Position Data		
Bits/cycle	ID	Description
0..32	MT	Multiturn position - MT_OFF (right-aligned)
0..32	ST	Singleturn position - ST_OFF (left-aligned)
1	nE [1]	Error bit ERR
1	nW [1]	Warning bit WARN
(6)	LC	Sign-of-Life Counter
6 (16)	CRC [2]	Polynomial 0x43 (0x190D9), adjustable start value.
CD Channel: Control Data		
Bits/cycle	ID	Description
1	nCDM [1], CDS	Support of bidirectional register access
	Slave IDs	1
	Commands	Support of selected BiSS Commands according to Table 49.
Notes	[1] Low active. [2] Bit inverted transmission.	

Table 39: BiSS slave performance

Single Cycle Data

The Single Cycle Data (SCD) is transmitted in the format highlighted blue in Figure 29. According to Table 39, the format includes the multiturn position followed by the singleturn position, one low-active error bit, one low-active warning bit, an optional 6-bit sign-of-life counter (LC) and a 6-bit or 16-bit CRC value. The position data is affected by the offsets MT_OFF and ST_OFF.

The data length of the ST and MT values can be individually set in bits via BISS_ST_DL and BISS_MT_DL. Bit count not filling up full bytes is supported. If the values set for BISS_ST_DL and BISS_MT_DL exceed the resolution provided by the system, the surplus bits are padded with zeros.

BISS_ST_DL(5:0)	Addr. 0x6, 0x08; bit 5:0	default: 0x18
Code	Value	
0..32	Number of singleturn bits that are transmitted. Padded right with zeros if more than available. 0 is only allowed for BISS_MT_DL≠0.	

Table 40: BiSS Singleturn Data Length

BISS_MT_DL(5:0)	Addr. 0x6, 0x09; bit 5:0	default: 0x18
Code	Value	
0..32	Number of multiturn bits that are transmitted. Padded left with zeros if more than available. 0 is only allowed for BISS_ST_DL≠0..	

Table 41: BiSS Multiturn Data length

The total data length (ST, MT, nERR, nWARN, LC) is limited to 57 bits for the 6-bit CRC polynomial and 64 bits for the 16-bit CRC polynomial excluding the bits needed for the CRC value. Refer to BISS_CRC16 for details.

Note: Common used profiles, like the BiSS Encoder Profile BP1 and BP3, do have certain restrictions regarding data length to be taken into account.

The sources triggering the active-low error bit nERR and the active-low warning bit nWARN can be selected individually. The diagnosis information logged in DIAG are only transferred via BiSS, if the according bit in the masks BISS_WM and BISS_EM is set to 1. Otherwise an error or warning will not be forwarded for corresponding events masked with 0. Refer to DIAGNOSIS on page 64 for further information.

BISS_EM(7:0) Addr. 0x6, 0x00; bit 7:0 default:	
BISS_EM(15:8) Addr. 0x6, 0x01; bit 7:0 0x11000F13	
BISS_EM(23:16) Addr. 0x6, 0x02; bit 7:0	
BISS_EM(31:24) Addr. 0x6, 0x03; bit 7:0	
Bit	Description
31:0	Activate error for corresponding DIAG bit

Table 42: BiSS Error Bit Mask

BISS_WM(7:0) Addr. 0x6, 0x04; bit 7:0 default:	
BISS_WM(15:8) Addr. 0x6, 0x05; bit 7:0 0x0200C00C	
BISS_WM(23:16) Addr. 0x6, 0x06; bit 7:0	
BISS_WM(31:24) Addr. 0x6, 0x07; bit 7:0	
Bit	Description
31:0	Activate warning for corresponding DIAG bit

Table 43: BiSS Warning Bit Mask

Sign-of-Life Counter

The transmission of a 6-bit sign-of-life counter (LC) can be enabled via BISS_ENSOL. The LC is initialized with 0, but counts from 1 to 63 skipping the 0 when wrapping. The counter is incremented with each BiSS frame.

BISS_ENSOL Addr. 0x6, 0x0A; bit 0 default: 0	
Code	Value
0	No sign-of-life counter is transmitted
1	A 6-bit sign-of-life counter is transmitted

Table 44: BiSS Enable Sign-of-life Counter

Cyclic Redundancy Check

The Cyclic Redundancy Check (CRC) value is transmitted in its inverted state at the end of each BiSS frame. The CRC start value is defined by BISS_CRCS. Via BISS_CRC16 the usage of either a 6-bit or a 16-bit CRC polynomial is selected.

BISS_CRCS(5:0) Addr. 0x6, 0x0B; bit 5:0 default: 0x00	
Code	Value
0x00..0x3F	Start value for BiSS CRC calculation (both 6 and 16 bit), used by all slaves on the BiSS channel

Table 45: BiSS CRC Start Value

BISS_CRC16 Addr. 0x6, 0x0A; bit 1 default: 0		
Code	CRC HEX Code	Description
0	0x43	6-bit CRC polynomial: $X^6 + X^1 + X^0$ Hamming Distance: 3 max data length: 57 bits
1	0x190D9	16-bit CRC polynomial: $X^{16} + X^{15} + X^{12} + X^7 + X^6 + X^4 + X^3 + X^0$ Hamming Distance: 6 max data length: 64 bits

Table 46: BiSS CRC Polynomial Selection

Fixed & Adaptive Timeout

Either a fixed or an adaptive timeout for BiSS communication can be selected via BISS_NTOA. The adaptive BiSS timeout is recommended for fastest communication speed.

BISS_NTOA Addr. 0x6, 0x0A; bit 2 default: 0	
Code	Value
0	Adaptive BiSS timeout used
1	Fixed BiSS timeout used

Table 47: BiSS Not Timeout Adaptive

The adaptive BiSS timeout is set according to the period of the BiSS MA clock T_{MA} and the internal sampling frequency $1/T_{SAMPLE}$ (see Elec. Char. item no. Z06). First, one and a half periods of the MA clock from first falling to second rising edge within each BiSS frame are measured during operation. Then, the timeout is calculated according to the equation below:

$$T_{SAMPLE} = \frac{16}{3 * fosc}$$

Where fosc is the system clock frequency (see Elec. Char. item no. O01 and Z06).

Timeout	**Min.**	**Max.**
t_{tout}	$1.5 * T_{BISS}$	$1.5 * T_{BISS} + 3.0 * T_{SAMPLE}$

Table 48: Adaptive Timeout Calculations

Note: More information on the adaptive timeout can be found in BiSS application note AN23 at www.biss-interface.com.

BiSS protocol commands

The following BiSS interface protocol commands are implemented.

CD Channel: BiSS Protocol Commands		
CMD	Availability	Function
Addressed		
00	Yes	Activate Single-Cycle Data channels
01	—*	Deactivate control communication
10	—	Reserved
11	—	Reserved
Broadcast (all slaves)		
00	Yes	Deactivate Single-Cycle Data channels
01	—*	Activate control communication
10	—	Reserved
11	—	Reserved
Notes	* Command w/o function, but will be acknowledged.	

Table 49: BiSS Protocol Commands

Short BiSS-frames with less than 6 MA pulses cause just the one directly following BiSS-frame to contain not refreshed but outdated data. Such reduced BiSS-frames (e. g. BiSS-Init) should be avoided. Alternatively, an intermediate frame with at least 6 MA pulses can be inserted without using its position data.

SSI SLAVE

The implemented SSI slave interface can be selected via port configuration pins as described in INTERFACE PORTS on page 20. As BiSS and SSI share its physical ports, the interface of choice has to be additionally enabled via SSI_EN. Refer to chapter BiSS SLAVE on page 43.

Two data formats are supported, of which one has to be selected via SSI_EXT. Regardless of the format, position data is latched on the first falling edge of MA and transferred with MSB first. The position data coding can be switched between Natural Binary Code and Gray Code via SSI_GRAY. A fixed or adaptive timeout can be set via BISS_NTOA. However, the use of an adaptive timeout is not recommended for SSI.

SSI_EXT	Addr. 0x6, 0x0A; bit 5	default: 0
Code	Value	
0	Standard SSI	
1	Extended SSI	

Table 50: Enable Extended SSI

SSI_GRAY	Addr. 0x6, 0x0A; bit 4	default: 0
Code	Value	
0	Natural binary	
1	Gray code	

Table 51: Activate SSI Gray Coding

According to Table 52, the standard SSI protocol format includes the multiturn (MT) and singleturn (ST) position. The ST data length has to be set to exactly 13 bit via BISS_ST_DL. The MT data length has to be set to either 0 or 12 bit via BISS_MT_DL. A transmission using the standard SSI protocol is shown in Figure 30.

Standard SSI Protocol Frame	
Bit Length	Description
0 or 12	Multiturn position - MT_OFF
13	Singleturn position - ST_OFF

Table 52: Standard SSI Protocol Frame

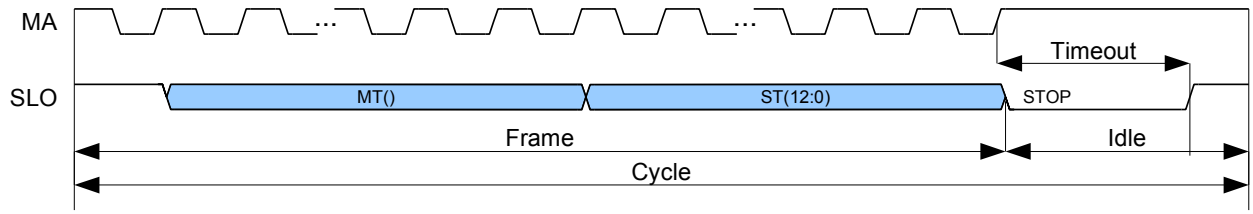


Figure 30: Standard SSI protocol

According to Table 53, the extended SSI protocol format includes the multiturn position followed by the singleturn position, one low-active error bit, one low-active warning bit, an optional 6-bit sign-of-life counter (LC) and a 6-bit or 16-bit CRC value. The format can be adjusted according to section Single Cycle Data in BiSS SLAVE on page 43.

Extended SSI Protocol Frame	
Bit Length	Description
0 - 32	Multiturn position - MT_OFF
0 - 32	Singleturn position - ST_OFF
1	Error bit nERR (active low)
1	Warning bit nWARN (active low)
0 or 6	Optional sign-of-life counter (LC)
6 or 16	CRC (inverted)

Table 53: Extended SSI Protocol Frame

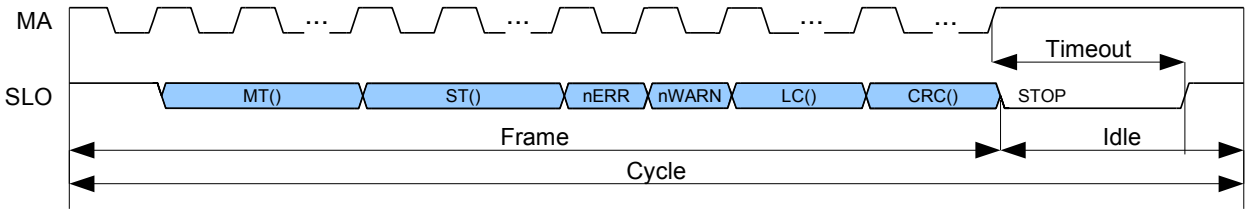


Figure 31: Extended SSI protocol

Short SSI-frames with less than 6 MA pulses cause just the one directly following SSI-frame to contain not refreshed but outdated data. Such short SSI-frames should be avoided.

SPI SLAVE

The implemented SPI slave can be selected via port configuration pins as described in INTERFACE PORTS on page 20. SPI modes 0 and 3 are supported. Idle state of SCLK can be either low or high. Data is sampled on the rising edge of SCLK. Communication is initiated with a falling edge on NCS. While NCS is low, iC-PZ is set active. Each SPI transaction starts with one of the opcodes listed in Table 54. Data is sent byte by byte with MSB first. An SPI transmission including SCLK lines for modes 0 and 3 is illustrated in Figure 32.

OPCODE	
Code	Description
0x81	Read Registers
0xCF	Write Registers
0xA6	Read Position
0xD9	Write Command
0x9C	Read Diagnosis
0x97	Request Data From I2C Slave
0xD2	Transmit Data To I2C Slave
0xAD	Get Transaction Info
0xB0	Activate Slave In Chain

Table 54: SPI Operation Codes

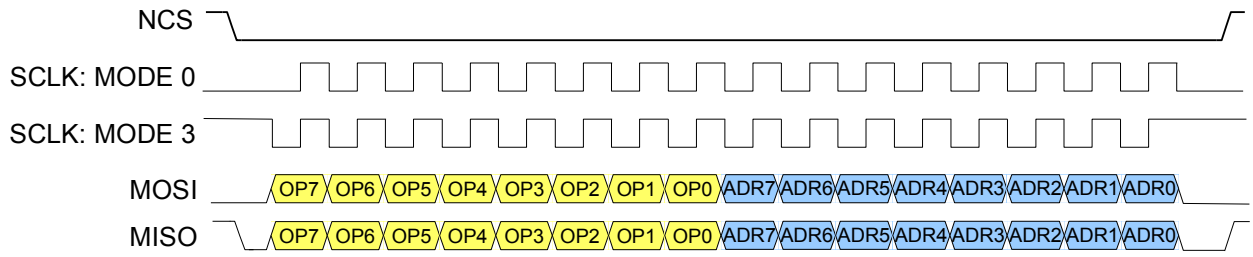


Figure 32: SPI transmission mode 0 and 3

Note: The output line MISO should have an external pull-up or pull-down resistor. Otherwise, this line will float when tristate (NCS high) and may produce crosscurrent in the following input stage.

Read Registers

Opcode Read Registers (0x81) is used to read data from any number of consecutive registers in the on-chip RAM. As shown in Figure 33, the data stream to be sent on MOSI consists of the opcode 0x81, followed by the address of the first register to be read and a delay byte 0x00. Those first three bytes are also transmitted by iC-PZ on MISO, before sending the requested data (DATA1) from the register at address (ADR). As long as clock is sent and the slave stays active, data (DATA2) from the next register at the incremented address (ADR + 1) is transmitted. This procedure may be continued for any number of consecutive registers.

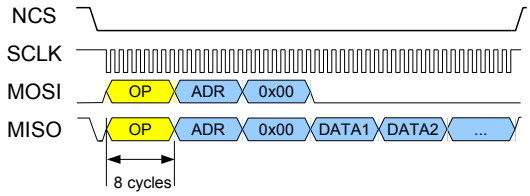


Figure 33: Read Registers

Write Registers

Opcode Write Registers (0xCF) is used to write data to any number of consecutive registers in the on-chip RAM. As shown in Figure 34, the data stream to be sent on MOSI consists of the opcode 0xCF, followed by the address of the first register to be written and the data. With each data byte the address of the register to be written is incremented by one (ADR + 1). If successfully received, the same data stream is transmitted on MISO by iC-PZ.

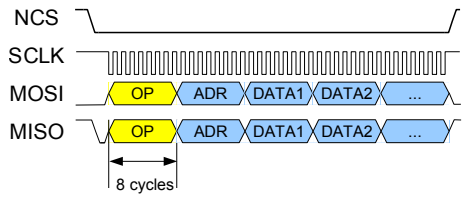


Figure 34: Write Registers

Read Position

Opcode Read Position (0xA6) is used to read the absolute position data from iC-PZ. As shown in Figure 35, the position data is latched on the first rising edge of SCLK (REQ).

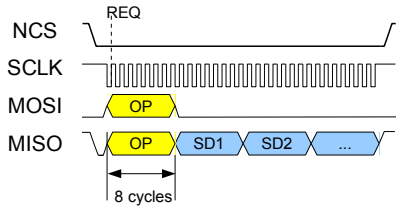


Figure 35: Read Position

As shown in Table 55, the position data format consists of the multiturn position followed by the singleturn position, an error bit, a warning bit, an optional sign-of-life counter (LC) and a CRC value. Singleturn and multiturn position data length can be adjusted individually. The position data includes the offset adjusted via MT_OFF and ST_OFF.

Position Data Format	
Byte Length	Description
for SPI_EXT = 0	
0 - 4	Multiturn Position - MT_OFF
0 - 4	Singleturn Position - ST_OFF
1	nERR, nWARN, 6-bit CRC
for SPI_EXT = 1	
0 - 4	Multiturn Position - MT_OFF
0 - 4	Singleturn Position - ST_OFF
1	nERR, nWARN, 6-bit LC
2	16-bit CRC

Table 55: SPI Position Data Format

The position information is transmitted in one of two data formats selected via SPI_EXT as shown in Table 56. The first format (SPI_EXT = 0) includes one low-active error bit, one low-active warning bit and a 6-bit CRC. The second format (SPI_EXT = 1) includes one low-active error bit, one low-active warning bit, a 6-bit sign-of-life counter (LC) and a 16-bit CRC. The LC is initialized with 0, but counts from 1 to 63 skipping the 0 when wrapping. The total data length (ST, MT, nERR, nWARN, LC) is limited to 57 bits (SPI_EXT = 0) or 64 bits (SPI_EXT = 1) without the bits needed for the CRC value.

SPI_EXT Addr. 0x7, 0x0A; bit 0 default: 0		
Code	CRC HEX Code	Description
0	0x43	6-bit CRC polynomial: $X^6 + X^1 + X^0$ Hamming Distance: 3 max data length: 57 bits No sign-of-life counter is transmitted
1	0x190D9	16-bit CRC polynomial: $X^{16} + X^{15} + X^{12} + X^7 + X^6 + X^4 + X^3 + X^0$ Hamming Distance: 6 max data length: 64 bits A 6-bit sign-of-life counter is transmitted. The counter starts at 0 counting from 1 to 63 and omitting 0 when wrapping.

Table 56: SPI Extended Position Data Format

The CRC value is transmitted in its inverted state at the end of each SPI frame. The CRC start value is defined by SPI_CRCS.

SPI_CRCS(5:0) Addr. 0x7, 0x0B; bit 5:0 default: 0x00	
Code	Value
0x00..0x3F	Start-value for SPI CRC calculation (both 6 and 16 bit)

Table 57: SPI CRC Start Value

The data length of the ST and MT value can be individually set in bits via SPI_ST_DL and SPI_MT_DL. Bit count not filling up full bytes is supported. Breaking up the position data at any bit during transmission is possible, if further parts of the data stream (nERR/nWARN, LC or CRC) are not needed. If the values set for SPI_ST_DL and SPI_MT_DL do not match the resolution provided by the system, the surplus bits are padded with zeros. In conjunction with some systems (e. g. microcontrollers) using full bytes for the position data is advisable, as it may help making data handling easier.

SPI_ST_DL(5:0) Addr. 0x7, 0x08; bit 5:0 default: 0x18	
Code	Value
0..32	Number of singleturn bits that are transmitted. padded right with zeros if more than available. 0 is only allowed when SPI_MT_DL ≠ 0.

Table 58: SPI Singleturn Data Length

SPI_MT_DL(5:0)	Addr. 0x7, 0x09; bit 5:0	default: 0x18
Code	Value	
0..32	Number of multiturn bits that are transmitted. padded left with zeros if more than available. 0 is only allowed when SPI_ST_DL ≠0.	

Table 59: SPI Multiturn Data Length

The sources triggering the active-low error bit nERR and the active-low warning bit nWARN can be selected individually. The diagnosis information logged in DIAG is only transferred via SPI, if the according bit in the masks SPI_WM and SPI_EM is set to 1. Otherwise an error or warning will not be forwarded for corresponding events masked with 0. Refer to DIAGNOSIS on page 64 for further information.

SPI_EM(7:0) SPI_EM(15:8) SPI_EM(23:16) SPI_EM(31:24)	Addr. 0x7, 0x00; bit 7:0 Addr. 0x7, 0x01; bit 7:0 Addr. 0x7, 0x02; bit 7:0 Addr. 0x7, 0x03; bit 7:0	default: 0x11000F13
Bit	Description	
31:0	Activate error for corresponding DIAG-bit	

Table 60: SPI Error Bit Mask

SPI_WM(7:0) SPI_WM(15:8) SPI_WM(23:16) SPI_WM(31:24)	Addr. 0x7, 0x04; bit 7:0 Addr. 0x7, 0x05; bit 7:0 Addr. 0x7, 0x06; bit 7:0 Addr. 0x7, 0x07; bit 7:0	default: 0x0200C00C
Bit	Description	
31:0	Activate warning for corresponding DIAG-bit	

Table 61: SPI Warning Bit Mask

Write Command

One of the commands specified in COMMANDS on page 53 can be executed via opcode Write Command (0xD9). The command is automatically written to the CMD register at address 0x77 before execution. As shown in Figure 36, the data stream to be sent on MOSI consists of the opcode 0xD9 followed by the command to be executed. Those two bytes are also transmitted by iC-PZ on MISO.

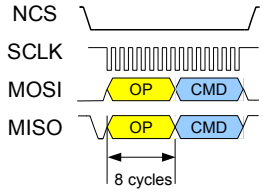


Figure 36: Write Command

Commands do require processing time until completed. Successful completion can be detected by polling the CMD register. Refer to COMMANDS on page 53 for details.

Read Diagnosis

Opcode Read Diagnosis (0x9C) is used to read the registers at address 0x6C to 0x73 containing error ERR and warning WARN information. As shown in Figure 37, only the opcode 0x9C has to be sent on MOSI. The opcode, followed by a delay byte 0x00 and 4 bytes each for ERR and WARN are transmitted by iC-PZ on MISO. Refer to DIAGNOSIS on page 64 for further information.

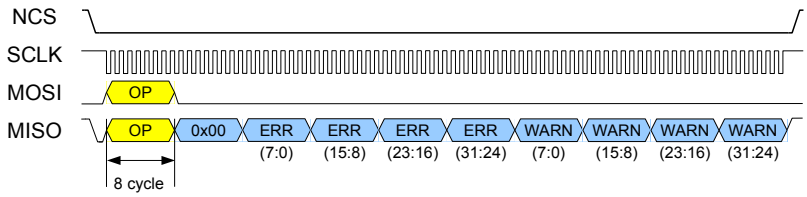


Figure 37: Read Diagnosis

Request Data From I2C Slave

Data from external devices connected to the I2C master of iC-PZ (e. g. EEPROM) can be requested via opcode Request Data From I2C Slave (0x97). As shown in Figure 38, the opcode followed by the register address of the I2C slave has to be sent on MOSI. The same content is transmitted by iC-PZ on MISO. After the opcode has been received, the initiated I2C communication will take additional time until completed. Opcode Get Transaction Info is used to poll for the current I2C communication status and new data.

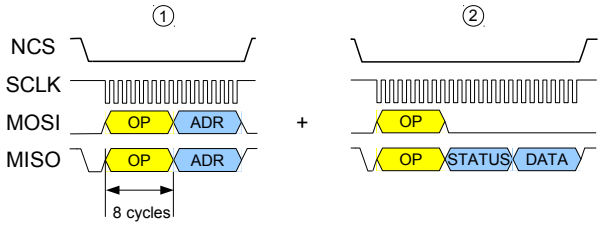


Figure 38: Request Data From I2C Slave

Transmit Data To I2C Slave

Data to external devices connected to the I2C master of iC-PZ (e. g. EEPROM) can be transmitted via opcode Transmit Data To I2C Slave (0xD2). As shown in Figure 39, the opcode followed by the register address of the I2C slave and the data byte to be transmitted has to be sent on MOSI. The same content is transmitted by iC-PZ on MISO. After the opcode has been received, the initiated I2C communication will take additional time until completed. Opcode Get Transaction Info is used to poll for the current I2C communication status.

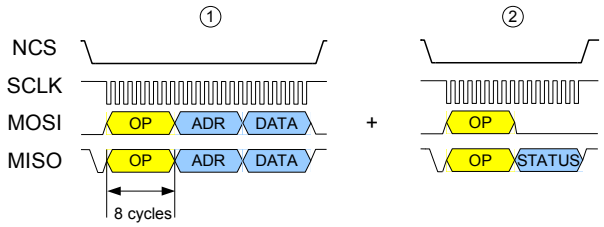


Figure 39: Transmit Data To I2C Slave

Note: For details about the address space of external I2C devices refer to MEMORY ORGANIZATION on page 22.

Note: For details on how to configure the I2C master refer to I2C MASTER on page 60.

Get Transaction Info

Via opcode Get Transaction Info (0xAD) the status of the last initiated SPI transaction is returned. Opcodes Read Position (0xA6) and Get Transaction Info (0xAD) itself are not updating the status byte. As shown in Figure 40, only the opcode has to be sent on MOSI. The opcode followed by the status byte defined in Table 62 is transmitted by iC-PZ on MISO. The data byte is only defined, if opcode Request Data From I2C Slave has been sent before.

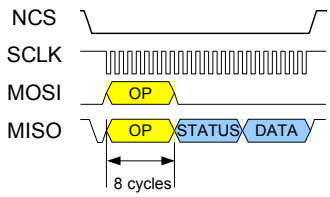


Figure 40: Get Transaction Info

SPI STATUS	
Bit	Description
7	Invalid Opcode
6:4	-
3	Illegal Address
2	Data Request Failed
1	Slave Busy
0	Data Valid

Table 62: SPI Status Byte

Multi-Slave Configurations with iC-PZ

A common SPI bus configuration for two iC-PZ is illustrated in Figure 41. Each slave is selected individually by the SPI master via a dedicated NCS line. Only one slave may communicate at the same time.

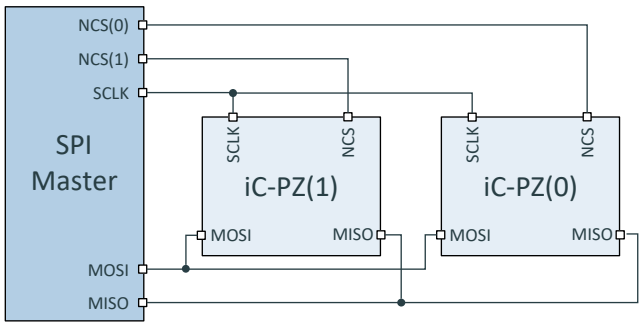


Figure 41: SPI bus configuration

Another possibility to connect multiple iC-PZ is by setting up an SPI daisy chain as shown in Figure 42. The MISO of each iC-PZ is connected to the MOSI of the next device. As only a single NCS line is used, individual slaves are selected via opcode Activate Slave in Chain.

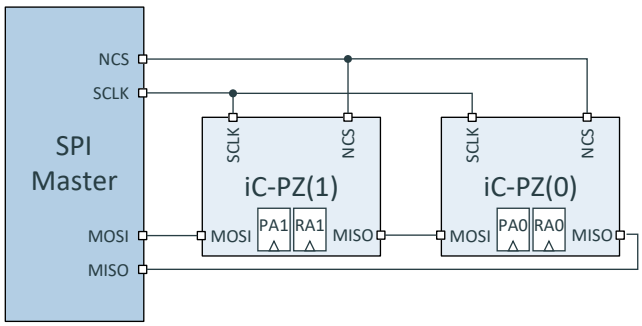


Figure 42: SPI daisy chain configuration

Note: Reading the current state of RACTIVE and PACTIVE is not possible.

Activate Slave In Chain

Each iC-PZ provides two separate channels for register and position data transfer that can be switched on and off individually. Register communication with iC-PZ is only possible if RACTIVE = 1. Otherwise register communication attempts are ignored. Position data can only be acquired from iC-PZ if PACTIVE = 1. Otherwise opcode Read Position (0xA6) is ignored.

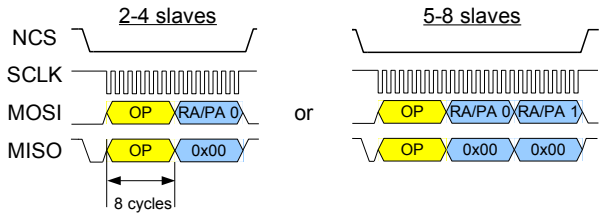


Figure 43: Activate Slave In Chain

By sending opcode Activate Slave in Chain (0xB0) each iC-PZ acts as a 2-bit shift register containing one RACTIVE and one PACTIVE configuration bit. RACTIVE and PACTIVE bits are initialized as '0', turning both data channels off. The SPI Status Byte is reset. Following the opcode, the desired RACTIVE/PACTIVE channel configuration is transmitted. Data bytes corresponding to all possible configurations are shown in Table 65. Slave number 0 is considered to be the last slave in chain directly connected to MISO of the SPI master.

RACTIVE	default: 1
Code	Description
0	Register communication deactivated
1	Register communication activated

Table 63: RACTIVE (RA)

PACTIVE	default: 1
Code	Description
0	Position data channel deactivated
1	Position data channel activated

Table 64: PACTIVE (PA)

Slaves	RA/PA configuration byte 0								RA/PA configuration byte 1							
2	0	0	0	0	RA0	PA0	RA1	PA1	Not used							
3	0	0	RA0	PA	RA1	PA1	RA2	PA2	Not used							
4	RA0	PA0	RA1	PA1	RA2	PA2	RA3	PA3	Not used							
5	0	0	0	0	0	0	RA0	PA0	RA1	PA1	RA2	PA2	RA3	PA3	RA4	PA4
6	0	0	0	0	RA0	PA0	RA1	PA1	RA2	PA2	RA3	PA3	RA4	PA4	RA5	PA5
7	0	0	RA0	PA0	RA1	PA1	RA2	PA2	RA3	PA3	RA4	PA4	RA5	PA5	RA6	PA6
8	RA0	PA0	RA1	PA1	RA2	PA2	RA3	PA3	RA4	PA4	RA5	PA5	RA6	PA6	RA7	PA7

Table 65: RA/PA channel configuration bits for 2-8 slaves

COMMANDS

CMD(7:0)		Addr. 0x77; bit 7:0	default: 0x00
Code	Name	Description	
0x00	<NOP_OK>	<Return-code: last operation succeded>	
0x10	REBOOT	Equivalent to power-on	
0x18	ADI_RESET	Reset the absolute data interface and re-synchronize with the external multiturn device	
0x20	SCLEAR	Clear the complete diagnosis register	
0x28	DIAG_USER0_RESET	Reset DIAG_USER(0) to 0	
0x29	DIAG_USER0_SET	Set DIAG_USER(0) to 1	
0x2A	DIAG_USER1_RESET	Reset DIAG_USER(1) to 0	
0x2B	DIAG_USER1_SET	Set DIAG_USER(1) to 1	
0x2C	DIAG_USER2_RESET	Reset DIAG_USER(2) to 0	
0x2D	DIAG_USER2_SET	Set DIAG_USER(2) to 1	
0x30	CRC_CALC	Calculate and apply valid CRC checksums for all configuration banks	
0x31	CRC_CHECK	Check for invalid CRC checksums in all configuration banks	
0x40	CONF_READ_ALL	Read configuration for all banks from EEPROM. This includes the RPL information for all banks and the RPL information for the EEPROM.	
0x41	CONF_WRITE_ALL	Write current configuration of all banks to EEPROM. This includes the RPL information for all banks and the RPL information for the EEPROM. Valid CRC checksums are always calculated automatically beforehand for all banks.	
0x42	CONF_READ	Read configuration for the active bank (*) from EEPROM. This includes the RPL information of the active bank.	
0x43	CONF_WRITE	Write current configuration of the active bank (*) to EEPROM. This includes the RPL information of the active bank. Valid CRC checksums are always calculated automatically beforehand for the active bank.	
0x80	MTST_PRESET	Calculate and apply MT_OFF and ST_OFF so that the current MT:ST-position will be equal to MT_PRE:ST_PRE	
0x81	MT_PRESET	Calculate and apply MT_OFF so that the current MT-position will be equal to MT_PRE	
0x82	ABZ_PRESET	Calculate and apply ABZ_OFF so that the current ABZ-position will be equal to ABZ_PRE	
0x83	UVW_PRESET	Calculate and apply UVW_OFF so that the current UVW-position will be equal to UVW_PRE	
0x88	MTST_PRESET_STORE	Identical to MTST_PRESET, additionally store the containing bank 0xB..C to EEPROM.	
0x89	MT_PRESET_STORE	Identical to MT_PRESET, additionally store the containing bank 0xC to EEPROM.	
0x8A	ABZ_PRESET_STORE	Identical to ABZ_PRESET, additionally store the containing bank 0x4 to EEPROM.	
0x8B	UVW_PRESET_STORE	Identical to UVW_PRESET, additionally store the containing bank 0x5 to EEPROM.	
0x90	GPIO_OUT0_SET0	Set GPIO_OUT(0) to 0	
0x91	GPIO_OUT0_SET1	Set GPIO_OUT(0) to 1	
0x92	GPIO_OUT1_SET0	Set GPIO_OUT(1) to 0	
0x93	GPIO_OUT1_SET1	Set GPIO_OUT(1) to 1	
0xA0	RPL_SET_NA	Set the register-protection-level of the active bank (*) to no-access. Call command CONF_WRITE to store the restriction in EEPROM	
0xA1	RPL_SET_RO	Set the register-protection-level of the active bank (*) to read-only. Call command CONF_WRITE to store the restriction in EEPROM	
0xA2	RPL_GET	Get the register-protection-level status of the active bank (*). The result is stored in CMD_STAT	
0xB0	AUTO_ADJ_ANA	Automatic analog adjustment. Refer to chapter ADJUSTMENT ANALOG for details.	
0xB1	AUTO_ADJ_DIG	Automatic digital adjustment (initial). Refer to chapter ADJUSTMENT DIGITAL for details.	
0xB2	AUTO_READJ_DIG	Automatic digital re-adjustment (in-field). Refer to chapter ADJUSTMENT DIGITAL for details.	
0xB3	AUTO_ADJ_ECC	Automatic eccentricity adjustment. Refer to chapter ADJUSTMENT ECCENTRICITY for details.	
0xC1	FORCE_BISS	Switch BiSS/SSI-Interface to BiSS (sets SSI_EN = 0)	
0xC2	FORCE_SSI	Switch BiSS/SSI-Interface to SSI (sets SSI_EN = 1)	
0xE0	CHIP_ID	Return CHIP_ID: for iC-PZ: 0x01	
0xE1	CHIP_REV	Return CHIP_REV: content identical to register REV	
0xFF	<NOP_FAIL>	<Return-code: last operation failed>	
(*) The active bank is defined by BSEL; BSEL must not be changed before the command finishes.			

Table 66: Commands

The CMD register is used to execute defined commands received via serial interface. As long as a command is queued or executed, CMD keeps the received command. Once the command has been completed successfully, CMD is set to 0x00. If an error occurs during command execution, CMD is set to 0xFF.

A separate CMD register is provided for each serial interface individually at address 0x77. It is forbidden to send a new command via the same interface while another command is still in queue or executed. Therefor, polling CMD after a command has been sent is essential. However, sending a single command via multiple interfaces is possible. If more than one command is received across different interfaces, execution is applied via first come first served scheduling so that delays may have to be taken into account.

For some commands useful information after execution, or in case an error occurred, are written to register CMD_STAT. A separate CMD_STAT register is provided for each serial interface individually at address 0x76.

CMD_STAT(7:0) Addr. 0x76; bit 7:0	default: 0x00, read-only
Code	Value
0x00	Last command succeeded
others	Last command error-code. See Table 68 for details

Table 67: Command Status

CMD_STAT error-code	
CRC_CHECK	
n	n = Amount of wrong bank CRCs. Refer to CRC_STAT for a detailed bitmask.
CONF_WRITE, CONF_WRITE_ALL, PRESET_STORE (all)	
0x10	Slave acknowledge missing, resulting in timeout. Slave may not be available or misconfigured.
0x11	Slave acknowledge missing after restart. Indicates a problem with the slave.
0x12	SCL stuck at zero
0x13	SDA stuck at zero
0x14	Arbitration lost
0x20	Unexpected event
CONF_READ, CONF_READ_ALL	
0x10..0x20	In case of communication issues with the EEPROM, the error code is identical to CONF_WRITE.
0x40	EEPROM communication ok, but at least one CRC is wrong. Refer to CRC_STAT for a detailed bitmask.
RPL_SET_x	
0x50	Illegal bank selected
0x60	Change refused. Only lower privileges are allowed.
RPL_GET	
0x00	No-access
0x01	Read-only
0x02	No restriction due to invalid CRC checksum
0x03	No restriction
0x50	Illegal bank selected
PRESET (all), FORCE (all)	
0xFE	Command rejected as it would modify data in a write-protected bank
AUTO_ADJ_ANA, AUTO_ADJ_DIG, AUTO_READJ_DIG, AUTO_ADJ_ECC	
0x80	Timeout. Either speed too low or settings too high. Increase speed or decrease AC_COUNT to prevent timeout.
AUTO_ADJ_ECC (continuing)	
0x81	Rotation reversal detected
0x82	Rotation too fast or position error occurred
others	
0x00	No error code available

Table 68: Command Status error-code

ABSOLUTE DATA INTERFACE (ADI)

Key features:

- Absolute data interface (ADI) master
- Read revolution counter (RC), i.e., multiturn (MT) position data, from external slave(s)
- SSI protocol with synchronization (SB), error (EB) and warning bits (WB)
- Slave position data (RC + SB) as one word (synced) or parts of words (unsynced)
- Access of raw slave position data

ADI key parameters	
Parameter	Value
Clock frequency	150 kHz or 1500 kHz
Frame repetition period	1.5 ms (normal operation) 0.2 ms (fast startup)
Slave timeout	11.5 µs. . . 40 µs
RC data length per slave	1 . . . 32 bit (single-slave operation) 1 . . . 5 bit (multi-slave operation)
Note	See also operating requirements for detailed timing information.

Table 69: ADI key parameters

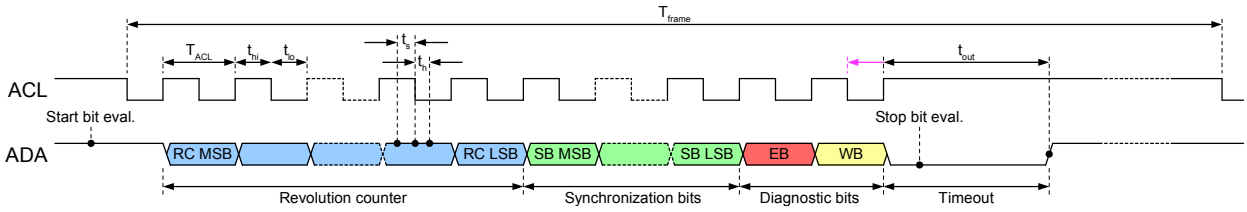


Figure 44: SSI protocol timing

Interface Enable

An internal revolution counter (RC) with a configurable absolute data interface (ADI) master is implemented to (periodically) read multiturn (MT) position data from an external sensor (slave) via the synchronous serial interface (SSI) protocol. Here, pin ACL is the clock output and pin ADA is the data input, respectively. The number of clock pulses depends on the configuration of the ADI master. The interface is enabled via bit ADI_CFG(7). If this bit is 0, only the internal revolution counter (RC) is active.

ADI_CFG(7)	Addr. 0x0, 0x0C; bit 7	default: 0
Code	Function	
0	Interface disabled (ACL=const=1), only counting	
1	Interface enabled	
Note	In case the bit becomes 0 while the interface is active, the communication is still completed, but the data is discarded.	

Table 70: ADI Enable

When the ADI master is enabled, the received position data is synchronized to the singleturn position to compensate for mechanical misalignment and SSI communication delays. The synchronized data is then compared to the internal revolution counter, which has been initialized during startup. In case of a position mismatch an error, DIAG(21), is reported and stored in the status register.

Single- and Multi-Slave Operation

Besides the classical single-slave operation, the ADI master also supports multi-slave operation, which is used to read in the raw (unsynchronized) position of multiple slave devices of a gear system and perform the synchronization among the slaves with the programmed synchronization bit length inside iC-PZ. Single- or multi--slave operation is configured via parameter ADI_MSO. In case a gear system with multiple slaves already provides a position that is synchronized among the slaves and only needs to be synchronized to the singleturn, ADI_MSO = 000 has to be used. That is because from the master's point of view, this system behaves like a single-slave system.

ADI_MSO(2:0)	Addr. 0x0, 0x0B; bit 7:5	default: 000
Code	Number of ADI slaves	
000	1 (Single-slave operation)	
001	2	
...	...	
110	7	
111	8	

Table 71: Multi-Slave Operation

The revolution counter (multiturn position) bit length per slave is implicitly configured via parameter MT_PDL, see Table 33. Here, MT_PDL always defines the total revolution counter bit length of the system. Hence, for single-slave operation (ADI_MSO = 000) the revolution

counter bit length per slave exactly corresponds to the value of MT_PDL. For multi-slave operation (ADI_MSO ≠ 000) however, the value of MT_PDL corresponds to the revolution counter bit length per slave multiplied by the number of slaves. In other words, valid values for MT_PDL depend on ADI_MSO. The maximum revolution counter bit length per slave is limited to 5. The allowed configurations for all supported systems are given in the Table below. Multi-slave operation is visualized at the end of this chapter in Figure 46 and Figure 47.

ADI_MSO	Slaves	Valid MT_PDL	Resulting RC bit length per slave
000	1	1..32	1..32
001	2	2, 4, 6, 8, 10	1, 2, 3, 4, 5
010	3	3, 6, 9, 12, 15	1, 2, 3, 4, 5
011	4	4, 8, 12, 16, 20	1, 2, 3, 4, 5
100	5	5, 10, 15, 20, 25	1, 2, 3, 4, 5
101	6	6, 12, 18, 24, 30	1, 2, 3, 4, 5
110	7	7, 14, 21, 28	1, 2, 3, 4
111	8	8, 16, 24, 32	1, 2, 3, 4

Table 72: Revolution counter bit length per slave

Synchronization

The ADI master implements a ±1 position data synchronization of two devices, i.e., the position of the so-called "sync-slave" is synchronized to the position of the so-called "sync-master". In a single-slave system there are only two devices: The singleturn device acts as the sync-master, while the multiturn device is the sync-slave. In a multi-slave (gear) system adjacent ADI slaves have to be synchronized as well: Here, the faster turning device acts as the sync-master, while the slower turning device is the sync-slave. The tolerable phase shift values in the following tables refer to a mechanical revolution of the sync-master device. Due to the ±1 synchronization principle, the optimal mounting phase shift between sync-master and sync-slave corresponds to 0 °m (center of the tolerable phase shift).

The synchronization bit length per slave is configured via parameter ADI_SBL. For the synchronization to the singleturn parameter ADI_OS can be used to compensate for a non-ideal mounting phase shift by shifting the received slave position according to ADI_OS inside the master device. If the mounting phase shift is unknown, one can determine it by reading parameter ADI_SB and comparing it to 4 MSBs of the singleturn position.

ADI_SBL(2:0)	Addr. 0x0, 0x0A; bit 2:0	default: 001
Code	Synchronization bit length per slave	Tolerable phase shift
Single-slave operation (ADI_MSO = 000) only.		
000	0	Sync. disabled
Single- and multi-slave operation		
001	1	± 90 °m
010	2	± 135 °m
011	3	± 157.5 °m
100	4	± 168.75 °m
others	invalid	
Note	Disabling the synchronization also disables the internal revolution counter, meaning the raw data received from the ADI slave can be accessed. This is only recommended for test or adjustment purposes. Increasing the revolution counter bit length in the ADI master by the number of synchronization bits of the slave grants access to the full, non-synchronized position data of the slave (RC + SB).	

Table 73: Synchronization Bit Length per Slave

ADI_OS(4:0)	Addr. 0x0, 0x0A; bit 7:3	default: 00000
Code	Synchronization offset	
00000	0 °m	
00001	11.25 °m	
...	...	
01110	157.5 °m	
01111	168.75 °m	
10000	-180 °m	
10001	-168.75 °m	
...	...	
11110	-22.5 °m	
11111	-11.25 °m	
Note	The synchronization offset is only applied to the synchronization of revolution counter to singleturn and not for the synchronization among slaves in multi-slave operation.	

Table 74: Synchronization Offset (electrical alignment slave vs. master)

ADI_SB(3:0)	Addr. 0x5E; bit 3:0	read-only
Output of up to 4 synchronization bits, as received from the ADI slave (left aligned).		

Table 75: Received Synchronization Bits (read-only)

Error and Warning Bits

For diagnostic purposes error and warning bits can be transmitted in the protocol besides the position data. The error bit length per slave is defined by parameter ADI_EBL, the polarity can be configured by parameter ADI_EBP. For multi-slave systems there are two different transmission schemes for the diagnostic bits, which are illustrated in Figure 46.

ADI_EBL(3:0)	Addr. 0x0, 0x0B; bit 3:0	default: 0001
Code	Error bit length per slave	
Single-slave operation (ADI_MSO = 000)		
0000	0	
0001	1	
...	...	
0111	7	
1000	8	
others	invalid	
Multi-slave operation (ADI_MSO ≠000)		
0000	0	
0001	1 (individual diagnostic bit transmission)	
0010	1 (gathered diagnostic bit transmission)	
others	invalid	
Note	See Figure 46 for the difference between individual and gathered diagnostic bit transmission.	

Table 76: Error Bit Length per Slave

ADI_EBP	Addr. 0x0, 0x0B; bit 4	default: 0
Code	Function	
0	Slave diagnostic bit polarity active low	
1	Slave diagnostic bit polarity active high	

Table 77: Diagnostic Bit Polarity

ADI_CFG(5)	Addr. 0x0, 0x0C; bit 5	default: 0
Code	Function	
0	No warning bit(s) in ADI data stream	
1	Evaluate warning bit(s) in ADI data stream	
Note	For ADI_CFG(5) = 1 the warning bit length corresponds to the configured error bit length.	

Table 78: Usage of Warning Bit(s)

Interface Settings

Register ADI_CFG contains additional important ADI configuration parameters, as described in the following tables.

ADI_CFG(8)	Addr. 0x0, 0x0D; bit 0	default: 0
Code	Function	
0	Slave position data in binary code	
1	Slave position data in gray code	
Note	The data format refers to the position data only (revolution counter + synchronization bits) and not the diagnostic bits.	

Table 79: ADI Slave Position Data Format

ADI_CFG(6)	Addr. 0x0, 0x0C; bit 6	default: 0
Code	Function	Typ. frequency
0	Slow ACL mode	150 kHz
1	Fast ACL mode	1500 kHz

Table 80: ACL Clock Operating Mode

ADI_CFG(4)	Addr. 0x0, 0x0C; bit 4	default: 1
Code	Function	
0	No cyclic counter verification (ACL=const=1)	
1	Cyclic counter verification vs. external data	

Table 81: Cyclic Counter Verification vs. external data

ADI_CFG(3)	Addr. 0x0, 0x0C; bit 3	default: 0
Code	Function	
0	Always keep internal counter	
1	Always load internal counter with external data	
Note	In case of ADI_CFG(3) = 1 the internal counter is always loaded with the available external data, but there is one exception: For ADI_CFG(2) = 1 the internal counter is kept in case of a single error event (ADA stuck-at, counter verification or error bit set).	

Table 82: External Data Priority

ADI_CFG(2)	Addr. 0x0, 0x0C; bit 2	default: 0
Code	Function	
0	Report single error events immediately	
1	Ignore single error events and keep internal counter value	
Note	In case of ADI_CFG(2) = 1, errors are only reported in case of two consecutive erroneous communications.	

Table 83: Double Error Messaging

ADI_CFG(1)	Addr. 0x0, 0x0C; bit 1	default: 0
Code	Function	
0	Default frame repetition period during startup (1500 µs)	
1	Modified frame repetition period during startup (200 µs)	
Note	For fast slaves a low frame repetition period during startup can be used to speed up the startup phase. It is recommended to configure the fast ACL mode here. Otherwise, the SSI communication might already exceed the target frame repetition period of 200 µs. In this case the actual frame repetition period is extended by iC-PZ to ensure a minimum waiting time of 50 µs between ACL pulse trains.	

Table 84: Fast Startup Enable

Startup

During system startup (after reset via power-cycle, NRES pin low or reset command) and if the interface is enabled (ADI_CFG(7) = 1), the ADI master cyclically tries to read data from the ADI slave(s). In case the slave(s) is(are) not yet ready (indicated by ADA = const = 1 or ADA = const = 0, which is recommended), the ADI master will stay in the startup phase and wait for the slave(s). If the ADI slave(s) does(do) not become ready, the startup phase is aborted after 100 ms and an error is reported. Note: The ADI master ensures a minimum idle time of 50 µs, before it initiates the first communication at the beginning of the startup phase.

Once valid communication is established with the ADI slave(s), the startup phase is not immediately left. To successfully finish the startup phase, two consecutive communications have to be valid (no protocol error), the internal counter versus external data verification has to be ok and no error bit in the protocol must be set. In case all conditions are met, the startup phase is left and the interface continues with normal operation.

Besides the system startup, the ADI master's startup phase can also be triggered by disabling and re-enabling the interface via ADI_CFG(7) or by executing command ADI_RESET. Note that in this case there is no termination criterion, i.e., the master will stay in the startup phase forever, if no valid communication can be established with the slave(s). The startup phase has in this case successfully finished, once DIAG(21) = 0 (Int./ext. RC position comparison) after clearing the status register.

The frame repetition period during startup can be lowered to 200 µs via ADI_CFG(1). For fast slaves this might be useful to speed up the startup phase.

Diagnosis

In addition to the synchronized position verification, DIAG(21), the received error and warning bits, DIAG(19:16) and DIAG(20), the ADI master also checks the following SSI protocol conditions:

1. ADA line is 1, right before the first ACL falling edge (start bit) → Verifies that the last frame finished correctly and detects ADA stuck-at-zero, DIAG(22).

2. ADA line is 0, right after the last ACL rising edge (stop bit) → Verifies the correct timeout and protocol length and detects ADA stuck-at-one, DIAG(23).

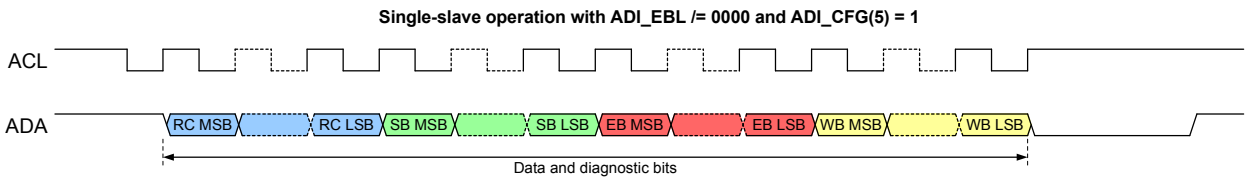


Figure 45: Single-slave operation – exemplary SSI protocol format

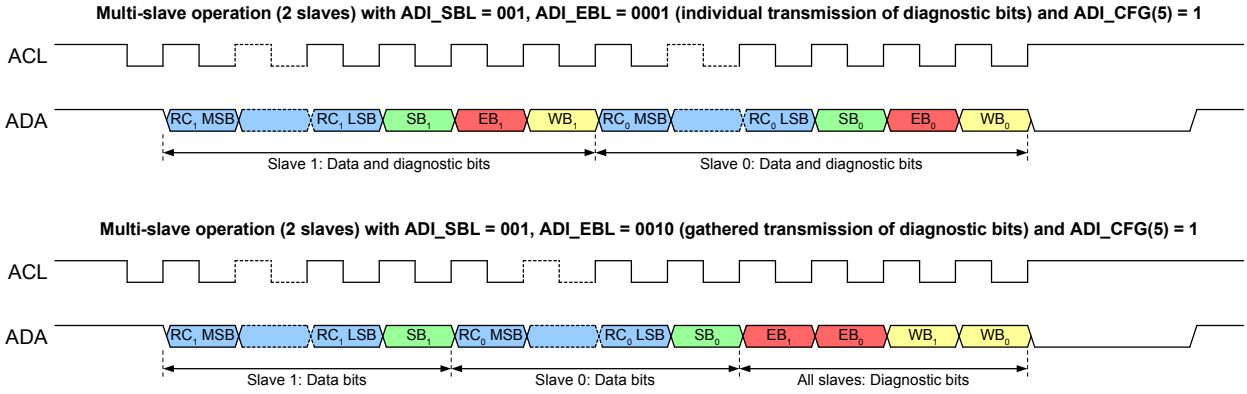


Figure 46: Multi-slave operation – exemplary SSI protocol formats

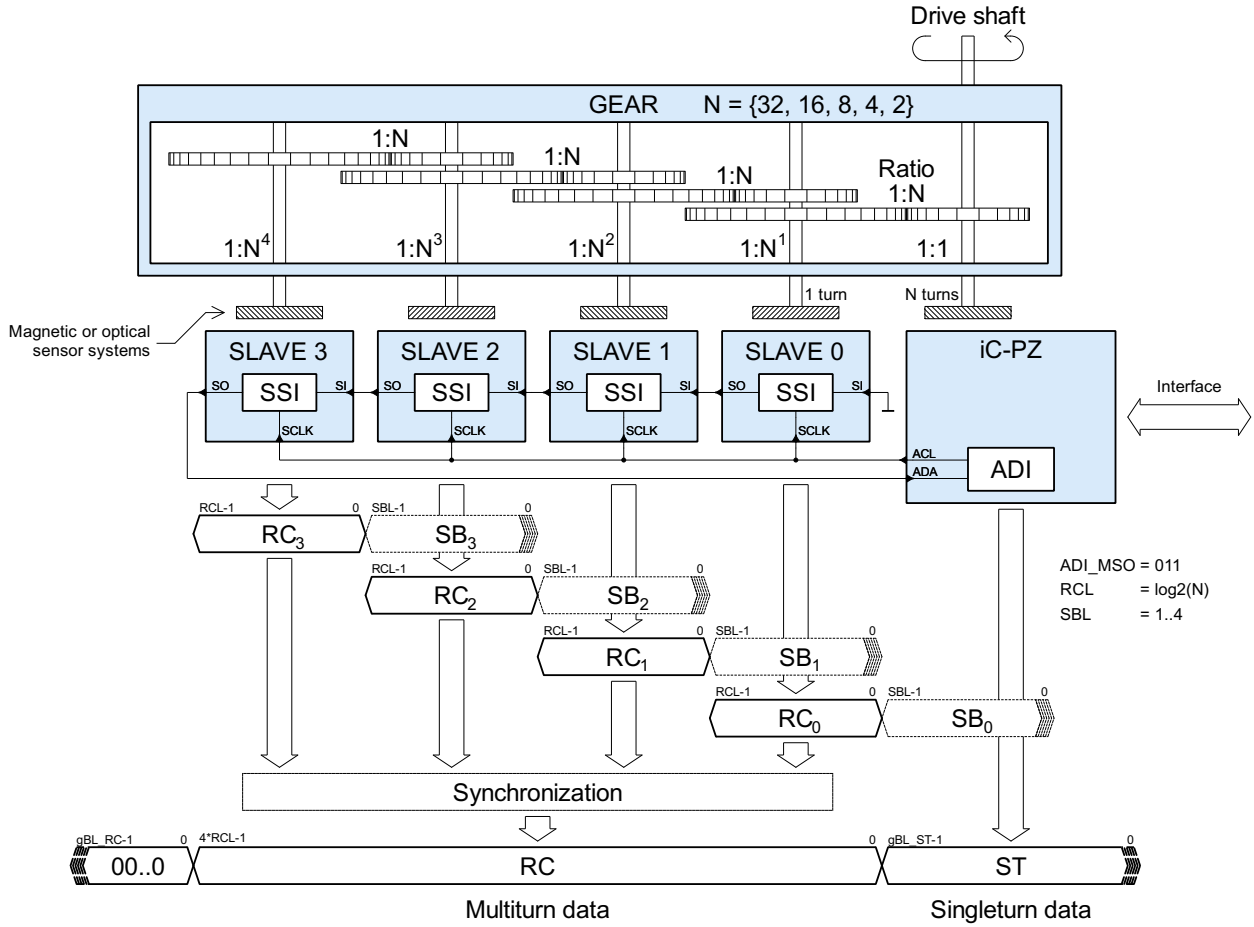


Figure 47: Multi-slave operation – application example with 4 slaves

I2C MASTER

The implemented I2C master is connected to at least one I2C slave, the EEPROM. Besides, it is possible to communicate with up to four additional slaves connected to the I2C master. The I2C communication can be initiated via BiSS or SPI.
The applied I2C clock frequency is selected via I2C_F_x. Up to 100 kHz and up to 400 kHz are supported. The individual I2C slave address has to be specified in I2C_DEV_ID_x. Only 7-bit addresses are supported. Additionally, the memory architecture of the individual I2C slave has to be defined via I2C_T_x. 8-bit or 16-bit devices are supported.

Communication with 8-bit devices

When using BiSS to initiate the I2C communication, the general procedure is quite similar to common on-chip register access. However, the I2C transmission takes additional processing time that has to be taken into account. No register accesses are allowed until the requested data has been fully received.
When using SPI to initiate the I2C communication, specific opcodes are available for that purpose. Refer to SPI SLAVE on page 48 for details.

Communication with 16-bit devices

The procedure described for 8-bit devices is still applicable. However, transferred data is buffered in I2C_DATA_x(15:0). When reading, the received byte must be ignored. Data will be available in I2C_DATA_x(15:0) after transmission has been completed. When writing, data to be transmitted has to be written to I2C_DATA_x(15:0) first. Then the appropriate procedures have to be executed, ignoring the data that is sent.

See Figures 48 and 49 for details of the supported I2C transmission modes.

Note: Before initiating any I2C communication, the active bank BSEL has to be set according to the address space used by the I2C slave. Refer to MEMORY ORGANIZATION on page 22 for details.

I2C_F_0	Addr. 0xA, 0x04;	bit 0	default: 0
I2C_F_1	Addr. 0xA, 0x05;	bit 0	default: 0
I2C_F_2	Addr. 0xA, 0x06;	bit 0	default: 0
I2C_F_3	Addr. 0xA, 0x07;	bit 0	default: 0

Code	Description
0	Up to 100 kHz I2C frequency
1	Up to 400 kHz I2C frequency

Table 85: I2C Frequency

I2C_DEV_ID_0	Addr. 0xA, 0x00;	bit 7:0	default: 0x00
I2C_DEV_ID_1	Addr. 0xA, 0x01;	bit 7:0	default: 0x00
I2C_DEV_ID_2	Addr. 0xA, 0x02;	bit 7:0	default: 0x00
I2C_DEV_ID_3	Addr. 0xA, 0x03;	bit 7:0	default: 0x00

Code	Description
0x80..0x9F, 0xB0..0xFF	available 7-bit I2C device ID, left-aligned, LSB is not used
others	forbidden

Table 86: I2C Device ID

I2C_T_0	Addr. 0xA, 0x04;	bit 7:1	default: 0x00
I2C_T_1	Addr. 0xA, 0x05;	bit 7:1	default: 0x00
I2C_T_2	Addr. 0xA, 0x06;	bit 7:1	default: 0x00
I2C_T_3	Addr. 0xA, 0x07;	bit 7:1	default: 0x00

Code	Description
0x00	8-bit access (devices like EEPROMs)
0x01	16-bit access (devices like temperature sensors)

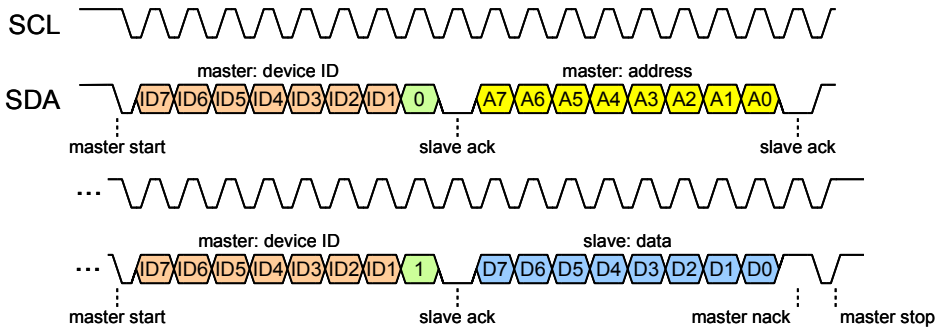
Table 87: I2C Slave Architecture Type

I2C_DATA_0(7:0)	Addr. 0x60;	bit 7:0	default: 0x00
I2C_DATA_0(15:8)	Addr. 0x61;	bit 7:0	default: 0x00
I2C_DATA_1(7:0)	Addr. 0x62;	bit 7:0	default: 0x00
I2C_DATA_1(15:8)	Addr. 0x63;	bit 7:0	default: 0x00
I2C_DATA_2(7:0)	Addr. 0x64;	bit 7:0	default: 0x00
I2C_DATA_2(15:8)	Addr. 0x65;	bit 7:0	default: 0x00
I2C_DATA_3(7:0)	Addr. 0x66;	bit 7:0	default: 0x00
I2C_DATA_3(15:8)	Addr. 0x67;	bit 7:0	default: 0x00

Value	Description
	I2C data for communication with 16-bit devices (I2C_T_x = 0x01)

Table 88: I2C Data

I²C register read (8 bit)



I²C register write (8 bit)

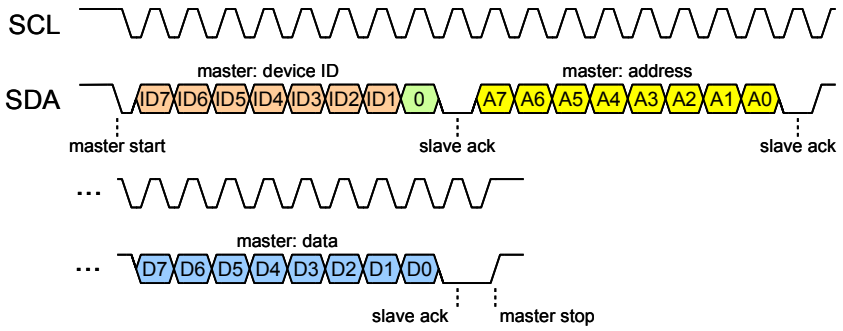
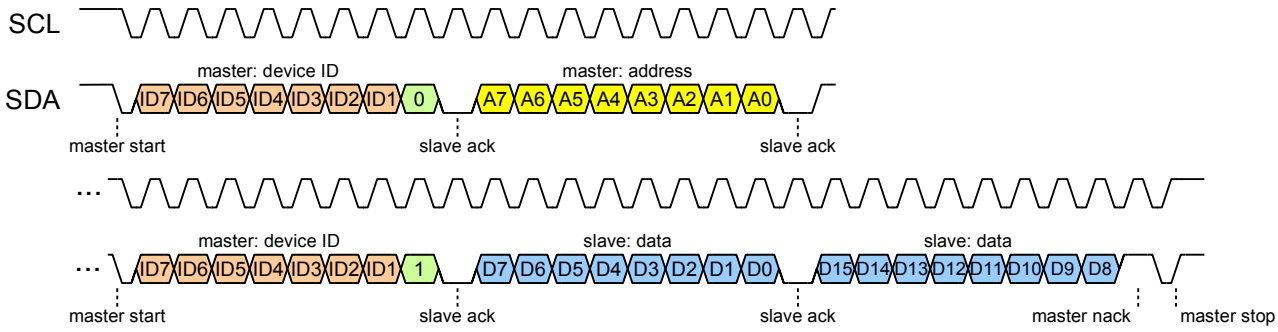


Figure 48: I2C 8-bit data protocol

I²C register read (16 bit)



I²C register write (16 bit)

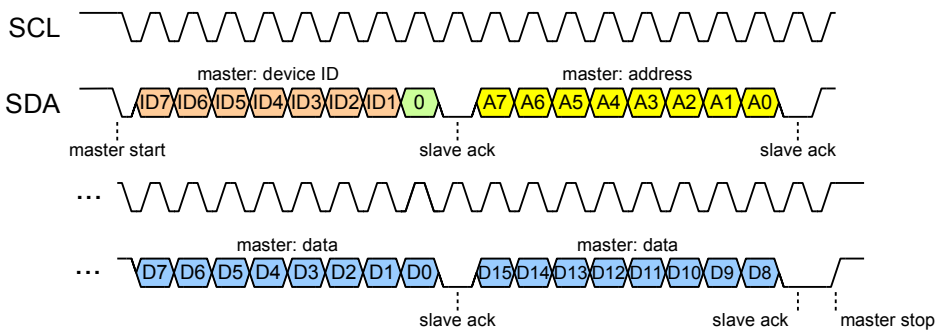


Figure 49: I2C 16-bit data protocol

GPIO

Two General Purpose Input/Output (GPIO) pins are provided by iC-PZ. Via GPIOx_CFG(1:0) each pin can be configured as input, push-pull output or open-drain in-out versus GNDIO or VDDIO. A graphical overview of the GPIO signal path is shown in Figure 50.

GPIO0_CFG(1:0) Addr. 0x9, 0x08; bit 1:0 default: 01 **GPIO1_CFG(1:0)** Addr. 0x9, 0x08; bit 5:4 default: 00	
Code	Description
00	Input only with pull-up
01	Open-drain (hard 0) and input with pull-up
10	Open-drain (hard 1) and input with pull-down
11	Push-pull (and input)

Table 89: GPIO Output Pad Configuration

GPIO as Input

When configured as input, the current state of GPIO(x) can be read from GPIO_IN(x). Additionally, an input can be used to trigger DIAG(26) or DIAG(27), which is useful to detect an error/warning from an external source. In GPIOx_DIAG the polarity triggering the error/warning is defined.

GPIO_IN(1:0) Addr. 0x4D; bit 3:2 default: n/a	
Bit	Description
1:0	Reads the current state of pins GPIO(1:0). The parameter is read-only

Table 90: GPIO Input State

GPIO as Output

When configured as output, the source controlling the logical pin state is selected via GPIOx_SEL. The output can either be controlled through setting the corresponding bit of GPIO_OUT(1:0), or using the state of specific events logged in DIAG. The bitmask GPIOx_M is used to select or deselect events for that purpose. In GPIOx_DIAG the polarity indicating the error/warning is defined.

GPIO0_SEL Addr. 0x9, 0x08; bit 3 default: 0 **GPIO1_SEL** Addr. 0x9, 0x08; bit 7 default: 0	
Code	Description
0	Pin GPIO(x) is driven by output of DIAG masked with GPIOx_M
1	Pin GPIO(x) is driven by register GPIO_OUT(x)

Table 91: GPIO Output Selection

GPIO_OUT(1:0) Addr. 0x4D; bit 1:0 default: 00	
Bit	Description
1:0	Defines output of pins GPIO(x), if selected by GPIOx_SEL. Can be written to directly, or command GPIO_OUTx_SETx can be sent

Table 92: GPIO Output State

GPIO0_DIAG Addr. 0x9, 0x08; bit 2 default: 0 **GPIO1_DIAG** Addr. 0x9, 0x08; bit 6 default: 0	
Code	Description
0	For input: 0 is interpreted as error/warning in DIAG For output: error is output as 0
1	For input: 1 is interpreted as error/warning in DIAG For output: error is output as 1

Table 93: GPIO Diagnosis Polarity

GPIO0_M(7:0)	Addr. 0x9, 0x00;	bit 7:0	default:
GPIO0_M(15:8)	Addr. 0x9, 0x01;	bit 7:0	0x01000000
GPIO0_M(23:16)	Addr. 0x9, 0x02;	bit 7:0	
GPIO0_M(31:24)	Addr. 0x9, 0x03;	bit 7:0	
GPIO1_M(7:0)	Addr. 0x9, 0x04;	bit 7:0	default:
GPIO1_M(15:8)	Addr. 0x9, 0x05;	bit 7:0	0x00000000
GPIO1_M(23:16)	Addr. 0x9, 0x06;	bit 7:0	
GPIO1_M(31:24)	Addr. 0x9, 0x07;	bit 7:0	
Bit	Description		
31:0	Selected bits of DIAG to be forwarded		

Table 94: GPIO(0/1) Bit Mask

Note: By default GPIO(0) is configured as open-drain output. After system startup has been completed successfully, GPIO(0) is set from hard 0 to pull-up 1.

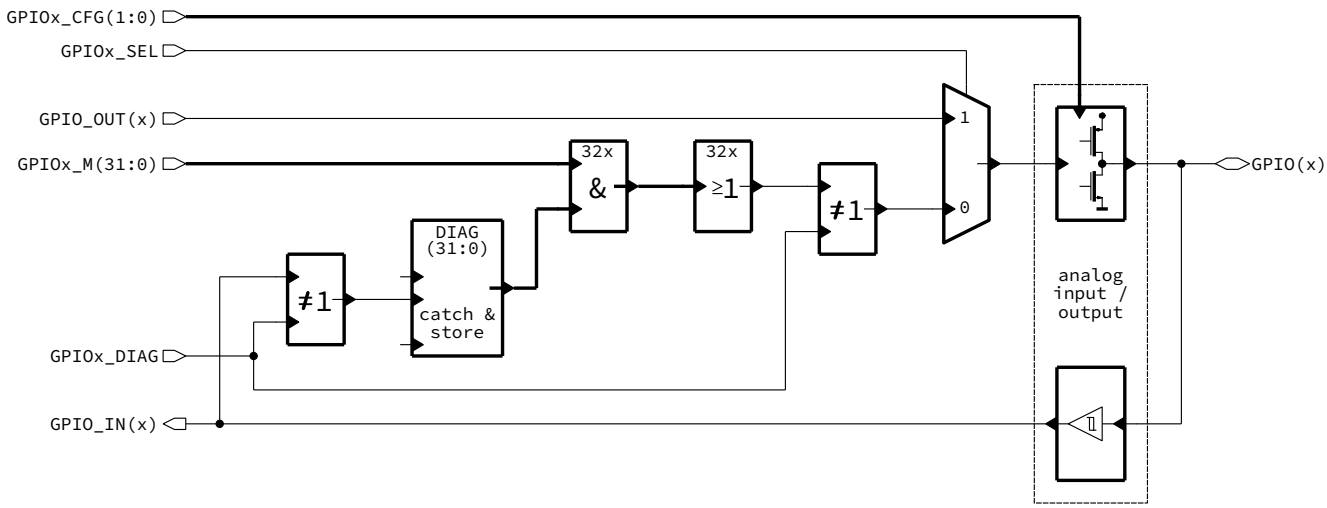


Figure 50: GPIO datapath overview

TEMPERATURE SENSOR

An on-chip temperature sensor with a resolution of 0.1 °C is integrated in iC-PZ. The temperature value is stored in TEMP. Refer to ELECTRICAL CHARACTERISTICS T01 for the temperature range covered.

TEMP(7:0) Addr. 0x4E; bit 7:0 read-only **TEMP(15:8)** Addr. 0x4F; bit 7:0 read-only	
Code	Value
Signed: 2K	$\frac{\text{value}}{10}$ °C
...	...
0xFE70	-40.0 °C
...	...
0xFFFF	- 0.1 °C
0x0000	0.0 °C
0x0001	0.1 °C
...	...
0x0578	140.0 °C
...	...

Table 95: Temperature

TEMP is latched by reading its lowest address 0x4E so that all corresponding register values are related to the same request. Reading this parameter from lowest to highest address is mandatory.

Additionally, two temperature limits can be set using TEMP_L_x. The limit uses the same coding as TEMP, but the upper four bits are omitted. TEMP_LT_x defines whether an upper or lower limit is set. If the temperature value is outside those limits at any time, an error/warning is reported in DIAG.

TEMP_L_1(7:0) Addr. 0xD,0x00; bit 7:0 default: 0x578 **TEMP_L_1(11:8)** Addr. 0xD,0x01; bit 3:0	
TEMP_L_2(7:0) Addr. 0xD,0x02; bit 7:0 default: 0xE70 **TEMP_L_2(11:8)** Addr. 0xD,0x03; bit 3:0	
Code	Value
	Coding equivalent to TEMP, omitting bits 15:12
...	...
0xE70	-40.0 °C
...	...
0xFFF	- 0.1 °C
0x000	0.0 °C
0x001	0.1 °C
...	...
0x578	140.0 °C
...	...

Table 96: Temperature Limit 1/2

TEMP_LT_1 Addr. 0xD, 0x04; bit 0 default: 0 **TEMP_LT_2** Addr. 0xD, 0x04; bit 1 default: 1	
Code	Value
0	Upper limit: will trigger diagnosis error/warning if temperature exceeds limit.
1	Lower limit: will trigger diagnosis error/warning if temperature falls below limit.

Table 97: Temperature Limit Type 1/2

DIAGNOSIS

An extensive diagnosis and error/warning reporting mechanism is provided by iC-PZ. A lot of parameters are monitored and recapped in the DIAG registers. They are caught and stored, even if occurring as a single event for a very short period of time. By masking specific bits in DIAG, the errors and warnings being reported in ERR and WARN can be selected individually.

For each serial interface an individual error/warning configuration can be defined. Refer to BiSS SLAVE, SSI SLAVE, and SPI SLAVE for details. An overview of the diagnosis datapath is shown in Figure 51.

Writing to DIAG will set the individually addressed bits. This can be used for testing purposes.

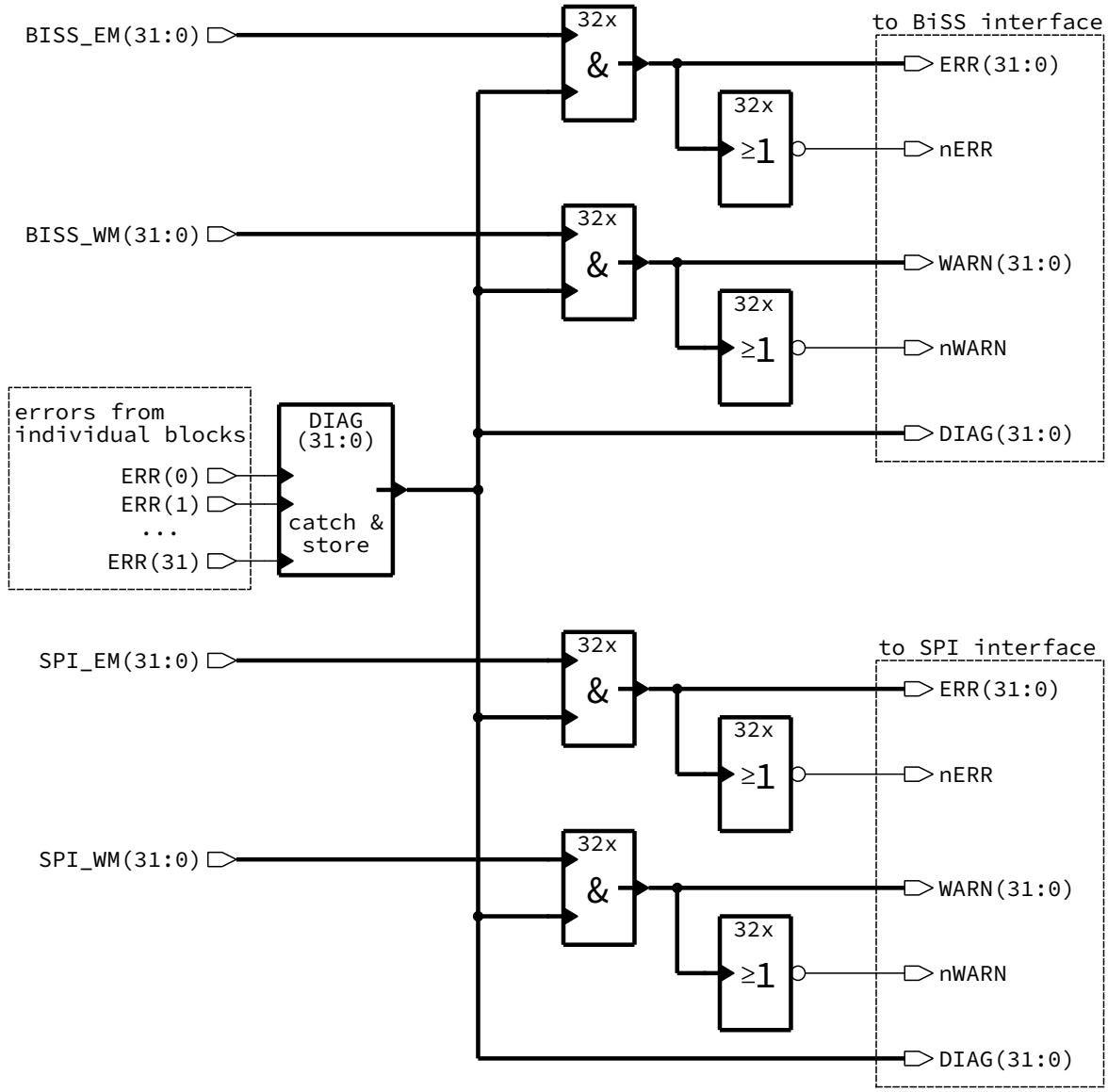


Figure 51: Diagnosis datapath overview

DIAG(7:0)		Addr. 0x68; bit 7:0	default:
DIAG(15:8)		Addr. 0x69; bit 7:0	0x00000000
DIAG(23:16)		Addr. 0x6A; bit 7:0	
DIAG(31:24)		Addr. 0x6B; bit 7:0	
Bit	Description	Error Condition	
Analog blocks:			
0	Digital photo-amplifiers in saturation	Illumination of at least one of the digital photo-diodes is too high, digital photocurrent-amplifier saturates	
1	LED current low	LED current smaller than 50% of the nominal current of square or sum control	
2	Temperature sensor not in steady state	Temperature sensor has not yet found the actual chip temperature	
3	VDDIO voltage low	Voltage at VDDIO below threshold set by VDDIOSEL as defined in Elec. Char. P05	
4	Interpolator error	Sinusoidal (analog) interpolator position is not within ±22.5°e of the digital interpolator position	
6	ABZ-Interface not ready	The ABZ-Interface has not yet reached the current position. Relevant at startup only. This error is not latched and automatically cleared when the position is reached.	
7	UVW-Interface not ready	The UVW-Interface has not yet reached the current position. Relevant at startup only. This error is not latched and automatically cleared when the position is reached.	
Digital blocks:			
8	Position filter: alpha overflow	Acceleration register alpha exceeds an internally defined limit resulting in new filter startup (≈ 256 µs)	
9	Position filter: omega overflow	Velocity register omega exceeds an internally defined limit resulting in new filter startup (≈ 256 µs)	
10	Digital photo-amplifiers not in steady state	Digital photo-amplifiers did not yet startup successfully	
11	PRC synchronization failed	PRC mismatching tolerance set in RAN_TOL exceeded. Most likely the PRC track was not sampled correctly. See chapter ADJUSTMENT DIGITAL for details on setting up the sampling.	
12	Analog adjustment parameter at boundary value	Parameter COS_OFFS, SIN_OFFS, SC_GAINS or SC_PHASES reached minimum or maximum value, or dynamic part of one of these registers is unexpected high (±12.5% of the range)	
13	Digital adjustment parameter at boundary value	Parameter AI_PHASES or AI_SCALES reached minimum or maximum value, or dynamic part of one of these registers is unexpected high (±12.5% of the range)	
14	Temperature limit 1	Chip temperature exceeds / falls below temperature limit defined by TEMP_L_1 and TEMP_LT_1	
15	Temperature limit 2	Chip temperature exceeds / falls below temperature limit defined by TEMP_L_2 and TEMP_LT_2	
Absolute data interface (ADI):			
19:16	Multiturn error bit(s) read from slave(s)	Mapping of multiturn error bit(s) as set and transmitted by multiturn slave(s). Error bits of slaves 0..2 are individually mapped to diagnosis bits 16..18, while error bits of slaves 3..7 are reduced (OR-operation) to diagnosis bit 19.	
20	Multiturn warning bit(s) read from slave(s)	Mapping of multiturn warning bit(s) as set and transmitted by multiturn slave(s). Warning bits of all slaves are reduced (OR-operation) to this single diagnosis bit	
21	Multiturn position comparison failed	Mismatch of internally counted revolution counter (RC) with external (synchronized) RC from multiturn interface	
22	Pin ADA stuck-at-0	SSI data line pin (ADA) is stuck-at-0 → No communication is possible	
23	Pin ADA stuck-at-1	SSI data line pin (ADA) is stuck-at-1 → No communication is possible	
Digital control:			
24	System startup in progress	System is starting up and not yet ready	
25	EEPROM CRC error	At least one CRC in the EEPROM is invalid (or EEPROM communication failed)	
26	Pin GPIO(0) as error input	Pin GPIO(0) is used as external error input. Error is reported if GPIO(0) ≠ GPIO0_DIAG	
27	Pin GPIO(1) as error input	Pin GPIO(1) is used as external error input. Error is reported if GPIO(1) ≠ GPIO1_DIAG	
28	System startup aborted due to timeout	Timeout reached while waiting for functional block to become ready at system startup	
31:29	User available	User-defined diagnosis register bits. Can be set and reset by any serial interface.	

Table 98: Diagnosis

Errors & Warnings

Individual error and warning bits can be cleared by writing the corresponding bits to ERR or WARN. If an error is cleared, the warning is also affected and the other way around. All error and warning bits are cleared by either writing 0xFFFFFFFF to ERR or WARN or executing command SCLEAR. Clearing errors or warnings affects all interfaces at the same time.

Note: The EEPROM CRC error bit in DIAG(25) cannot be cleared externally. For that purpose either one of the commands CONF_READ and CONF_READ_ALL has to be executed or a power-on reset has to be performed.

ERR(7:0)	Addr. 0x6C;	bit 7:0	default:
ERR(15:8)	Addr. 0x6D;	bit 7:0	0x00000000
ERR(23:16)	Addr. 0x6E;	bit 7:0	
ERR(31:24)	Addr. 0x6F;	bit 7:0	
Bit	Description		
31:0	Errors as indicated by DIAG(31:0) and masked with BISS_EM(31:0) / SPI_EM(31:0). Each interface reads its individually selected errors only.		

Table 99: Error

WARN(7:0)	Addr. 0x70;	bit 7:0	default:
WARN(15:8)	Addr. 0x71;	bit 7:0	0x00000000
WARN(23:16)	Addr. 0x72;	bit 7:0	
WARN(31:24)	Addr. 0x73;	bit 7:0	
Bit	Description		
31:0	Warnings as indicated by DIAG(31:0) and masked with BISS_EM(31:0) / SPI_EM(31:0). Each interface reads its individually selected warnings only.		

Table 100: Warning

CRC Status

Invalid CRC values of a bank are marked as 1 in CRC_STAT. After startup, CRC_STAT is automatically updated. Banks that could not be read from the EEPROM due to communication problems, are marked as invalid as well. CRC_STAT = 0x0000 indicates that all CRC values are valid. By using the command CRC_CALC, correct CRC values for all banks are calculated and marked as valid in CRC_STAT.

Example:
CRC_STAT = 0b0000000000001001 indicates invalid CRC values for bank 0x0 and bank 0x3.

CRC_STAT(7:0)	Addr. 0x74;	bit 7:0	default: 0xFFFF,
CRC_STAT(15:8)	Addr. 0x75;	bit 7:0	read-only
Bit	Value		
0:14	Register banks 0x0 to 0xE		
15	EEPROM protection CRC		

Table 101: CRC Status

SYSTEM CONFIGURATION

Revision & Identification

ID, REV, and SYS are defined by iC-Haus and are read-only.

ID(7:0)	Addr. 0x48; bit 7:0	read-only
ID(15:8)	Addr. 0x49; bit 7:0	read-only
ID(23:16)	Addr. 0x4A; bit 7:0	read-only
ID(31:24)	Addr. 0x4B; bit 7:0	read-only
	Individual chip identification number from iC-Haus	

Table 102: ID

REV(3:0)	Addr. 0x4C; bit 3:0	read-only
Code	Value	
0x0	iC-PZxxxx_0	
0x1	iC-PZxxxx_Z	
0x2	iC-PZxxxx_Y	
0x3	iC-PZxxxx_X	

Table 103: Chip Revision

SYS(3:0)	Addr. 0x4C; bit 7:4	read-only
Code	Value	
0x7	7-bit system, native for iC-PZ0974 rotary ∅9 mm	
0x8	8-bit system, native for iC-PZ2656 rotary ∅26 mm	
0xF	15-bit system, native for iC-PZ205 linear with length up to 6.71m	

Table 104: Chip System

System Definition

If the resolution provided by the system is not equal to SYS, in case the FLEXCODE® feature is used, SYS_OVR has to be set accordingly. The effective chip system SYS_eff is defined as:

SYS_eff = SYS for SYS_OVR = 0

SYS_eff = SYS_OVR for SYS_OVR ≠0

SYS_OVR(3:0)	Addr. 0x0, 0x07; bit 7:4	0x0
Code	Value	
0x0	no override: SYS_eff equals system-setting SYS	
others	override: SYS_eff equals SYS_OVR iC-PZ0974: 0x7 iC-PZ2656: 0x7 . . . 0x9 iC-PZ205: 0x9 . . . 0xF	

Table 105: Chip System Override

If SYS_OVR is adapted, that change has to be written to the EEPROM and the system must then be rebooted.

In case discs/scales with inverted and/or flipped codes are used, CD_INV and CD_FLIP can adjust iC-PZ accordingly. Both corrections can be used at the same time.

CD_INV	Addr. 0x0, 0x07; bit 0	default: 0
Code	Value	
0	Code on disc/scale not inverted (default)	
1	Code on disc/scale inverted (reflective/non-reflective)	

Table 106: Inverted Code Correction

CD_FLIP	Addr. 0x0, 0x07; bit 1	default: 0
Code	Value	
0	Code on disc/scale not flipped (default)	
1	Code on disc/scale flipped (mirrored left-to-right)	

Table 107: Flipped Code Correction

BiSS Profile & Identifier

EDS_BANK, BISS_PROFILE_ID, SERIAL, DEV_ID, and MFG_ID are available as editable parameters in bank 0xE and as read-only registers in the direct access registers 0x40..0x7F. Both are mapped to the same internal memory, so that their content is identical. After editing the parameters in bank 0xE, it can be good practice to protect the registers from being accessed by using command RPL_SET_RO (read-only) or RPL_SET_NA (no access). As last step, the bank then has to be written to the external EEPROM sending command CONF_WRITE.

EDS_BANK(7:0)	Addr. 0x41; bit 7:0	read-only
EDS_BANK_X(7:0)	Addr. 0xE, 0x01; bit 7:0	
Value	Pointer to BiSS EDS bank	

Table 108: BiSS EDS Bank

BISS_PROFILE_ID_1(7:0)	Addr. 0x42; bit 7:0	read-only
BISS_PROFILE_ID_0(7:0)	Addr. 0x43; bit 7:0	read-only
BISS_PROFILE_ID_1_X(7:0)	Addr. 0xE, 0x02; bit 7:0	
BISS_PROFILE_ID_0_X(7:0)	Addr. 0xE, 0x03; bit 7:0	
Value	BiSS profile ID	

Table 109: BiSS Profile ID

SERIAL_3(7:0)	Addr. 0x44; bit 7:0	read-only
SERIAL_2(7:0)	Addr. 0x45; bit 7:0	read-only
SERIAL_1(7:0)	Addr. 0x46; bit 7:0	read-only
SERIAL_0(7:0)	Addr. 0x47; bit 7:0	read-only
SERIAL_3_X(7:0)	Addr. 0xE, 0x04; bit 7:0	
SERIAL_2_X(7:0)	Addr. 0xE, 0x05; bit 7:0	
SERIAL_1_X(7:0)	Addr. 0xE, 0x06; bit 7:0	
SERIAL_0_X(7:0)	Addr. 0xE, 0x07; bit 7:0	
Value	Module manufacturer serial number	

Table 110: Serial Number

DEV_ID_5(7:0)	Addr. 0x78; bit 7:0	read-only
DEV_ID_4(7:0)	Addr. 0x79; bit 7:0	read-only
DEV_ID_3(7:0)	Addr. 0x7A; bit 7:0	read-only
DEV_ID_2(7:0)	Addr. 0x7B; bit 7:0	read-only
DEV_ID_1(7:0)	Addr. 0x7C; bit 7:0	read-only
DEV_ID_0(7:0)	Addr. 0x7D; bit 7:0	read-only
DEV_ID_5_X(7:0)	Addr. 0xE,0x08; bit 7:0	0x50 ('P')
DEV_ID_4_X(7:0)	Addr. 0xE,0x09; bit 7:0	0x5A ('Z')
DEV_ID_3_X(7:0)	Addr. 0xE,0x0A; bit 7:0	SYS & REV
DEV_ID_2_X(7:0)	Addr. 0xE,0x0B; bit 7:0	BISS_ST_DL
DEV_ID_1_X(7:0)	Addr. 0xE,0x0C; bit 7:0	BISS_MT_DL
DEV_ID_0_X(7:0)	Addr. 0xE,0x0D; bit 7:0	CRC16 & ENSOL & CRCS
Value	BiSS device ID	

Table 111: BiSS Device ID

MFG_ID_1(7:0)	Addr. 0x7E; bit 7:0	read-only
MFG_ID_0(7:0)	Addr. 0x7F; bit 7:0	read-only
MFG_ID_1_X(7:0)	Addr. 0xE,0x0E; bit 7:0	0x69 ('i')
MFG_ID_0_X(7:0)	Addr. 0xE,0x0F; bit 7:0	0x43 ('C')
Value	BiSS manufacturer ID	

Table 112: BiSS Manufacturer ID

FLEXCODE®

With the FlexCode® feature the available iC-PZ devices can be used to realize rotative absolute encoder systems with arbitrary code disc diameters:

Device	Covered code disc diameters
iC-PZ2656	16.2 mm . . . 44.6 mm
iC-PZ205	44.6 mm . . . up to linear 6.71 m

Table 113: FlexCode® supported disc diameters

The FlexCode® system is set up with FCL and FCS. Additionally, overriding the chip system via SYS_OVR might be necessary. Two examples of FlexCode®-systems are given in Table 116. Parameters and settings for specific code disc diameters are provided at support@ichaus.de.

FCL(7:0)	Addr. 0x8, 0x00;	bit 7:0	default:
FCL(14:8)	Addr. 0x8, 0x01;	bit 6:0	0x0000
Code	Value		
0x0000	FlexCode® disabled		
others	See Table 116 for example		

Table 114: FlexCode® Length

FCS(7:0)	Addr. 0x8, 0x02;	bit 7:0	default:
FCS(14:8)	Addr. 0x8, 0x03;	bit 6:0	0x0000
See Table 116 for example			

Table 115: FlexCode® Identifier

Code disc	Device	SYS_OVR	FCL	FCS
PZ08S, ⌀ 44 mm	iC-PZ2656	9	446	216
Other FlexCode®-systems on request.				

Table 116: FlexCode®-system example

Independent of the number of increments on the code disc, the digital interfaces BiSS, SSI, and SPI always output data as fully coded powers of 2, i.e., the binary singleturn value range is defined by SYS_eff bits for the PRC track (MSBs) plus the interpolated bits (LSBs).

Example:
iC-PZ2656 with PZ08S is a FlexCode®-system with SYS_eff = 9 and FCL = 446 (number of increments on the code disc). During a full mechanical revolution of 360°m, the 9 MSBs of the output singleturn position take values between 0 and 511.

Specification Modifications for FlexCode®

In a FlexCode®-system, the hysteresis values given in °e in Table 22 change according to

$$\frac{FCL}{2^{SYS\_eff}} \cdot \frac{2 \cdot ABZ\_HYS}{2^{14}} \cdot 360°e$$

The maximum rotary speed defined in Table 145 is

$$RPM \leq \frac{14.4 \cdot 10^6}{FCL}.$$

Minimum speed and time required for analog and digital autocalibration change as follows:

analog (see page 73):

$$n_{min} = \frac{2^{AC\_COUNT}}{FCL} \cdot 1.25 \frac{1}{s}$$

$$t_{rot} \approx \frac{2^{AC\_COUNT}}{FCL} \cdot \frac{AC\_SEL1 - AC\_SEL2}{n}$$

digital (see page 75):

$$n_{min} = \frac{2^{AC\_COUNT}}{FCL} \cdot 1.5 \frac{1}{s}$$

$$t_{rot} \approx \frac{2^{AC\_COUNT}}{FCL} \cdot \frac{AC\_SEL1 - AC\_SEL2}{\frac{3}{4} \cdot n}$$

ADJUSTMENT ANALOG

To achieve best interpolation results, the signal quality can be optimized on-chip via analog adjustment. Typical errors such as offset between the positive and the negative phases of cosine and sine, amplitude mismatch between cosine and sine, and incorrect phase shift between cosine and sine can be compensated. Good practice is to use the autocalibrations on command, however entering parameters manually is possible. In general, the raw signals to be adjusted can be described as

$$\begin{aligned} COS &= PCOS - NCOS \\ &= AMP\_COS \cdot \sin(\omega t + PH\_COS) + OS\_COS \end{aligned}$$

$$\begin{aligned} SIN &= PSIN - NSIN \\ &= AMP\_SIN \cdot \sin(\omega t + PH\_SIN) + OS\_SIN \end{aligned}$$

Offset

The cosine signals before and after the offset has been adjusted are shown in Figure 52. By setting COS_OFF to a positive value, the DC value of the differential signal is increased. The applied offset is independent of the actual signal amplitudes. For the sine signals this is applied identically.

$$COS = \cos(\omega t) + OS\_COS + COROS(COS)$$

To compensate the offset, a DC value COROS(COS) has to be added in the opposite direction of the measured offset OS_COS:

$$COROS(COS) = - OS\_COS$$

COS_OFF(1:0)	Addr. 0x1, 0x00;	bit 7:6	default: 0x000
COS_OFF(9:2)	Addr. 0x1, 0x01;	bit 7:0	
SIN_OFF(1:0)	Addr. 0x1, 0x02;	bit 7:6	default: 0x000
SIN_OFF(9:2)	Addr. 0x1, 0x03;	bit 7:0	

Code	COROS(COS) COROS(SIN)
Signed (2K)	COS_OFF · 0.235 mV SIN_OFF · 0.235 mV
0x000	0.000 mV
0x001	0.235 mV
0x002	0.470 mV
. . .	. . .
0x1FE	119.765 mV
0x1FF	120.000 mV
0x200	-120.000 mV (equal to 0x201)
0x201	-120.000 mV
0x202	-119.765 mV
. . .	. . .
0x3FE	-0.470 mV
0x3FF	-0.235 mV

Table 117: Adjustment Offset (static)

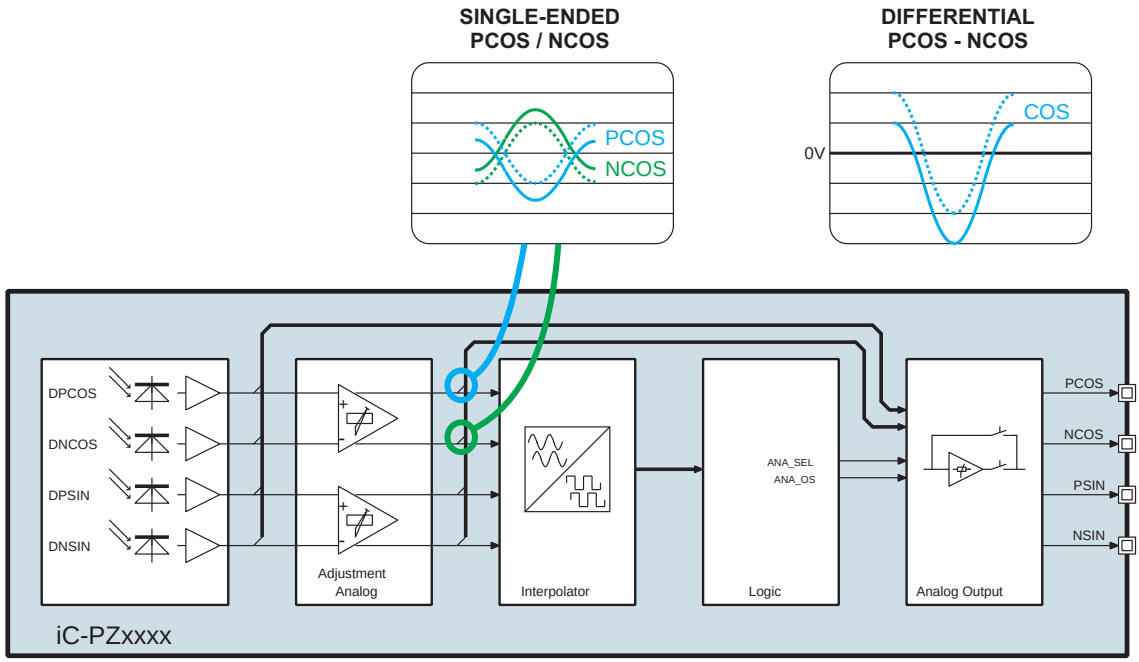


Figure 52: Signals before (solid) and after (dashed) Offset Adjustment with a positive DC value

Amplitude
All four phases of the cosine and sine signals before and after amplitude adjustment are shown in Figure 53. By changing SC_GAIN, the amplitudes of both cosine and sine are changed.

$$COS = COS\_GAIN \cdot AMP\_COS \cdot \cos(\omega t)$$
$$SIN = SIN\_GAIN \cdot AMP\_SIN \cdot \sin(\omega t)$$

Higher SC_GAIN increases the amplitude of the cosine signals and decreases the amplitude of the sine signals.

The amplitude correction factor CFA is defined as

$$CFA = \frac{COS\_GAIN}{SIN\_GAIN}$$

To correct amplitude mismatch, the correction factor CFA can be calculated as

$$CFA = \frac{AMP\_SIN}{AMP\_COS}$$

Note: AMP_SIN and AMP_COS are the **uncorrected** amplitudes for SC_GAIN = 0x000.

SC_GAIN(1:0) Addr. 0x1, 0x04; bit 7:6 default: 0x000 **SC_GAIN(9:2)** Addr. 0x1, 0x05; bit 7:0	
Code	CFA
Signed (2K)	$\left(\frac{14}{11}\right)^{\frac{SC\_GAIN}{511}}$
0x200	0.7857 (equal to 0x201)
0x201	0.7857
0x202	0.7861
...	...
0x3FF	0.9995
0x000	1.0000
0x001	1.0005
...	...
0x1FE	1.2721
0x1FF	1.2727

Table 118: Adjustment cosine-to-sine amplitude ratio (static)

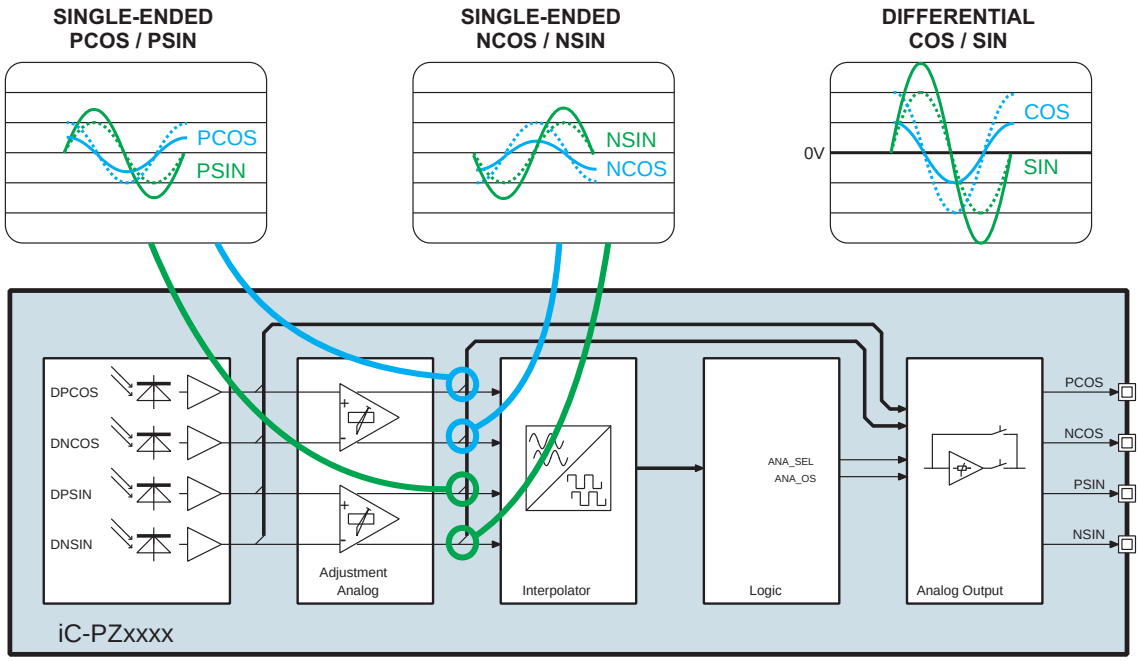


Figure 53: Signals before (solid) and after (dashed) Amplitude Adjustment with a positive value

Phase
The differential cosine and sine signals before and after phase adjustment are shown in Figure 54.

In ideal systems with no phase error, PH_COS =90°e and PH_SIN =0°e, the phase error can be described as

$$PH\_ERR = 90°e - (PH\_COS - PH\_SIN) = 0°e$$

In this example, the phase difference between cosine and sine is larger than 90°e:

$$PH\_COS - PH\_SIN > 90°e$$

$$PH\_ERR = 90°e - (PH\_COS - PH\_SIN) < 0°e$$

By changing SC_PHASE, both the phase of cosine and sine are changed:

$$PH\_ERR = 90°e - (PH\_COS - PH\_SIN) + CORPH$$

To adjust the phase between cosine and sine, SC_PHASE has to be increased until PH_ERR = 0°e:

$$CORPH = PH\_COS - PH\_SIN - 90°e$$

SC_PHASE(1:0) Addr. 0x1, 0x06; bit 7:6 default: 0x000 **SC_PHASE(9:2)** Addr. 0x1, 0x07; bit 7:0	
Code	CORPH
Signed (2K)	$\frac{SC\_PHASE}{511} \cdot 11.4\,°e$
0x200	-11.400 °e (equal to 0x201)
0x201	-11.400 °e
0x202	-11.378 °e
. . .	. . .
0x3FF	-0.022 °e
0x000	0.000 °e
0x001	0.022 °e
. . .	. . .
0x1FE	11.378 °e
0x1FF	11.400 °e

Table 119: Adjustment phase between cosine and sine (static)

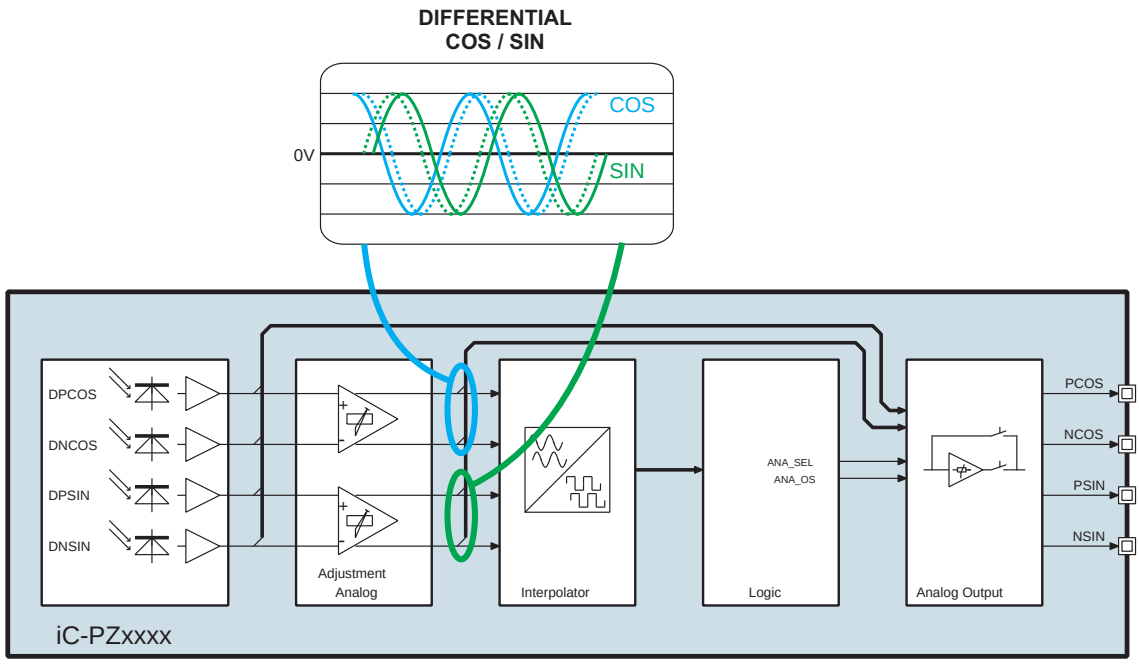


Figure 54: Signals before (solid) and after (dashed) Phase Adjustment with a positive value

Adjustment Analog, Static

COS_OFF, SIN_OFF, SC_GAIN and SC_PHASE can be calculated automatically by executing command AUTO_ADJ_ANA. There are several settings available to individually adapt the autocalibration procedure, however using the default values for AC_SEL1, AC_SEL2, AC_COUNT and AC_ETO is highly recommended.

When executing command AUTO_ADJ_ANA, the system must be rotating/moving. If constant speed is applied, the minimum speed can be calculated with the formulas in Table 124. There is also an example given that contains typical values for a rotary system with a code disc of 26 mm diameter and a linear system, both with the default values for AC_SEL1, AC_SEL2, AC_COUNT and AC_ETO.

The time required for the analog autocalibration with constant speed can be calculated with the formulas in Table 125. There is also an example given that contains typical values for systems described above and rotating/moving at 6 times the minimum speed.The time required can be reduced by increasing the speed. However, very high speeds may reduce the adjustment quality. For very slow systems, the minimum speed can be reduced by factor 10 activating AC_ETO.

Note: In FlexCode®-systems, the minimum speed and the time required for the analog autocalibration change as described in FLEXCODE® on page 69. For short linear applications, the calibration process can be performed by moving the sensor back and forth.

For frequencies f()sin above approx. 50 kHz, the analog adjustment is internally disabled.

AC_SEL1(3:0)	Addr. 0x5C; bit 3:0	default: 0xF
Code	Description	
0xF	Best but longest autocalibration	
..	..	
0x0	Worst but fastest autocalibration	

Table 120: Autocalibration Select Start

AC_SEL2(3:0)	Addr. 0x5C; bit 7:4	default: 0x0
Code	Description	
0x0	Best but longest autocalibration	
..	..	
0xE	Worst but fastest autocalibration	
0xF	No autocalibration	

Table 121: Autocalibration Select End

AC_COUNT(3:0)	Addr. 0x5D; bit 3:0	default: 0x8
Bit	Value	
3:0	Samples per autocalibration step, logarithmic	

Table 122: Autocalibration Count

AC_ETO	Addr. 0x5D; bit 7	default: 0
Code	Description	
0	Regular timeout for analog/digital autocalibration	
1	Extended timeout for analog/digital autocalibration: minimum speed required is reduced by factor 10	

Table 123: Autocalibration Extended Timeout

Note: AC_SEL1, AC_SEL2, AC_COUNT and AC_ETO are shared among all autocalibrations.

rotary	$n_{min} = 2^{AC\_COUNT - SYS\_eff} \cdot 1.25 \frac{1}{s}$	$n_{min,typ,\varnothing 26} = 1.25 \frac{1}{s} = 75\,RPM$
linear	$v_{min} = 2^{AC\_COUNT} \cdot 2.5 \cdot 10^{-4} \frac{m}{s}$	$v_{min,typ} = 6.4 \frac{cm}{s}$

Table 124: Minimum speed required for analog autocalibration with default settings

rotary	$t_{rot} \approx 2^{AC\_COUNT - SYS\_eff} \cdot \frac{AC\_SEL1 - AC\_SEL2}{n}$	$t_{rot,typ,\varnothing 26,450\,RPM} \approx 2.0\,s$
linear	$t_{lin} \approx 2^{AC\_COUNT} \cdot \frac{AC\_SEL1 - AC\_SEL2}{4883 \frac{1}{m} \cdot v}$	$t_{lin,typ,38.4\,cm/s} \approx 2.0\,s$

Table 125: Time required for analog autocalibration with default settings

Adjustment Analog, Dynamic

Besides the static analog adjustment, iC-PZ is able to correct signal drift during operation, e. g. caused by temperature. The sensitivity against dynamically occurring effects is selected individually for each parameter via SC_OFF_SEL, SC_GAIN_SEL and SC_PHASE_SEL. Those values are not affecting the static values set for COS_OFF, SIN_OFF, SC_GAIN and SC_PHASE.

SC_OFF_SEL (3:0)	Addr. 0x2, 0x00; bit 3:0	default: 0x0
Code	Function	
0x0	Disabled	
0x1	Lowest Dynamic	
...	... (logarithmic)	
0x7	Moderate Dynamic	
...	... (logarithmic)	
0xF	Highest Dynamic	

Table 126: Dynamic analog offset adjustment select

SC_GAIN_SEL (3:0)	Addr. 0x2, 0x00; bit 7:4	default: 0x0
Code	Function	
0x0	Disabled	
0x1	Lowest Dynamic	
...	... (logarithmic)	
0x7	Moderate Dynamic	
...	... (logarithmic)	
0xF	Highest Dynamic	

Table 127: Dynamic analog amplitude-ratio adjustment select

SC_PHASE_SEL (3:0)	Addr. 0x2, 0x01; bit 3:0	default: 0x0
Code	Function	
0x0	Disabled	
0x1	Lowest Dynamic	
...	... (logarithmic)	
0x7	Moderate Dynamic	
...	... (logarithmic)	
0xF	Highest Dynamic	

Table 128: Dynamic analog phase adjustment select

Adjustment Analog, Applied Correction

COS_OFFS, SIN_OFFS, SC_GAINS and SC_PHASES are giving information about the currently applied correction values of both static and dynamic analog adjustment.

Note: COS_OFFS, SIN_OFFS, SC_GAINS and SC_PHASES are read-only and can not be stored in the EEPROM. When the dynamic adjustment is disabled, its correction value is set to 0 and only the static adjustment is effective.

COS_OFFS(1:0)	Addr. 0x1, 0x20; bit 7:6	default: 0x000
COS_OFFS(9:2)	Addr. 0x1, 0x21; bit 7:0	
SIN_OFFS(1:0)	Addr. 0x1, 0x22; bit 7:6	default: 0x000
SIN_OFFS(9:2)	Addr. 0x1, 0x23; bit 7:0	
Code	Value	
	Identical to COS_OFF and SIN_OFF	

Table 129: Adjustment offset (static+dynamic)

SC_GAINS(1:0)	Addr. 0x1, 0x24; bit 7:6	default: 0x000
SC_GAINS(9:2)	Addr. 0x1, 0x25; bit 7:0	
Code	Value	
	Identical to SC_GAIN	

Table 130: Adjustment cosine-to-sine amplitude ratio (static+dynamic)

SC_PHASES (1:0)	Addr. 0x1, 0x26; bit 7:6	default: 0x000
SC_PHASES (9:2)	Addr. 0x1, 0x27; bit 7:0	
Code	Value	
	Identical to SC_PHASE	

Table 131: Adjustment phase between cosine and sine (static+dynamic)

COS_OFFS, SIN_OFFS, SC_GAINS and SC_PHASES are latched by reading their lowest address 0x20, 0x22, 0x24 and 0x26 so that all corresponding register values are related to the same request. Reading those parameters from lowest to highest register address is mandatory.

ADJUSTMENT DIGITAL

Adjustment Digital, Static
The initial digital autocalibration is done by executing command AUTO_ADJ_DIG. AI_PHASE and AI_SCALE are calculated automatically, so that even significant misalignments between incremental and absolute track can be compensated.

Note: Changing AI_PHASE and/or AI_SCALE affects position calculation so that current offsets ST_OFF, MT_OFF, ABZ_OFF and UVW_OFF as well as eccentricity compensation parameters may become invalid.

Command AUTO_READJ_DIG can be used to compensate minor changes in alignment for a system that has been calibrated before. The current singleturn position will not be affected and all offsets stay valid. There are several settings available to individually adapt the autocalibration procedure, however using the default values for AC_SEL1, AC_SEL2, AC_COUNT and AC_ETO is highly recommended.

Note: AC_SEL1, AC_SEL2, AC_COUNT and AC_ETO are shared among all autocalibrations.

When executing command AUTO_ADJ_DIG or AUTO_READJ_DIG, the system must be rotating/moving. If constant speed is applied, the minimum speed can be calculated with the formulas in Table 134. There is also an example given that contains typical values for a rotary system with a code disc of 26 mm diameter and a linear system, both with the default values for AC_SEL1, AC_SEL2, AC_COUNT and AC_ETO.

The time required for the digital autocalibration with constant speed can be calculated with the formulas in Table 135. There is also an example given that contains typical values for systems described above and rotating/moving at 5 times the minimum speed. The time required can be reduced by increasing the speed. However, very high speeds may reduce the adjustment quality. For very slow systems, the minimum speed required can be reduced by factor 10 activating AC_ETO.

Note: In FlexCode®-systems, the minimum speed and the time required for digital autocalibration change as described in FLEXCODE® on page 69. For short linear applications, the calibration process can be performed by moving the sensor back and forth.

AI_PHASE(1:0) Addr. 0x1, 0x08; bit 7:6 **AI_PHASE(9:2)** Addr. 0x1, 0x09; bit 7:0	default: 0x000
Code	Phase adjustment value
Signed (2K)	$\frac{\text{AI\_PHASE}}{512} \cdot 180\,°\text{e}$

Table 132: Adjustment phase error (static)

AI_SCALE(0) Addr. 0x1,0x0A; bit 7 **AI_SCALE(8:1)** Addr. 0x1,0x0B; bit 7:0	default: 0x000
Code	Scale adjustment factor
Signed (2K)	$1 + \frac{\text{AI\_SCALE}}{1820}$

Table 133: Adjustment scale error (static)

rotary	$n_{min} = 2^{\text{AC\_COUNT - SYS\_eff}} \cdot 1.5\frac{1}{s}$	$n_{min,typ,\varnothing 26} = 1.5\frac{1}{s} = 90\,RPM$
linear	$v_{min} = 2^{\text{AC\_COUNT}} \cdot 3 \cdot 10^{-4}\frac{m}{s}$	$v_{min,typ} = 7.68\frac{cm}{s}$

Table 134: Minimum speed required for digital autocalibration with default settings

rotary	$t_{rot} \approx 2^{\text{AC\_COUNT - SYS\_eff}} \cdot \frac{AC\_SEL1 - AC\_SEL2}{\frac{3}{4} \cdot n}$	$t_{rot,typ,\varnothing 26,450\,\text{RPM}} \approx 2.67s$
linear	$t_{lin} \approx 2^{\text{AC\_COUNT}} \cdot \frac{AC\_SEL1 - AC\_SEL2}{3662\frac{1}{m} \cdot v}$	$t_{lin,typ,38.4cm/s} \approx 2.73s$

Table 135: Time required for digital autocalibration with default settings

Adjustment Digital, Dynamic

Besides the static digital adjustment, iC-PZ is able to compensate misalignments during operation. The sensitivity against dynamically occurring effects is selected individually for each parameter via AI_P_SEL and AI_S_SEL. Those values are not affecting the static values set for AI_PHASE and AI_SCALE.

AI_P_SEL(3:0)	Addr. 0x2, 0x03; bit 3:0	default: 0x0
Code	Phase adjustment value	
0x0	Disabled	
0x1	Lowest Dynamic	
...	... (logarithmic)	
0x7	Moderate Dynamic	
...	... (logarithmic)	
0xF	Highest Dynamic	

Table 136: Dynamic adjustment phase select

AI_S_SEL(3:0)	Addr. 0x2, 0x03; bit 7:4	default: 0x0
Code	Scale adjustment value	
0x0	Disabled	
0x1	Lowest Dynamic	
...	... (logarithmic)	
0x7	Moderate Dynamic	
...	... (logarithmic)	
0xF	Highest Dynamic	

Table 137: Dynamic adjustment scale select

Adjustment Digital, Applied Correction

AI_PHASES and AI_SCALES are giving information about the currently applied correction values of both static and dynamic digital adjustment.

Note: AI_PHASES and AI_SCALES are read-only and can not be stored in the EEPROM. When the dynamic adjustment is disabled, its correction value is set to 0 and only the static adjustment is effective.

AI_PHASES(1:0)	Addr. 0x1, 0x28; bit 7:6	read-only
AI_PHASES(9:2)	Addr. 0x1, 0x29; bit 7:0	
Code	Phase adjustment in °e (rounded)	
	Identical to AI_PHASE	

Table 138: Adjustment phase error (static+dynamic)

AI_SCALES(0)	Addr. 0x1, 0x2A; bit 7	read-only
AI_SCALES(8:1)	Addr. 0x1, 0x2B; bit 7:0	
Code	Description	
	Identical to AI_SCALE	

Table 139: Adjustment scale error (static+dynamic)

AI_PHASES and AI_SCALES are latched by reading their lowest address 0x28 and 0x2A so that all corresponding register values are related to the same request. Reading those parameters from lowest to highest register address is mandatory.

ADJUSTMENT ECCENTRICITY

Code discs mounted eccentric are providing a long-wave sinusoidal position error over a full revolution. Most of this error can be compensated by the eccentricity adjustment of the iC-PZ. The correction values ECC_AMP and ECC_PHASE are calculated on-chip by executing command AUTO_ADJ_ECC. The autocalibration is performed over 2^AC_COUNT revolutions. Using the default value for AC_COUNT is highly recommended. Before starting the autocalibration, the eccentricity correction has to be switched off via ECC_EN.

Note: AC_COUNT is shared among all autocalibrations.

The minimum speed for the eccentricity autocalibration given in Table 143 is independent of the code disc diameter.

The time required for the eccentricity autocalibration procedure with constant speed can be calculated with the formula in Table 144. There is also an example given that contains a typical value for a system rotating/moving at 30 times the minimum speed. The time required can be reduced by increasing the speed.

Rotating at constant speed and at steady state is crucial when eccentricity autocalibration is performed.

ECC_AMP(7:0)	Addr. 0x2, 0x04; bit 7:0	default:
ECC_AMP(15:8)	Addr. 0x2, 0x05; bit 7:0	0x0000000
ECC_AMP(23:16)	Addr. 0x2, 0x06; bit 7:0	
ECC_AMP(31:24)	Addr. 0x2, 0x07; bit 7:0	
Code	Eccentricity amplitude value	
Unsigned	$1.407 \cdot 10^{-9} \cdot r_{opt\_AB} \cdot$ ECC_AMP, with $r_{opt\_AB}(\varnothing 26mm) = 10700\,\mu m$ $r_{opt\_AB}(\varnothing 09mm) = 3600\,\mu m$	

Table 140: Eccentricity amplitude error

ECC_PHASE(5:0)	Addr. 0x2, 0x08; bit 7:2	default: 0x0000
ECC_PHASE(13:6)	Addr. 0x2, 0x09; bit 7:0	
Code	Eccentricity phase value	
Signed (2K)	$\frac{360°m}{2^{14}} \cdot$ ECC_PHASE	

Table 141: Eccentricity phase error

ECC_EN	Addr. 0x2, 0x0A; bit 0	default: 0
Code	Value	
0	Eccentricity correction off	
1	Eccentricity correction on	

Table 142: Enable eccentricity correction

rotary	$n_{min} = 0.5\frac{1}{s}$	$n_{min,all} = 0.5\frac{1}{s} = 30\,RPM$

Table 143: Minimum speed for eccentricity autocalibration

rotary	$t_{rot} \approx 2^{AC\_COUNT} \cdot \frac{1}{n}$	$t_{rot,typ,all,900\,RPM} \approx 17\,s$

Table 144: Time required for eccentricity autocalibration with default settings

SAFETY ADVICE

Depending on the mode of operation, these devices emit highly concentrated visible blue light which can be hazardous to the human eye.

Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1 and IEC 62471.

HANDLING ADVICE

Because of the specific housing materials and geometries used, these LED devices are sensitive to rough handling or assembly and can thus be easily damaged or may fail in regard to their electro-optical operation. Excessive mechanical stress or load on the LED surface or to the glass windows must be avoided.

DEVICE OVERVIEW

Rotative

Device	CPR	Resolution		Code Disc		Typ. I(VDDA) / mA			Max. RPM[2]
	native	bit (CPR+IPO)	arcsec	P/O Code	Type	LED off	1.5 mm[1]	2.0 mm[1]	
iC-PZ0974	74	< 21	1.08	PZ07S	M	18.4	21.6	23.3	190 000
iC-PZ2656	256	22 (8+14)	0.31	PZ03S	P	18.4	21.6	23.3	56 250
iC-PZ2656	256	22 (8+14)	0.31	PZ03S	M	18.4	21.6	23.3	56 250
iC-PZ2656	446	< 23	0.18	PZ08S	M	18.4	21.6	23.3	32 200
iC-PZ205	1024	24 (10+14)	0.08	PZ05S	M	18.4	24.0	27.4	14 000

Linear

Device	Max. Len.	Resolution		Code Disc		Typ. I(VDDA) / mA			Max. Speed
	m	bit	nm	P/O Code	Type	LED off	1.5 mm[1]	2.0 mm[1]	m/s
iC-PZ205	6.7	29 (15+14)	12.5	PZ01L		18.4	25.1	29.4	50

Type M = Metal
Type P = Polycarbonate
Type F = Film
Type [ ] = Glass

Device availability on request.

Table 145: Device overview

[1] Air gap (iC to code disc / linear scale), I(VDDA) without analog output buffer

[2] In FlexCode®-systems, Max. RPM changes as described in chapter **FLEXCODE®**.

DESIGN REVIEW: Notes On Chip Functions

iC-PZxxxx Z		
No.	Function, Parameter/Code	Description and Application Hints
1	ABZ Generator	Z signal level changes during configuration read from external EEPROM if ABZ_CFG(1) = 1.
2	UVW Generator	UVW signal levels not determined during startup. Valid UVW signal output 50 µs after DIAG(24) = 1 (RDY).
3	System Definition	For SYS_OVR ≠ 0x0, system startup may finish incompletely. In this case, a system reboot is required, e. g. via pin NRES, command REBOOT, or power cycle.
4	I2C	I2C-interface suits single-master applications only.
5	Feature FLEXCODE® Feature DISC/SCALE CORRECTION Feature ABZ/UVW ready Parameter LED_CONST Command CHIP_REV Default value IPO_FILT1	Feature/parameter/command available with chip release Y.

Table 146: Notes on chip functions regarding iC-PZxxxx chip revision Z

iC-PZxxxx Y		
No.	Function, Parameter/Code	Description and Application Hints
3	System Definition	For SYS_OVR ≠ 0x0, system startup may finish incompletely. In this case, a system reboot is required, e. g. via pin NRES, command REBOOT, or power cycle.
4	I2C	I2C-interface suits single-master applications only.
6	Adjustment Analog	Command AUTO_ADJ_ANA requires SC_OFF_SEL, SC_GAIN_SEL or SC_PHASE_SEL ≠ 0.

Table 147: Notes on chip functions regarding iC-PZxxxx chip revision Y

iC-PZxxxx X		
No.	Function, Parameter/Code	Description and Application Hints
		None at time of release.

Table 148: Notes on chip functions regarding iC-PZxxxx chip revision X

REVISION HISTORY

Rel.	Rel. Date[1]	Chapter	Modification	Page
A1	2019-04-18	...	Initial release	all

Rel.	Rel. Date[1]	Chapter	Modification	Page
B1	2019-11-08	FEATURES	Features updated	1
		BLOCK DIAGRAM	Updated	1
		DESCRIPTION	Description updated	2
		PACKAGING INFORMATION	Added reference for C1V8	5
		ABSOLUTE MAXIMUM RATINGS	G006/G007: Added parameters	7
		ELECTRICAL CHARACTERISTICS	003: Changed max. value 217: Added parameter 222/224: Added parameter 226/227: Changed Conditions and max. value 229/230: Changed parameter description 231: Added parameter 3: Renamed section 505: Corrected definition C02: Replaced SYS with SYS_eff T03: Added min./max. values W01: Renamed parameter, updated Conditions W02: Removed parameter tstart()fast Z01-Z02: Updated values Z05-Z07: Updated values	8-11
		OPERATING REQUIREMENTS: Supply Voltages	Chapter added	12
		OPERATING REQUIREMENTS: SSI Slave	I206: Changed max. value	14
		OPERATING REQUIREMENTS: SSI Slave	I202-I204: Changed min. value	14
		OPERATING REQUIREMENTS: SPI Slave	I311: Changed max. value	15
		EEPROM SELECTION	Chapter updated	18
		INTERFACE PORTS	Chapter renamed	19
		PCB EXAMPLES	Chapter added for PCB Examples	20
		BANK ORGANIZATION, EEPROM & RPL	Renamed section "I2C Devices" to "Banks for I2C Devices"	21
		REGISTER MAP	Updated	23-28
		GENERAL	FILT1 setting for normal operation changed to 0xEA	29
		LED POWER CONTROL	Parameter LED_CONST added	31
		TEMPERATURE SENSOR	Chapter renamed	35
		ABSOLUTE DATA INTERFACE (ADI)	Chapter renamed	36
		ABZ GENERATOR	Chapter updated	41-45
		UVW GENERATOR	Chapter updated	46-48
		POSITION OFFSET	Figure added	49
		COMMANDS	Added command "CHIP_REV"	61
		IDs, SERIAL NUMBERS & SYSTEM DEFINITION	Definition of SYS_eff added Note added	65
		FLEXCODE®	Chapter added for FlexCode®	67
		DISC/SCALE CORRECTION	Chapter added for Disc/Scale Correction	68
		DIAGNOSIS	Diagnosis bits 6, 7 added	68
		ADJUSTMENT ANALOG	Notes added Updated formulas for autocalibration speed and time	71-76
		ADJUSTMENT DIGITAL	Note added Updated formulas for autocalibration speed and time	77
		DEVICE OVERVIEW	PZ0974 added	82

Rel.	Rel. Date[1]	Chapter	Modification	Page
C1	2020-07-08	all	Updated descriptions	all
		BLOCK DIAGRAM	Renamed function blocks: 'Random Evaluation' → 'Singleturn Position Evaluation' 'Disc/Scale Correction' → 'System Configuration' 'Position Offset' → 'Position Settings'	1

		DESCRIPTION	Added 'General notice on application-specific programming'	2
		PACKAGING INFORMATION	Added Sensor Layout and AOI Criteria	5
		ELECTRICAL CHARACTERISTICS	215: Moved typ. value to min. value P03: Changed max. value W01: Changed typ. value Renamed 'Random' → 'PRC'	9-12
		OPERATING REQUIREMENTS	Reworked Figure 1: Supply voltages at startup	13
		EEPROM SELECTION	Added requirement: 11-bit addressing scheme	19
		STARTUP	Removed bullet point about uProcessor watchdog	19
		CIRCUIT DESIGN PROPOSALS	Renamed chapter (former: PCB EXAMPLES)	21
		MEMORY ORGANIZATION	Renamed chapter (former: BANK ORGANIZATION, EEPROM & RPL)	22
		REGISTER MAP	Removed IPO_MODE, IPO_RESMIN, IPO_RESMAX, IPO_HYS and RAN_VAL Added AC_ETO Renamed sector 'Random Evaluation' → 'Singleturn Position Evaluation'	23-28
		INTERFACE PORTS CONFIGURATION	Renamed chapter (former: GENERAL) Moved subsections about interpolator to new chapter 'INTERPOLATOR' Moved subsection about position data length to new chapter 'POSITION SETTINGS' Renamed subsection 'VDDIO voltage selection' → 'VDDIO Monitoring'	29
		INTERPOLATOR	Added chapter Removed interpolator legacy mode	31
		SINGLETURN POSITION EVALUATION	Renamed chapter (former: RANDOM EVALUATION) Removed RAN_VAL and timing diagram Changed description of RAN_TOL and RAN_FLD	31
		ANALOG OUTPUT	Corrected LED_CUR = 0 to LED_CONST = 0 in note box	32
		POSITION SETTINGS	Renamed chapter (former: POSITION OFFSET) Included ST_PDL and MT_PDL of former chapter GENERAL	41
		BiSS SLAVE	Removed note on SSI_GRAY affecting BiSS single cycle data Removed Figure: BiSS protocol showing Control Communication Removed subsection BiSS Commands	43-44
		SPI SLAVE	Reworked SPI Operation Codes: 0x81 Read Registers (former: Register Read (Continuous)) 0xCF Write Registers (former: Register Write (Continuous)) 0xA6 Read Position (former: Position Read) 0xD9 Write Command (former: Write Command) 0x9C Read Status (former: Read Status) 0x97 Request Data From I2C Slave (former: Register Read (Single)) 0xD2 Transmit Data To I2C Slave (former: Register Write (Single)) 0xAD Get I2C Transmission Info (former: Register Status/Data) 0xB0 Activate Slave In Chain (former: Activate)	46-50
		COMMANDS	Added commands MTST_PRESET_STORE, MT_PRESET_STORE, ABZ_PRESET_STORE, UVW_PRESET_STORE	51
		ABSOLUTE DATA INTERFACE (ADI)	Added note on ADI_CFG bit 0	55
		I2C MASTER	Added Figure 47: I2C protocol	59
		DIAGNOSIS	Renamed DIAG bit 11 'Random synchronization failed' → 'PRC synchronization failed'	63
		SYSTEM CONFIGURATION	Added chapter (former: IDs, SERIAL NUMBERS & SYSTEM DEFINITION and DISC/SCALE CORRECTION) Changed default values of DEV_ID and MFG_ID Changed note on SYS_OVR Changed SYS_OVR overriding SYS_eff only, not affecting SYS anymore Changed naming order of BISS_PROFILE_ID, SERIAL, DEV_ID and MFG_ID	65-66
		ADJUSTMENT ANALOG	Added AC_ETO Removed analog adjustment requiring SC_OFF_SEL, SC_GAIN_SEL or SC_PHASE_SEL to be non-zero Corrected minimum speed to 1.25 1/s in Table 131 Changed recommended values to default	68-72
		ADJUSTMENT DIGITAL	Added note on AC_SEL1, AC_SEL2, AC_COUNT and AC_ETO Changed recommended values to default	73-74
		ADJUSTMENT ECCENTRICITY	Corrected calculation of ECC_AMP Added note on AC_COUNT Changed recommended values to default Changed RPM to 900 in Table 150	75
		DEVICE OVERVIEW	Updated	77

Rel.	Rel. Date[1]	Chapter	Modification	Page
D1	2020-10-23	ELECTRICAL CHARACTERISTICS	004: Changed typ. value Added filter settings to C01 and C02 Updated Z03 to more than 2 slaves in SPI daisy chain	9-12
		BiSS Slave	Changed I105 to include Start Bit Delay	14
		SPI Slave	Added I312 and I313	16

		EEPROM SELECTION	Updated description	19
		INTERFACE PORTS CONFIGURATION	Corrected default value of VDDIOSEL	29
		BiSS SLAVE	Updated description regarding total data length	43
		SPI SLAVE	Updated description regarding total data length Reworked description for SPI opcode 0xB0	47, 50
		I2C MASTER	Changed available I2C_DEV_ID range	58
		FLEXCODE®	Removed specification modification for ABZ_PER Added description and example for output data value range	67
		ORDERING INFORMATION	Updated Evaluation Kits	82

Rel.	Rel. Date[1]	Chapter	Modification	Page
E1	2021-06-14	FEATURES	Added assembly tolerances to features	1
		PACKAGING INFORMATION	Updated link to customer information 'Optical Selection Criteria'	5
		PACKAGE DIMENSIONS	Updated drawing	7
		THERMAL DATA	T03: Updated link to customer information 'Handling and Soldering Conditions'	8
		ELECTRICAL CHARACTERISTICS	Added 'GNDA = GNDIO = 0 V' to operating conditions Updated 'VDDIO = 2.25...VDDA' in operating conditions 007: Added note on linear applications C03: Added parameter fout() S05/S06: Corrected unit Renamed Item No. of Temperature Sensor to U Z01: Added 'Permissible' Z02: Added 'Permissible' Z03: Added 'Permissible'	9ff
		SPI Slave	I306: Corrected parameter description	16
		EEPROM SELECTION	Added I2C device address 0x50	19
		REGISTER MAP	Changed ADI_CFG(0) to reserved[0]	23
		ABZ GENERATOR	Updated example for ABZ_PER Added example for v_{max} Corrected description of DIAG(6) to 'not(ABZ_RDY)' Corrected description of DIAG(24) to 'not(RDY)'	33, 37
		UVW GENERATOR	Corrected description of DIAG(7) to 'not(UVW_RDY)'	40
		POSITION SETTINGS	Added note for properly setting MT_PDL with external MT slaves	41
		BiSS SLAVE	Updated BiSS slave performance table Added BiSS protocol commands Added warning when sending short BiSS frames < 6 MA pulses	43, 45
		SSI SLAVE	Added warning when sending short SSI frames < 6 MA pulses	47
		SPI SLAVE	Renamed opcode 0x9C 'Read Status' → 'Read Diagnosis' Renamed opcode 0xAD 'Get I2C Transmission Info' → 'Get Transaction Info' Reworked description of opcode 0xAD 'Get Transaction Info'	48ff
		ABSOLUTE DATA INTERFACE (ADI)	Removed note on ADI_CFG(0)	57
		TEMPERATURE SENSOR	Added instruction for reading TEMP	63
		ADJUSTMENT ANALOG	Corrected description of SC_GAIN 0x001 to '1.0005' Note on linear applications Added instruction for reading COS_OFFS, SIN_OFFS, SC_GAINS and SC_PHASES	71,73,74
		ADJUSTMENT DIGITAL	Added note on position validity when changing AI_PHASE and/or AI_SCALE Note on linear applications Added instruction for reading AI_PHASES and AI_SCALES	75f

Rel.	Rel. Date[1]	Chapter	Modification	Page
F1	2023-04-20	DEVICE OVERVIEW	Corrected PZ07S disc M-Type	79
		THERMAL DATA	MSL3	8
		ABSOLUTE MAXIMUM RATINGS	ESD desription	8
		ELECTRICAL CHARACTERISTICS	Renamed parameters in "Temperature Sensor" from Uxx to Txx	11
		CIRCUIT DESIGN PROPOSALS	EEPROM Advice	21
		ORDERING INFORMATION	Corrected Eval-Kit Code Disc PZ03PS	85

[1] Release Date format: *YYYY-MM-DD*

ORDERING INFORMATION

Type	Package	Options	Order Designation
iC-PZ2656	32-pin optoQFN, 5 mm x 5 mm, 0.9 mm thickness RoHS compliant		iC-PZ2656 oQFN32-5x5
iC-PZ0974	32-pin optoQFN, 5 mm x 5 mm, 0.9 mm thickness RoHS compliant		iC-PZ0974 oQFN32-5x5
iC-PZ205	32-pin optoQFN, 5 mm x 5 mm, 0.9 mm thickness RoHS compliant		iC-PZ205 oQFN32-5x5
Evaluation Kit	Kit with Reflective Encoder IC (approx. 61mm x 64 mm), Code Disc PZ03PS		iC-PZ2656 EVAL PZ1M
	Kit with Reflective Encoder IC (approx. 61mm x 64 mm), Linear Scale PZ01L		iC-PZ205 EVAL PZ1M LIN
	Kit with Reflective Encoder IC (approx. 61mm x 64 mm), Code Disc PZ05SM		iC-PZ205 EVAL PZ1M ROT
	Kit with Reflective Encoder IC (approx. 61mm x 64 mm), Code Disc PZ07SM		iC-PZ0974 EVAL PZ1M
Motherboard	Adapter PCB (approx. 80 mm x 110 mm)		iC-PZ EVAL PZ2D

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